

SHARP

Electronic Components
January 2010

For Your Creative Products

ELECTRONIC COMPONENTS



<http://sharp-world.com/products/device/>

CONTENTS

Sharp—Working to Realize a Low Carbon Society	2
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TFT

LCD Modules	8
-------------------	---

LSI REG RF Analog

CMOS IMAGE SENSORS

CMOS Camera Module Road Map	14
CMOS Camera Modules	15

CCDs

Road Map for High-resolution CCDs for Digital Cameras	16
High-resolution CCDs	17
1/3-type CCDs	17
1/3.8-type CCD	17
1/4-type CCDs	17
CCD Peripheral ICs/LSIs	18

LSIs FOR LCDs/ANALOG ICs

For Notebook PCs, PC Monitors and LCD TVs	24
For Mobile Phones	24
Power Supply ICs for TFT-LCDs	25

SYSTEM LSIs

System LSIs	26
Smart Modules	26
One-chip Graphic Controller	27
IrSimple™ Communications Series	28

SMART CARD SYSTEMS

Smart Cards/LSI Modules for Smart Cards	29
SDK (Software Development Kit) for Smart Cards	29

FLASH MEMORIES

Highly Functional Flash Memories	
Boot Block Type 3 V Page Mode Flash Memories	30/31
System-Flash for Automotive Use	30/31
System-Flash for Network Equipment	30/31

POWER DEVICES/ANALOG ICs

POWER DEVICES

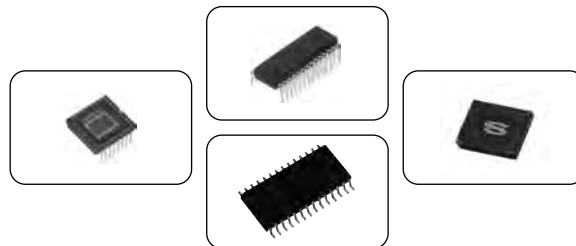
Low Power-Loss Voltage Regulators	32
Surface Mount Type Low Power-Loss Voltage Regulators	33
Surface Mount Type Chopper Regulators (DC-DC Converters)	38
Chopper Regulators (DC-DC Converters)	39
Power Supply ICs for CCDs/CCD Camera Modules	40

ANALOG ICs

Power Supply ICs for TFT-LCDs	40
LED Drivers	40
Power Supply Modules for LED Lighting (AC Direct Drive)	42
Power Amplifiers or Wireless LAN	43
Fail Safe ICs	43
Solar Modules for Mobile Devices	43

PACKAGES

CSP (Chip Size Package)	44
SiP (System in Package)	45
SOF (System On Film)	47
Package Lineup	48



OPTO

OPTOELECTRONICS

Photocoupler Lineup	55
Photocouplers	
Phototransistor Output Type	56
OPIC Output	60
Phototriac Coupler Lineup	62
Phototriac Couplers	63
Solid State Relay Lineup	65
Solid State Relays	66
Photointerrupter Lineup	69
Photointerrupters <Transmissive type>	70
Single Phototransistor Output	70
Darlington Phototransistor Output	72
OPIC Type	72
Photointerrupters <Reflective type>	74
Single Phototransistor Output	74
OPIC Output	75
Photointerrupters for Specific Application	76
Transmissive Type	76
Reflective Type	76
Proximity Sensor	77
Proximity Sensor with Integrated Ambient Light Sensor	77
Ambient Light Sensors	78
OPIC Light Detectors	79
Phototransistor Lineup	81
Phototransistors	82
Photodiodes/OPIC Light Detectors	
PIN Photodiodes	83
Laser Power Monitoring Photodiodes for Optical Disc System	83
Infrared Emitting Diode Lineup	84
Infrared Emitting Diodes	85
Optical-Electric Sensor Lineup	86
Distance Measuring Sensors	88
Wide Angle Sensors	90
Paper Size Sensors	90
High-Precision Displacement Sensor	90
Dust Sensor Unit	91
Smoke Sensor Module (For Fire Alarms)	91
Color Toner Concentration (Deposition Amount) Sensors	91

Fiber Optics Lineup

Fiber Optics Lineup for Audio Equipment.....	92
Fiber Optic Transmitters	93
Fiber Optic Receivers.....	93

LED

LEDs

High-Luminosity LED Lamps.....	94
Dichromatic LED Lamps	95
LED Lamps	96
High-Luminosity Surface Mount LEDs	97
Surface Mount LEDs	98
High-Luminosity White Surface Mount LEDs	99
High-Luminosity Surface Mount LEDs (RGB 3-color)	100
ZENIGATA LEDs for Lighting.....	100
Surface Mount LEDs for Lighting	101
Surface Mount LEDs for Lighting (RGB 3-color)	101



LASER

LASER DIODES

Laser Diodes	102
--------------------	-----



RF

RF COMPONENTS

Low Noise Blockdown Converters	
Europe: LNBs for Satellite Broadcast.....	104
Japan/Asia/Australia: LNBs for CS Digital Satellite Broadcast	105
Japan: LNBs for BS/CS 110° Satellite Broadcast.....	105
Digital DBS Front-End Units.....	106
Combination Front-End Units for Digital Terrestrial, Analog Terrestrial and Digital Satellite Broadcasting.....	108
Digital Terrestrial Front-End Units	
Front-End Units for ISDB-T/DVB-T/CTTB/CATV	109
Digital Terrestrial/Analog Terrestrial Front-End Units	
Front-End Units for Digital Terrestrial and Analog Terrestrial Broadcasting	111

Digital Terrestrial Compound Receiver Module/One-Seg Tuner Modules

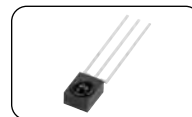
RF-separation Type Digital Terrestrial Compound Receiver Module.....	112
One-Seg Tuner Module.....	112
One-Seg Tuner Module for Simultaneous 2-program Reception	113
Tuner Module for China's CMMB-system Mobile Broadcasts.....	113
Embedded Wireless LAN Module.....	114
Embedded Wireless LAN-Bluetooth Combo Module.....	115



IR

IR DEVICES

Infrared Data Communication Device Lineup	116
Infrared Data Communication Devices	117
IR Detecting Unit for Remote Control Lineup (Classified by Form/Operating Voltage)	119
IR Detecting Units for Remote Control	120



PCB

PRINTED CIRCUIT BOARDS

Advanced Flex Printed Circuit Boards	121
Flexible Build-up Multilayer PCBs.....	122
Flexible Printed Circuit Boards	123



UNIT

PICKUPS

Slim Combo Drive Pickup	124
Slim DVD Super-Multi Drive Pickup	124
DVD Pickup for Automotive Use	124

Sharp—Working to Realize a Low Carbon Society

Under its environmental vision for fiscal 2010, which states that “Sharp’s Energy-Creating and Energy-Saving Products Will More Than Balance Out Sharp’s Greenhouse Gas Emissions,” Sharp is strengthening its efforts towards realizing a low-carbon society, in particular by expanding solar cell production, making its products more energy efficient, and pushing forward with energy-saving measures in its business activities.

● Basic Environmental Philosophy ●

Creating an Environmentally Conscious Company with Sincerity and Creativity

● The Sharp Group Charter of Corporate Behavior ●

Contribution to Conservation of the Global Environment

The Sharp Group will fulfill our responsibility for environmental conservation by promoting the creation of proprietary technologies that contribute to protection of the global environment, and by carrying out our product development and business activities in an environmentally conscious manner.

● The Sharp Code of Conduct ●

Contribution to Conservation of the Global Environment

1. To Conserve the Environment:

- ① We will comply with all applicable environmental laws, regulations and territorial agreements, and work to practice efficient use and conservation of resources and energy voluntarily, in the recognition that environmental conservation is an essential facet of corporate and individual pursuits.
- ② We will ensure proper use and control of chemical substances in our business activities, including research, development and manufacturing, meeting or exceeding levels determined by laws and regulations.
- ③ We will engage in the active acquisition, reporting and promotion of environmental information at an international level, as the Sharp Group companies promote communication with shareholders and local residents.
- ④ We understand the importance of internal company systems and related details in acquiring third-party certification and recertification of our ISO environmental management systems, and we will conduct our business operations in accordance with relevant internal guidelines.

2. To Develop Environmentally Conscious Products and Services, and Conduct Our Business Operations in an Environmentally Conscious Manner:

- ① We will engage positively in the minimization of resource use, reduction in the size and weight of products, use of recycled materials, and the development of long-lasting, energy-saving, energy-creating products.
- ② We will work to compile information related to harmful substances that might damage the environment or human health, and will not, as a matter of principle, make use of these harmful substances in our products, services and business activities.
- ③ We will use recyclable materials wherever possible, with product development focused as a matter of policy on structures that are detachable or capable of dismantling, and suited to recycling.
- ④ We will work aggressively to reduce greenhouse gas emissions in the full range of our business activities, in order to contribute to the prevention of global warming.
- ⑤ We will work to conduct our business in such a way as to select and purchase materials that are harmless to the global environment, and to local residents and employees, for the resources needed for business activities (equipment, raw materials, subsidiary materials, tools, etc.).
- ⑥ We realize that waste material is a valuable resource, and we will actively conduct our business operations in such a way as to maximize the 3Rs (reduce, recycle and reuse) and will contribute to minimizing the amount of waste sent for permanent landfill disposal.

* The Sharp Group Charter of Corporate Behavior and the Sharp Code of Conduct were instituted in May 2005 as a revised edition of the preceding Sharp Charter of Conduct (instituted in 2003). The section above is an excerpt from descriptions of Sharp's environmental conservation efforts. For more information: <http://sharp-world.com/corporate/eco/report/index.html>

Sharp's Environmental Vision for Fiscal 2010:

Sharp's Energy-Creating and Energy-Saving Products Will More Than Balance Out Sharp's Greenhouse Gas Emissions

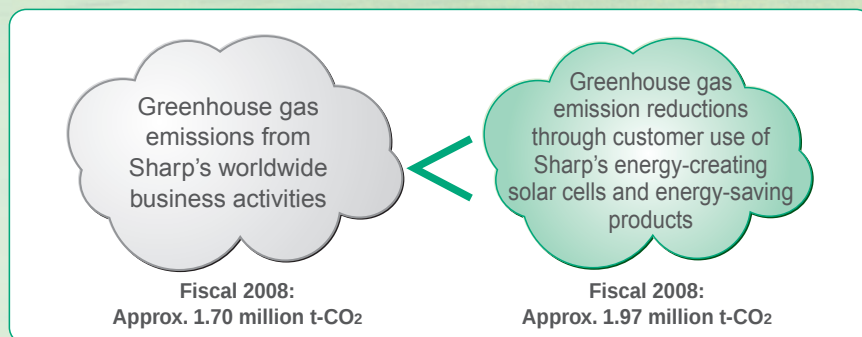
In fiscal 2004, Sharp announced its medium-term corporate objective of being an environmentally advanced company and established its environmental vision for fiscal 2010 of having its energy-creating and energy-saving products more than balance out its greenhouse gas emissions. Under the environmental vision, by reducing the amount of greenhouse gases emitted as a result of Sharp's worldwide business activities to the greatest extent possible, while at the same time significantly increasing the magnitude of reductions in greenhouse gas emissions through customer use of Sharp energy-creating solar cells and energy-saving products, the net reduction in greenhouse gases will more than balance out the level of emissions from fiscal 2010 onward.

Since 2004, Sharp has been working to achieve this objective based on its Super Green Strategy, pushing a proactive approach, particularly by expanding the use of solar power but also by improving the environmental performance of its products and devices, raising the level of environmental performance at its production facilities, and developing unique, one-of-a-kind environmental technologies. As a result, according to Sharp's estimation for fiscal 2008, the reduction in greenhouse gas emissions through customer use of Sharp solar cells was approximately 1.02 million t-CO₂*¹ and through customer use of energy-saving products was approximately 0.95 million t-CO₂*², for a total reduction of approximately 1.97 million t-CO₂. At the same time, Sharp's total greenhouse gas emissions from business activities for fiscal 2008 were 1.70 million t-CO₂. (Please see "Sharp Environmental and Social Report 2009" and Sharp's website for details.)

Sharp will continue contributing to the realization of a low-carbon society by expanding solar cell production, making its products more energy efficient, and pushing forward with energy-saving measures in its business activities.

*1 Calculated based on the annual estimated amount of electricity generated in fiscal 2008 (2,260 GWh) by solar cells produced by Sharp in the 20 years from fiscal 1988 to 2007 and using the figure of 0.453 kg/kWh for CO₂ emissions intensity (emissions per kWh of electricity consumed), announced by the Federation of Electric Power Companies of Japan (for fiscal 2007).

*2 For fiscal 2008, the reduction in greenhouse gas emissions from the effect of customer use of energy-saving products was calculated by multiplying the CO₂ emissions intensity (emissions per kWh of electricity consumed) of 0.453 kg/kWh by the estimated reduction in power consumption (2,093 GWh) achieved from April 1, 2008 to March 31, 2009 by the use of Sharp TVs, air conditioners, and refrigerators shipped in Japan between fiscal 2003 and fiscal 2007 and that were assumed to have been purchased as replacements for older models. The reduction in power consumption was calculated based on average power consumption for old representative models within the industry for fiscal 1997 (kWh).



Developing Devices with High Environmental Performance

Certification of Green Devices and Super Green Devices

Sharp calls its environmentally conscious devices Green Devices (GD). To define guidelines for development and design based on seven concepts, Sharp established the GD Guidelines, which it began applying at all device business divisions in fiscal 2004. The GD Standard Sheet was formulated based on these guidelines, and environmentally conscious devices that meet these standards are certified as GD. Sharp began certifying devices from among GD with the highest possible levels of environmental performance as Super Green Devices (SGD) from fiscal 2005.

In developing devices, Sharp sets specific objectives according to the GD Standard Sheet during the planning stage; and, in the trial manufacture and mass production stages, Sharp determines if the actual device is environmentally conscious from all perspectives by evaluating how well it has met the criteria.

In fiscal 2008, both GD and SGD exceeded their sales ratio targets. In the coming years, Sharp plans to raise these figures even higher.

Green Device Concept

Energy saving	Reduce total power consumption and reduce power consumed in standby mode compared to previous models
Recyclability	Use standard plastic or materials that are easy to separate and disassemble (target: LCD devices)
Resource saving	Reduce device weight or volume compared to previous models
Green materials	Control usage of chemical substances contained in parts and materials and use no substances prohibited under Sharp standards
Long life	Extend the life of the product with exchangeable parts and consumables (target: LCD devices)
Packaging	Reduce packaging materials
Information disclosure	Provide information on chemical substances in devices

Examples of Fiscal 2008 Certified Super Green Devices

LNB*1 for Satellite Broadcasts (BS1R9EL100A)

European universal LNB enables reception of all satellite broadcasts in Europe.



- One of the industry's smallest and lightest*2
- Low-current-consumption, 80 mA (typ.) design boasts improved energy efficiency

*1 LNB: Low noise block converter

*2 As of May 2009.

ZENIGATA LED for Lighting (GW5BWC15L02)

High-output LED for lighting purposes with superior environmental performance: long lasting, low power consumption, and mercury-free.



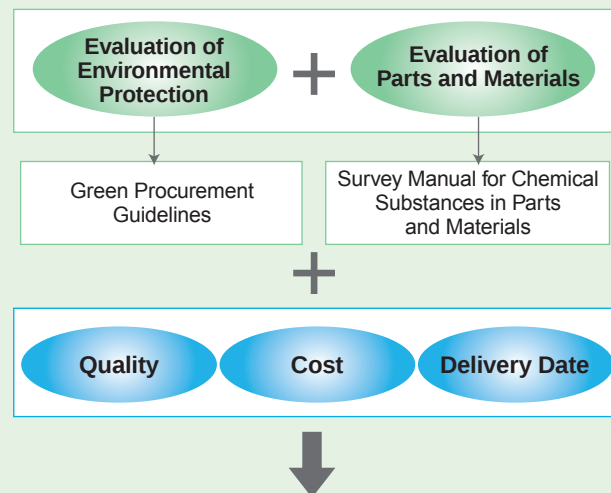
- Improved luminous efficiency for the LED chip and reflection efficiency for the package help achieve one of the industry's highest levels of brightness and luminous efficiency*3 in the 3.6 W input class
- 1 module (has 30 elements): 280 lumens (3.6 W)
- Luminous efficiency: 78 lumens/watt (pseudo white type)

*3 As of May 2009.

Green Procurement

Sharp judges suppliers' overall environmental compliance by setting evaluation standards for environmental considerations in addition to evaluating quality, cost, and delivery date (see below).

Evaluation of Environmental Consciousness



Raising the Level of Environmental Performance in Factories

Green Factory Certification

At Sharp, a factory must achieve a high degree of environmental performance to earn the designation of Green Factory (GF). The basic policies and operational know-how for achieving GF status have been formulated in line with 10 concepts*¹ in the GF Guidelines. These guidelines have been introduced at all plants in Japan and overseas.

In fiscal 2003 in Japan and in fiscal 2004 overseas, Sharp established assessment criteria for GF and Super Green Factories (SGF) and launched efforts to award in-house certification. Sharp uses unique, quantified environmental performance criteria to assess and approve a plant for certification. A plant must score 70 or more points out of a possible 100 in the assessment process to earn GF certification, and score 90 or more points to achieve SGF certification.

*¹ The 10 GF concepts are 1) greenhouse gases, 2) energy, 3) waste, 4) resources, 5) chemical substances, 6) atmosphere/water/soil, 7) harmony with nature, 8) harmony with the community, 9) environmental awareness, and 10) information disclosure

Making All Plants Super Green Factories

By fiscal 2007, all 10 Sharp Corporation plants had achieved SGF status.

In fiscal 2008, an additional two plants in Japan and four overseas were certified as SGF, making 21 of Sharp's 38 worldwide plants SGFs. SGFs in Japan have begun stepping up their eco efforts with the aim of achieving certification for SGF II.

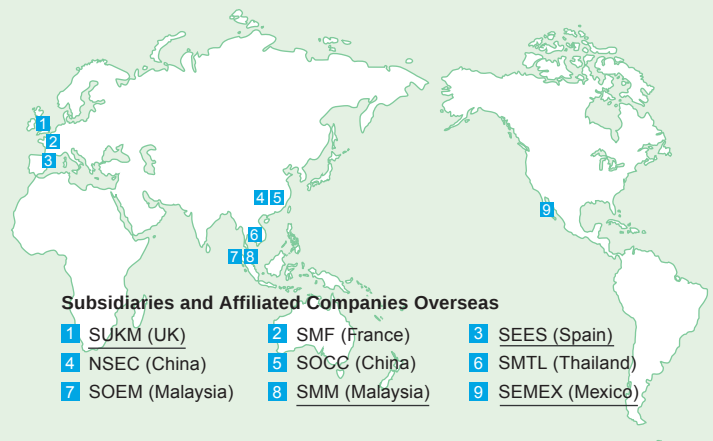
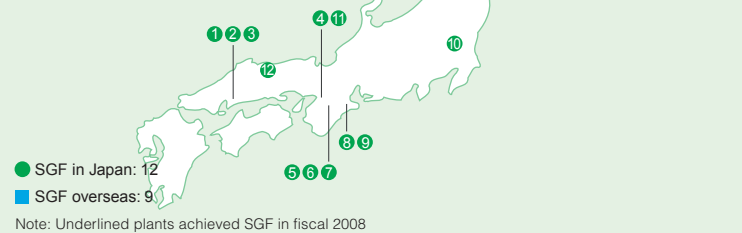
Certified Super Green Factories Worldwide

Sharp Corporation

- ① Hiroshima Plant ② Mihara Plant ③ Fukuyama Plant ④ Yao Plant ⑤ Katsuragi Plant
⑥ Nara Plant ⑦ Tenri Plant ⑧ Kameyama Plant ⑨ Mie Plant ⑩ Tochigi Plant

Subsidiaries and Affiliated Companies in Japan

- ⑪ Sharp Manufacturing Systems Corporation
⑫ Sharp Yonago Corporation



Development of GREEN FRONT SAKAI

In continuing its efforts to become an environmentally advanced company, Sharp has been developing its business on the two pillars of energy-saving LCDs and energy-creating solar cells. In order to further these efforts, Sharp commenced operations at a new LCD panel plant in October 2009 in Sakai, Osaka prefecture. We hope to propel our business forward by having companies in other fields with advanced technology join us, to help us achieve the goal of creating a "green society" suitable to today's environmentally conscious mindset.



Overview of GREEN FRONT SAKAI

Location: 1-banchi, Takumi-cho, Sakai-ku, Sakai-shi, Osaka
Site area: 1.27 million m²
(approx. 28 times the size of Tokyo Dome)

LCD Panel Plant

Start of operations: October 2009
Mother glass size: 2,880 mm x 3,130 mm
(10th generation)
Mother glass input capacity: 72,000 substrates per month (initial capacity at start of operations: 36,000 substrates per month)

Thin-Film Solar Cell Plant

Start of operations: by March 2010
Glass substrate size: 1,000 mm x 1,400 mm
Plant capacity: up to 1 GW expansion in production is possible

Achieving Super Green Factories

Sharp is systematically acting to enhance the environmental consciousness of its production sites worldwide. Sharp has established proprietary assessment standards to rank factories with high environmental consciousness as Green Factories, and those with extremely high environmental consciousness as Super Green Factories.

Sharp's First Super Green Factory Kameyama Plant

AVC Liquid Crystal Display Group (Kameyama, Mie Prefecture)

The Kameyama Plant is Sharp's first "Super Green Factory," a compilation of the company's environmental protection technologies. In preparing for construction, we gave a great deal of careful consideration to protecting the environment, beginning at the initial design stage. Working in consultation with local governments and with nearby residents, we carefully selected the parameters that would be subject to environmental protection measures. We chose the standards that would apply, and confirmed them through evaluation by independent experts. Also, when building Kameyama Plant No. 2, we took the opportunity to introduce the latest environmental technology to make it one of the world's most advanced "Super Green" factories.



An Efficient and Environment-Friendly Integrated Production System

The entire process is carried out in a single plant—from fabricating the LCD panels to final assembly. This system makes it possible to consolidate technical departments and strengthen our development capabilities, as well as shorten the lead-time from order to shipping. Eliminating the need to ship sub-assemblies between distant plants has also enabled us to slash the amount of packaging materials required for shipping and reduce emissions such as carbon dioxide (CO₂).

Countering Global Warming by Unifying Diverse Power Sources Distributed over a Wide Area

The Kameyama plant generates one-third of its annual electricity consumption and has reduced CO₂ emissions to about 40% lower than previous levels by means of a cogeneration system* using liquefied natural gas (LNG) (approx. 40,000 kW), as well as one of the largest fuel cell systems in Japan (approx. 1,000 kW), and one of the world's largest-class photovoltaic (PV) power generation systems (5,210 kW).

* Cogeneration system: A system designed to save energy by using city gas to generate electricity. The waste heat generated is then used in applications such as air conditioning, hot water supply and steam electricity generation.

The Kameyama Plant Receives Japan Sustainable Management Award

The Kameyama Plant in Japan was recognized for its outstanding environmental sustainability management by being chosen from among 125 applicants for the highest honor, the Sustainable Management Pearl Award, in the 2004 Japan Sustainable Management Awards* (sponsored by the Japan Sustainable Management Awards Committee and Mie Prefecture). This award shows the high esteem for the environmental measures—including 100% recycling of manufacturing process wastewater, the introduction of a cogeneration system and the installation of a photovoltaic power system—taken by the Kameyama Plant, Sharp's first Super Green Factory.

The Kameyama Plant received the first Minister of Economy, Trade and Industry Award in the 8th Japan Water Prize (2006), the Energy Saving Encouraging Prize in the 4th Excellent Cogeneration System Commendation (FY 2005) sponsored by the Japan Cogeneration Center, and the Minister of the Environment's Award for Activities to Fight Global Warming (FY2007).

* The Japan Sustainable Management Awards honor all organizations across the nation, no matter what their size or type of business—including private companies, NPOs and schools—that demonstrate outstanding results of their environmental sustainability management efforts.

Creating Energy at the Factory for Energy-Saving Products, Using One of the World's Largest-Class* PV Power Generation Systems

In addition to the existing 60-kW photovoltaic (PV) power generation system, new PV power generation systems, in a total area of approx. 47,000 m² and with a total output of 5,150 kW, have been installed. Located at the large-screen LCD TV factory, the distribution building, and on the roof and curtain wall of the Kameyama Plant No. 2, these systems generate an annual electricity output that would power 1,300 average Japanese households.

* As a building-installed system. Survey by Sharp.

Water Purifying System—100% Water Recycling in the Production Process

The plant collects all the wastewater from the production process of liquid crystal panels, etc. and recycles it 100% with water purification techniques using microorganism treatment. Malodorous wastewater containing chemicals is deodorized using peat moss* from Ishikari River, Hokkaido.

* Bog moss decomposed and piled up for several thousands of years.

Mie Plant Becomes First Existing Factory to Achieve Super Green Status

Mobile Liquid Crystal Display Group (Taki, Mie Prefecture)

The results described below are major efforts in upgrading to a Super Green Factory.

Mie Plant Environmental Site Report Receives the Site Report Award

At the 12th annual Environmental Reporting Awards hosted by Toyo Keizai Inc. and Green Reporting Forum, the Sharp Mie Plant environmental site report earned praise for keeping the public's point of view in mind and for its easy readability, and was presented with the Site Report Award. The Environmental Reporting Awards is the only award program in Japan that recognizes environmental reports released by factories. The program receives high praise throughout society, boasts a high level of name recognition, and attracts a large number of submissions every year.

CO₂ Emissions Reduction Efforts

Sharp has assembled a CO₂ Emissions Reduction Commission to curb emissions from heavy CO₂-emitting equipment and achieve major cuts in overall CO₂ emissions. Included among the members of this committee are the managers in charge of running all types of production equipment. The Commission has outlined plans for annual emissions reductions of 3% or more, and the entire Mie Plant is making an all-out effort to minimize the volume of CO₂ emitted.

Energy-Saving Efforts

Since it began operations, the Mie Plant has been taking all kinds of steps to conserve energy. The members of the Mie Environmental Safety Promotion Center, an energy management department, have received prizes for excellence in energy management from the Energy Conservation Center, Japan (ECCJ), for three consecutive years since 2006. The number of members presented with awards has grown to five, reflecting the recognition the Mie Plant has achieved for its efforts toward energy conservation.

Waste Reduction Efforts

In 2004 the Mie Plant achieved zero discharge to landfill, but employees have been making further efforts to reduce the burden on the environment, taking a variety of steps including expanding the sale of valuable portions of waste materials for reuse, and changing the types and reducing the volume of chemicals used.



Participation in Local Activities

As a regional corporate citizen, members of the Mie Plant are making active contributions to local activities. Members have been taking part in educational programs at local schools; have dispatched visiting lecturers to about 20 elementary, junior high and high schools in the vicinity of the plant; are conducting joint environmental activities; and are seeking to raise young people's level of environmental awareness.

Participation in Local Environmental Conservation Activities

In addition to efforts to mitigate the impact of the plant on the surrounding environment, the Mie plant is playing a role in local environmental conservation activities. Activities include a wide range of mountain, river, road and park-related programs, such as the upkeep of the forest surrounding the water source in the Osugi Valley, maintenance of the forests and mountains in the town of Taki, cleaning of the plant's effluent stream (the Sanagawa River), cleanup and planting of flowers on National Route 42, and work on the plaza at Taki Crystal Town Shopping Center.

Green Factory Activities at Key Electronic Device Factories



**Advanced Development & Planning Center/
Corporate Research & Development Group/
Production Technology Development Group
(Tenri, Nara Prefecture)**

ISO 14001 certification: December 3, 1996

Adoption of a Cogeneration System*

About 26% of facility power is provided through private power generation. Waste heat is used for heating or cooling and also supplied to a steam generator for power generation. This cuts facility CO₂ emissions by about 13%.

* An energy-saving system that generates power using municipal gas and uses the produced waste heat for heating or cooling, hot water supply and steam electricity generation, etc.

Installation of a Solar Generation System

Installation of solar panels with a generating capacity of 40 kW.

Waste Fluid Processing System based on Natural Purification*

Waste and the pollution load of released water are reduced by using a waste fluid treatment system for waste water containing alcohol or other organic components.

After treatment, water is given further high-level treatment and used as intermediate factory water, to ensure more effective use of water resources.

* A natural purification system based on micro-organisms, developed independently by Sharp. (Patented)

Promotion of Zero Emissions*

Zero emissions were achieved in fiscal 2002 through reclamation of waste into useful resources for other business fields. Efforts will continue to further reduce waste emissions.

Installation of Environmental Equipment

In fiscal 2007, equipment for the safe disposal of PFC gas and gases subject to the Pollutant Release and Transfer Register (PRTR) Law was installed and factory wastewater was converted to sewerage, with the objective of minimizing environmental impact.

Relations with the Local Community

As the only Sharp establishment that has an ancient burial mound on its grounds, the center's employees are actively involved in the maintenance of the mound. In August of each year, the center invites employees and their families and local people to a "Sharp Festa." An environmental exhibition space is prepared to showcase the environmental activities of the center. Furthermore, the company hosts parent-child tours during the spring, summer and winter breaks at its Sharp Memorial Technology Hall.



**Electronic Components & Devices Group
(Fukuyama, Hiroshima Prefecture)**

ISO 14001 certification: September 24, 1996

Development of Unique Environmental Technologies

The Group developed a fusion of micro-nano bubble (MNB) technology and a unique microorganism treatment technology, and put it into practice in July 2006 in the world's first semiconductor plant using non-dilution treatment technology on the nitrogen contained in wastewater. The plant also incorporated waste treatment technology to address emissions of 2-aminoethanol, covered under the Pollutant Release and Transfer Register (PRTR) system, and has succeeded in cutting such emissions to approximately one-third of previous amounts.

Promotion of Zero Emissions*

Zero emissions was achieved in 2001 through ongoing efforts such as reductions in volume of waste produced, recycling of waste into useful materials, and reuse.

Prevention of Global Warming

An energy conservation committee has been formed to promote energy conservation efforts involving the entire Group. Efforts such as building a unique energy-saving outdoor air treatment system have been highly regarded, and the Group received a "2005 Excellent Energy Conservation Factory & Building (electricity category)" award from the Director-general of the Agency for Natural Resources and Energy.

Relations with the Local Community

In August of each year, employees and their families and local people are invited to the "Family Day in Sharp (Summer Festival)." At this festival, an environmental exhibition space is prepared to provide an opportunity for people to experience nature and to introduce the environmental protection efforts of the facility.

The plant also implemented the semiconductor industry's first full-scale risk communication system (July 2005), and holds ongoing meetings and other events with local residents in order to provide a better understanding of them. Furthermore, the plant jointly produced a large communication panel (4 m x 6 m) called "Daimoncho—Yesterday and Today" in cooperation with the local residents who approved and supported our efforts. The panel is on display at our premises and is being used to introduce our business and Daimoncho to visitors.

Communication activities such as these have been highly evaluated, and the Group received the "2005 PRTR Prize" sponsored by the Center for Environmental Information Science.



**Solar Systems Group
Electronic Components & Devices Group
(Katsuragi, Nara Prefecture)**

ISO 14001 certification: June 25, 1996

Prevention of Water Pollution

All wastewater from production and other processes is released into public sewers only after being purified at a wastewater treatment facility within the factory grounds. The treated wastewater released into public sewers is held to voluntary standards that are stricter than water emission standards set forth in the Sewerage Law.

A portion of the wastewater from production processes is collected, purified, and recycled as water reused in production, mitigating environmental impact and making efficient use of water resources.

Prevention of Air Pollution

Waste gases containing acids, alkalis and organic solvents produced during production and other processes, are purified and rendered harmless by onsite waste gas treatment equipment (acid/alkali scrubbers or solvent scrubbers, depending on the waste gas properties).

Continuation (Maintenance) of Zero Waste Emissions*

In fiscal 2001, the factory achieved zero emissions through the recycling of waste into useful materials. It is now working to promote further reduction of waste volumes, as well as further recycling efforts.

Solar Generation System

A solar generation system (194.5 kW total capacity) has been installed on the rooftops of factory buildings and elsewhere on the grounds, and the electricity generated is used for tasks such as factory air conditioning.

Relations with the Local Community

The factory takes an active role as a member of the community, participating in the twice-yearly local event known as "tsuyu-barai," or "banishing the dew." Held in April and September, this event includes cleanup of the waterways (ditches) and roads in the vicinity of the factory.

In October of each year, the factory holds the Katsuragi Festa (festival) to maintain positive relations with the surrounding community and showcase the site's environmental activities.



**Electronic Components & Devices Group
(Mihara, Hiroshima Prefecture)**

ISO 14001 certification: November 17, 2003

Prevention of Global Warming

The precise air-conditioning necessary for production activities is maintained by operating coolers and boilers on municipal gas, which produces little CO₂. The turbo coolers provided in air-conditioning equipment use a waste heat recovery system. A remover optimized for greenhouse gases is provided to suppress emission of such gases and prevent global warming.

Installation of a Solar Generation System

In February 2007, solar panels with a generating capacity of 20 kW were installed on the roof of the No. 2 Plant.

Promotion of Zero Emissions*

Zero waste emission has been achieved through active efforts to reduce and reclaim waste, instituted from the beginning of the facility. In recognition of these efforts, Sharp was awarded the Clean Japan Center's 2008 chairperson's award in recognition of distinguished persons promoting the principle of "Reduce, Reuse, and Recycle" (sponsored by the Ministry of Economy, Trade and Industry).

Efforts to Prevent Pollution

After treatment at an in-house facility, all process waste water is discharged into the public sewer only after clearing voluntary standards stricter than waste water standards. Sludge produced in waste water treatment is sorted by type and reclaimed.

Measures are taken such as installing equipment indoors to prevent noise escaping to the surrounding area from noisy equipment, such as large fans and large compressors. Noise levels at the site boundary are within regulation values.

The plant is working to improve management of chemical substances, prevent accidents and environmental disasters, and reduce environmental impact.

Efforts to Contribute to the Local Community

Through efforts such as inviting local people to festivals and activities to protect forests, the plant aims to deepen relations with people in the local area and protect the environment.

Efforts are being made to beautify the area by participating in greenification activities in the Mihara Western Industrial District where this facility is located.

* Sharp defines this as bringing the amount of buried waste (final disposal amount) as close to zero as to be negligible.

In figures, a final disposal rate of less than 0.5% (final disposal rate = buried amount / total discharged amount x 100) is taken to be zero emissions.

■ LCD Modules

<For industrial appliances> (1)

	Display size	Model No.	Number of pixels (dot) H × V	Pixel pitch (mm) H × V	Display colors	Lumi- nance (cd/m ²)	Input video signal	Power consumption (W)	Outline dimensions (mm) W × H × D	Weight (g)	Backlight	Remarks
TFT	28.3" (72cm)	LQ283G1TW11	2 560 × RGB × 2 048	0.219 × 0.219	16.77 M	225	4ch TMDS	103.2	640.0 × 530.0 × 60.0	Max. 15 000	18CCFT	Built-in inverter Advanced Super V
	28.1" (71cm)	LQ281L1LW14	2 048 × RGB × 2 048	0.246 × 0.246	16.77 M	225	4ch LVDS	96.0	594.0 × 594.0 × 83.0	15 000	18CCFT	Built-in inverter Advanced Super V
	23.1" (59cm)	☆LQ231U1LW31	1 600 × RGB × 1 200	0.294 × 0.294	16.77 M	500	LDI 8 bit RGB	T.B.D.	530.0 × 431.5 × 32.5	(Max. 4 500)	LED	Advanced Super V LED backlight
	20.1" (51cm)	LQ201U1LW11Z	1 600 × XYZ × 1 200	0.255 × 0.255	256 (gray scales)	700	2ch LVDS 8 bit XYZ	32.9	436.0 × 335.0 × 27.5	Max. 3 800	6CCFT	Advanced Super V
		LQ201U1LW21	1 600 × RGB × 1 200		16.77 M	250	2ch LVDS 8 bit RGB	33.8	432.0 × 331.5 × 25.0	3 200		
	19.0" (48cm)	LQ190E1LW02	1 280 × RGB × 1 024	0.294 × 0.294	16.77 M	300	2ch LVDS 8 bit RGB	(25.5)	404.2 × 330.0 × 20.0	Max. 2 800	4CCFT	Advanced Super V
		☆LQ190E1LW43				400		37	404.2 × 330.0 × 22.0	Max. 3 200	6CCFT	
		☆LQ190E1LX51				1 000		75	404.2 × 330.0 × 34.0	Max. 2 600	LED	Advanced Super V LED backlight
	15.0" (38cm)	LQ150X1LGB1	1 024 × RGB × 768	0.297 × 0.297	16.19 M	600	1ch LVDS 8 bit RGB (6 bit + 2FRC)	16.0	331.6 × 254.76 × 12.5	1 200±50	4CCFT	Compliant with the PSWG standard
		LQ150X1LG55				350		9.6	326.5 × 253.5 × 11.2	Max. 1 000	2CCFT	
		LQ150X1LG81				350		9.8	326.0 × 252.0 × 11.2			
		LQ150X1LG82				250		10.8	326.0 × 252.0 × 13.7	Max. 1 200	LED	Long-life LED backlight
		LQ150X1LW71N						350	18.1	331.6 × 254.76 × 12.5	Max. 1 300	4CCFT
		LQ150X1LW72				T.B.D.			Max. 1 350			
		☆LQ150X1LW73										
	12.1" (31cm)	LQ121K1LG11	1 280 × RGB × 800	0.204 × 0.204	16.19 M	370 TYP.	1ch LVDS 8 bit RGB	7.7	278.0 × 184.0 × 11.3 TYP.	640	2CCFT	12.1" wide XGA
		LQ121S1DG42/LG42	800 × RGB × 600	0.3075 × 0.3075	260 k	370	CMOS 6 bit RGB/ 1ch LVDS 6 bit RGB	8.3	276.0 × 209.0 × 11.0	Max. 660		Strong LCD2 Long-life LED backlight
		LQ121S1DG61/LG61				450						
		☆LQ121S1LG62				450	1ch LVDS 6 bit RGB	(5.3)		Max. 750		
		LQ121S1LW01				250	8.5	Max. 800		Advanced Super V		
	10.4" (26cm)	LQ104S1DG2A/LG2A	800 × RGB × 600	0.264 × 0.264	260 k	350	CMOS 6 bit RGB/ 1ch LVDS 6 bit RGB	6.5/6.6	246.5 × 179.4 × 15.5	Max. 620	2CCFT	Strong LCD2
		LQ104S1DG61/LG61				420		8.0	246.5 × 179.4 × 13.7	Max. 620		
		LQ104V1DG21	640 × RGB × 480	0.330 × 0.330		350	CMOS 6 bit RGB	6.4	265.0 × 195.0 × 11.5	Max. 700	2CCFT	Strong LCD2
		LQ104V1DG5A				246.5 × 179.4 × 15.5			Max. 620			
		LQ104V1DG61/LG61				450	CMOS 6 bit RGB/ 1ch LVDS 6 bit RGB	6.3	246.5 × 179.4 × 13.7	Max. 580		
		LQ104V1DG62				550					246.5 × 179.4 × 12.5	

(Note) The following models listed on this page are not sold in the United States.
 LQ283G1TW11, LQ281L1LW14, LQ231U1LW31, LQ201U1LW11Z, LQ201U1LW21,
 LQ190E1LW02, LQ190E1LW43, LQ190E1LX51, LQ150X1LW71N, LQ150X1LW72,
 LQ121S1LW01

Notice

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<For industrial appliances> (2)

	Display size	Model No.	Number of pixels (dot) H × V	Pixel pitch (mm) H × V	Display colors	Lumi- nance (cd/m ²)	Input video signal	Power con- sumption (W)	Outline dimensions (mm) W × H × D	Weight (g)	Backlight	Remarks	
TFT	8.4'' (21cm)	LQ084S3DG01	800 × RGB × 600	0.213 × 0.213	260 k	350	CMOS 6 bit RGB	6.0	199.5 × 149.5 × 11.6	Max. 405	2CCFT	Strong LCD2	
		LQ084S3LG01	800 × RGB × 600		16.19 M	400	1ch LVDS 8 bit RGB	5.9					
		LQ084V3DG01	640 × RGB × 480	0.270 × 0.270	260 k		CMOS 6 bit RGB	5.7		Max. 400			
		LQ084V3DG02		0.267 × 0.267			CMOS 6 bit RGB	4.6		221.0 × 152.4 × 12.0	Max. 430	1CCFT	Long-life LED backlight
		LQ084V1DG41				300						4.9	
	6.4'' (16cm)	LQ064V3DG01	640 × RGB × 480	0.204 × 0.204	260 k	350	CMOS 6 bit RGB	4.7	161.3 × 117.0 × 12.0	Max. 280	2CCFT		
	5.7'' (14cm)	LQ057V3DG01	640 × RGB × 480	0.180 × 0.180	260 k	400	CMOS 6 bit RGB	4.1	144.0 × 104.6 × 12.3*	Max. 250	1CCFT	Strong LCD2	
		LQ057V3DG02				400		4.5	144.0 × 104.6 × 13.0				
		☆LQ057V3LG11			16 M	350	1ch LVDS 8 bit RGB	2.3	144.0 × 104.6 × 12.3	Max. 190	LED	Long-life LED backlight	
		LQ057Q3DC12	320 × RGB × 240	0.360 × 0.360	260 k	500	CMOS 6 bit RGB	3.9	144.0 × 104.6 × 13.0	Max. 240	1CCFT		
		☆LQ057Q3DG01				320		1.4	144.0 × 104.6 × 13.8	230	LED	LED backlight with resistive-film touch panel	
		☆LQ057Q3DG02				400			144.0 × 104.6 × 12.3	190		LED backlight	
	4.3'' (12cm)	LQ043T3DG01	480 × RGB × 272	0.198 × 0.198	260 k	400	CMOS 6 bit RGB	0.6	105.5 × 67.2 × 5.05	65	LED	LED backlight	
		LQ043T3DG02				480			105.5 × 67.2 × 3.95	55			
	3.8'' (10cm)	LQ038Q3DC01	320 × RGB × 240	0.240 × 0.240	260 k	240	CMOS 6 bit RGB	0.7	90.6 × 79.9 × 9.9	Max. 105			
	3.5'' (9cm)	LQ035Q3DG01			260 k	450		0.48	76.9 × 63.9 × 3.5	33			
		☆LQ035Q3DG03		0.2205 × 0.2205	16 M	(450)	T.B.D.	76.9 × 63.9 × 4.7	T.B.D.	Long-life LED backlight			
		LQ035Q3DW02			260 k	450	0.5	76.9 × 63.9 × Max. 3.5	33	Advanced Super V LED backlight			
	2.5'' (6cm)	LQ025Q3DW02			0.156 × 0.156	260 k	350 TYP.	CMOS 6 bit RGB	0.28	56.8 × 48.8 × Max. 3.5			Max. 25

* Protrusions such as backlight harnesses and positioning bosses are not included.

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<Large-size LCD Module>

Display size (cm) ["]	Model No.	Number of pixels*1	Dot format H × V (dot)	Active area H × V (mm)	Number of colors (color)	Outline dimensions*2 W × H × D (TYP.) (mm)	Backlight	Interface (Input signal)	Remarks
TFT	207.2 [81.6]	★LK816D3LA19	2 073 600	1 080 × 1 920 × RGB	1 015.7 × 1 805.8	16.77M	1 094.0 × 1 879.0 × (81.9)	2ch-LVDS*3 (8-bit digital)	Portrait/Landscape free-setting Advanced Super V High luminance: (1 500 Max.)*4 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (1 500:1) High-speed response [G to G]: (6) ms (Ave.)
		★LK816D3LA29	2 073 600	1 080 × 1 920 × RGB	1 015.7 × 1 805.8	16.77M	1 094.0 × 1 879.0 × (81.9)	2ch-LVDS*3 (8-bit digital)	Portrait/Landscape free-setting Advanced Super V High luminance: (700) cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (1 500:1) High-speed response [G to G]: (6) ms (Ave.)
	152.5 [60]	★LK600D3LA38	2 073 600	1 920 × RGB × 1 080	1 329.1 × 747.6	1.06B (8-bit + 2FRC)	(1 401.1 × 820.4 × 43.0)	2ch-LVDS*3 (10-bit digital)	Ultraviolet induced multi-domain Vertical Alignment LCD High luminance: 500 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (5 000:1) 120 Hz drive compatible
	132.2 [52]	★LK520D3LA5X	2 073 600	1 920 × RGB × 1 080	1 152.0 × 648.0	1.06B (8-bit + 2FRC)	(1 219.0 × 706.7 × 36.6)	2ch-LVDS*3 (10-bit digital)	Advanced Super V High luminance: 500 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (2 000:1) High-speed response [G to G]: (6) ms (Ave.)
	116.8 [46]	★LK460D3LA2X	2 073 600	1 920 × RGB × 1 080	1 018.1 × 572.7	1.06B (8-bit + 2FRC)	(1 083.0 × 624.7 × 32.5)	2ch-LVDS*3 (10-bit digital)	Advanced Super V High luminance: 500 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (3 000:1) High-speed response [G to G]: (6) ms (Ave.)
	101.6 [40]	★LK400D3LA14	2 073 600	1 920 × RGB × 1 080	885.6 × 498.2	1.06B (8-bit + 2FRC)	(952.0 × 551.0 × 35.0)	2ch-LVDS*3 (10-bit digital)	Advanced Super V High luminance: 500 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (2 500:1) High-speed response [G to G]: (6) ms (Ave.)
	80.0 [31.5]	★LK315T3LA5X	1 049 088	1 366 × RGB × 768	697.7 × 392.3	16.77M	(760.0 × 450.0 × 32.5)	1ch-LVDS*3 (8-bit digital)	Advanced Super V High luminance: 500 cd/m ² Wide viewing angle: L/R 176°/ U/D 176° High contrast: (2 500:1) High-speed response [G to G]: (7) ms (Ave.)

*1 Pixel means a set of each RGB dot.

*2 Excluding FPC for connection and other protruding parts.

*3 LVDS: Low Voltage Differential Signaling

*4 With cooling module prepared by user.

(Note) Please note that the specifications are subject to change without prior notice for product improvement.

(Note) The following models listed on this page are not sold in the United States.
LK816D3LA19, LK816D3LA29, LK520D3LA5X, LK460D3LA2X, LK400D3LA14, LK315T3LA5X

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☆New product

★Under development

<For automotive applications> (1)

● LQ065T9DZ03A: operating temperature (panel surface temperature) -40 to +85°C / storage temperature -40 to +95°C

● Other models: operating temperature (panel surface temperature) -30 to +85°C / storage temperature -40 to +85°C

	Display size (cm) ["]	Model No.	Dot format H × V (dot)	Pixel pitch H × V (mm)	Active area H × V (mm)	Input signal system	Input video signal	Back-light	Luminance (cd/m ²) (TYP.)	Power consumption (mW) (TYP.)	Outline dimensions*1 W × H × D (mm) (TYP.)	Weight (g) (TYP.)	Remarks
TFT	7.6 [3]	★LQ030T5DG01	480 × RGB × 240	0.13925 × 0.153	66.84 × 36.72	6-bit digital RGB	6-bit digital	Built-in LED	400	T.B.D.	77 × 48 × 6.0	T.B.D.	Wide QVGA (16:9), Thin, LED backlight, 260K-color display, Wide viewing angle
	8.9 [3.5]	LQ035Q5DG02	320 × RGB × 240	0.222 × 0.222	71.0 × 53.3	6-bit digital RGB	6-bit digital	Built-in LED	500	T.B.D.	86.4 × 84 × 6.7	65	"Compact LCD" suitable for display in meter, LED backlight, High luminance, Thin, High-speed response (low temperature), 260K-color display, Wide viewing angle, RoHS compliant
	11 [4.3]	☆LQ043T5DG02	400 × RGB × 234	0.2385 × 0.2275	95.4 × 53.24	6-bit digital RGB	6-bit digital	Built-in LED	500	1 200	107.7 × 65.5 × 8.15	65	Wide QVGA (16:9), LED backlight, Digital I/F, 260K-color display, High luminance, Wide viewing angle, RoHS compliant
	12.7 [5]	☆LQ050T5DG01	400 × RGB × 240	0.27 × 0.27	108 × 64.8	6-bit digital RGB	6-bit digital	Built-in LED	600	840	120.6 × 75.2 × 9.0	110	Wide QVGA (16:9), LED backlight, Thin, 260K-color display
	15 [5.8]	☆LQ058T5DG02	480 × RGB × 240	0.268 × 0.297	128.4 × 70.92	6-bit digital RGB	6-bit digital	Built-in LED	420	994	139 × 82.7 × 6.0	120 (Max.)	Wide QVGA (16:9), LED backlight, Thin, 260K-color display
		LQ058Y5DG01	800 × RGB × 480	0.1605 × 0.1505	128.4 × 72.24	6-bit digital RGB	6-bit digital*2	Built-in LED	450	3 100	141.1 × 82.9 × 7.2	140 (Max.)	High resolution (wide VGA/16:9), LED backlight, Thin, Digital I/F, 260K-color display, Wide viewing angle, RoHS compliant
	16 [6.5]	☆LQ065T5GG64	400 × RGB × 234	0.3585 × 0.339	143.4 × 79.326	NTSC/ PAL	TFT specific analog RGB*2	Built-in LED	900	1 220	155 × 89.2 × 6.5	140 (Max.)	Wide QVGA (16:9), Thin, High luminance, LED backlight, 260K-color display, Wide viewing angle, RoHS compliant
		LQ065T5DG02	400 × RGB × 240	0.359 × 0.331	143.4 × 79.3	6-bit digital RGB	6-bit digital*2	Built-in 1CCFT	620	4 100	155 × 89.2 × 9.1	170	Wide QVGA (16:9), Digital I/F, 260K-color display, High luminance, Wide viewing angle, RoHS compliant
		LQ065T9DZ03A	400 × RGB × 240	0.359 × 0.331	143.4 × 79.3	6-bit digital RGB	6-bit digital	Built-in 1CCFT	250	5 200	155 × 89.2 × 12.5	205 (Max.)	"Super Mobile LCD" with high visibility under bright ambient light, Wide QVGA (16:9), Wide viewing angle, Gray-scale inversion free, 260K-color display, RoHS compliant
		LQ065Y5DG03	800 × RGB × 480	0.18 × 0.165	144.0 × 79.2	6-bit digital RGB	6-bit digital*2	Built-in 1CCFT	500	3 600	157.4 × 89.7 × 7.5	180 (Max.)	High resolution (wide VGA/16:9), digital I/F, 260K-color display, High luminance, Wide viewing angle, RoHS compliant

*1 Excluding FPC for connection and other protruding parts.

*2 Video interface: External (Device specific external video interface IC is available.)

(Note) Please refer to the latest relevant specification sheets before using these devices.

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<For automotive applications> (2)

● LQ070Y5DG06/LQ080Y5DG03/LQ080Y5DR04: operating temperature (panel surface temperature) –30 to +85°C / storage temperature –40 to +95°C

● Other models: operating temperature (panel surface temperature) –30 to +85°C / storage temperature –40 to +85°C

	Display size (cm) ["]	Model No.	Dot format H × V (dot)	Pixel pitch H × V (mm)	Active area H × V (mm)	Input signal system	Input video signal	Back-light	Luminance (cd/m ²) (TYP.)	Power consumption (mW) (TYP.)	Outline dimensions*1 W × H × D (mm) (TYP.)	Weight (g) (TYP.)	Remarks
TFT	18 [7]	☆LQ070T5DG04	480 × RGB × 240	0.326 × 0.339	156.48 × 81.72	6-bit digital RGB	6-bit digital	Built-in LED	450	1 184	167 × 93 × 6.0	150 (Max)	Wide QVGA (16:9), LED backlight, 260K-color display, RoHS compliant
		☆LQ070T5DG05	480 × RGB × 240	0.321 × 0.363	154.08 × 86.94	6-bit digital RGB	6-bit digital	Built-in LED	450	1 314	164.4 × 99.5 × 6.0	160 (Max)	Wide QVGA (16:9), LED backlight, 260K-color display, RoHS compliant
		LQ070Y5DG06	800 × RGB × 480	0.191 × 0.191	152.4 × 91.4	6-bit digital RGB	6-bit digital*2	Built-in LED	430*3	4 900	170 × 104 × 8.0	210	High resolution (wide VGA/15:9), High color purity (65% of NTSC), High-speed response (low temperature), LED backlight, Thin, 260K-color display, Wide viewing angle, RoHS compliant
		LQ070Y5DG20	800 × RGB × 480	0.195 × 0.1725	156.0 × 82.8	6-bit digital RGB	6-bit digital*2	Built-in 1CCFT	500	3 600	167 × 93 × 7.2	196 (Max)	High resolution (wide VGA/17:9), Thin, W-QVGA (GG21) vertical/horizontal compatible, 260K-color display, Wide viewing angle, RoHS compliant
		LQ070Y5DE03	800 × RGB × 480	0.195 × 0.1725	156.0 × 82.8	6-bit digital RGB	6-bit digital*2	Built-in LED	370*3	6 400	170.8 × 107.95 × 12.6	315 (Max.)	Dual directional viewing LCD, Wide screen (17:9), LED backlight, 260K-color display, Wide viewing angle, RoHS compliant
	20 [8]	LQ080Y5DG03	800 × RGB × 480	0.2175 × 0.2175	174.0 × 104.4	6-bit digital RGB	6-bit digital*2	Built-in LED	430*3	6 200	190 × 120 × 8.0	270	High resolution (wide VGA/15:9), High color purity (65% of NTSC), High-speed response (low temperature), LED backlight, Thin, 260K-color display, Wide viewing angle, RoHS compliant
		LQ080Y5DR04	800 × RGB × 480	0.2175 × 0.2175	174.0 × 104.4	6-bit digital RGB	6-bit digital*2	Built-in LED	480	6 200	190 × 120 × 8.0	290 (Max.)	High resolution (wide VGA/15:9), Thin, LED backlight, 260K-color display, Wide viewing angle, RoHS compliant
		LQ080Y5DGQ3	800 × RGB × 480	0.222 × 0.207	177.6 × 99.4	NTSC/PAL/PAL (60)	Composite	Built-in 1CCFT	400	10 400	198 × 117 × 17.9	391	High resolution (wide VGA/16:9), All-in-one, Wide viewing angle, RoHS compliant
		☆LQ080Y5DW01	800 × RGB × 480	0.2175 × 0.2175	174.0 × 104.4	6-bit digital RGB	6-bit digital	Built-in LED	625	9 925	190 × 120 × 13.0	385	Wide VGA (15:9), LED backlight, 260K-color display, RoHS compliant
		☆LQ080Y5DW30	800 × RGB × 480	0.2175 × 0.2175	174.0 × 104.4	6-bit digital RGB	6-bit digital	Built-in LED	543	8 632	190 × 120 × 15.0	435	Wide VGA (15:9), LED backlight, 260K-color display, Touch panel, RoHS compliant

*1 Excluding FPC for connection and other protruding parts.

*2 Video interface: External (Device specific external video interface IC is available.)

*3 Luminosity at eye point

(Note) Please refer to the latest relevant specification sheets before using these devices.

The plants No. 1 and No. 2 (JQA-AU0121) at the Mie site of the Mobile Liquid Crystal Display Group have been certified under the ISO/TS 16949:2002 Quality Management System. [Certifying organization: Japan Quality Assurance Organization (JQA)]

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<For automotive applications> (3)

● Operating temperature (panel surface temperature) –30 to +85°C / storage temperature –40 to +85°C

	Display size (cm) ["]	Model No.	Dot format H × V (dot)	Pixel pitch H × V (mm)	Active area H × V (mm)	Input signal system	Input video signal	Back-light	Luminance (cd/m ²) (TYP.)	Power consumption (mW) (TYP.)	Outline dimensions*1 W × H × D (mm) (TYP.)	Weight (g) (TYP.)	Remarks
TFT	20 [8]	☆LQ080Y5DE30	800 × RGB × 480	0.2175 × 0.2175	174.0 × 104.4	6-bit digital RGB	6-bit digital	Built-in LED	272*3	8 617	190 × 120 × 15.0	439	Dual directional viewing LCD, Wide VGA (16:9), LED backlight, 260K-color display, Touch panel, RoHS compliant

*1 Excluding FPC for connection and other protruding parts.

*2 Video interface: External (Device specific external video interface IC is available.)

*3 Luminosity at eye point

(Note) Please refer to the latest relevant specification sheets before using these devices.

The plants No. 1 and No. 2 (JQA-AU0121) at the Mie site of the Mobile Liquid Crystal Display Group have been certified under the ISO/TS 16949:2002 Quality Management System. [Certifying organization: Japan Quality Assurance Organization (JQA)]

<For mobile phones>

	Display size (cm) ["]	Model No.	Dot format H × V (dot)	Pixel pitch H × V (mm)	Active area H × V (mm)	Input video signal	Back-light	Contrast ratio (Transmissive/ Reflective)	Luminance (cd/m ²) (TYP.)	Outline dimensions*2 W × H × D (mm) (TYP.)	Weight (g) (TYP.)	Remarks
TFT	7.2 [2.8]	LQ028Q3UX01	240 × RGB × 320*1	0.18 × 0.18	43.2 × 57.6	16-bit parallel CPU	Built-in LED	500 : 1	250	50.2 × 69.3 × 3.6	T.B.D.	

*1 Number of Pixels: 76 800

*2 Excluding FPC for connection and other protruding parts.

(Note) Please refer to the latest relevant specification sheets before using these devices.

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CMOS Camera Modules Road Map

Image format	2008 or before	2009	2010	
5 M (QSXGA)		RJ63SC400  1/3.2 type 0.53 cc Built-in auto focus function 9.5 x 9.5 x 5.9	★RJ63SC500  1/3.2 type 0.53 cc Built-in auto focus function 9.5 x 9.5 x 5.9	★RJ64SC100  1/4 type 0.36 cc Built-in auto focus function 8.5 x 8.5 x 5.0
3 M (QXGA)	RJ64PC200  1/4 type 0.38 cc Built-in auto focus function 8.5 x 8.5 x 5.3		★RJ64PC700  1/4 type 0.43 cc Built-in auto focus function 8.5 x 8.5 x 6.0	★RJ64PC800  1/4 type 0.37 cc Built-in auto focus function 8.5 x 8.5 x 5.1
2 M (UXGA)	RJ65NC100  1/5 type 0.20 cc Built-in auto focus function 7.0 x 7.0 x 4.0			
VGA	RJ6ABA103  1/10 type 0.05 cc 5.0 x 5.0 x 1.95	RJ68BA100  1/8 type 0.07 cc 6.0 x 5.5 x 2.2		★RJ6ABA600  1/10 type 0.05 cc 5.0 x 5.0 x 1.95

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Model No.

Optical format & volume

Outline dimensions (D x W x H) TYP. (mm)

■ CMOS Camera Modules

Module configuration : CMOS image sensor, CDS/AGC/10-bit ADC, timing generator, DSP*, lens

Color filter : R, G, B primary color mosaic filters

Operating temperature : -20 to 60°C

* For RJ63SC500/RJ64PC700, DSP is externally mounted.

Optical format	Image format	Optical function	Model No.	Features	Output pixels (H x V) MAX.	Lens			Output signal	Supply voltage (V)	Power consumption (mW) TYP.	Package*2
						F No.	Configuration	Horizontal viewing angle (°)				
1/3.2 type	QSXGA	Auto focus function	RJ63SC400	• QSXGA to SubQCIF • 5 fps at QSXGA/30 fps at VGA • 8x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	2 592 x 1 944	F2.8	4 pcs.	61	UYVY (Parallel)	2.8/1.8 (I/O: 1.8 or 2.8)	240 (at 5 fps)	40FPC type
			★RJ63SC500*1	• QSXGA to SubQCIF • 5 fps at QSXGA/30 fps at VGA • Image inversion function (right and left)					RAW10 (Parallel)		120 (at 5 fps)	34FPC type
★RJ64SC100			• QSXGA to SubQCIF • 5 fps at QSXGA/30 fps at VGA • 8x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	54	UYVY (Parallel)		T.B.D.	35FPC type				
1/4 type	QXGA		RJ64PC200	• QXGA to SubQCIF • 7.5 fps at QXGA/30 fps at XGA • 6.4x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	2 048 x 1 536		3 pcs.	53	RAW10 (Parallel)		230 (at 7.5 fps)	30FPC type
			★RJ64PC700*1	• QXGA to SubQCIF • 7.5 fps at QXGA/30 fps at XGA • Image inversion function (right and left)			4 pcs.	54	UYVY (Parallel)		110 (at 7.5 fps)	27FPC type
			★RJ64PC800	• QXGA to SubQCIF • 7.5 fps at QXGA/30 fps at XGA • 6.4x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)					UYVY (Parallel)		190 (at 7.5 fps)	
1/5 type	UXGA		RJ65NC100	• UXGA to SubQCIF • 10 fps at UXGA/30 fps at SXGA • 5x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	1 600 x 1 200		3 pcs.	54	UYVY (Parallel)		220 (at 10 fps)	30FPC type
1/8 type	FWVGA	RJ68BA100	• FWVGA to SubQCIF • 30 fps at FWVGA • 2x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	854 x 480	2 pcs.	62	UYVY (Mipi)	125 (at 30 fps)	17FPC type			
1/10 type	VGA	RJ6ABA103	• VGA to SubQCIF • 30 fps at VGA • 2x electronic zoom at QVGA size (MAX.) • Image inversion function (right and left)	640 x 480			54	UYVY (Parallel)	70 (at 30 fps)	20LCC type (Socket mounted only)		
		★RJ6ABA600	• Image inversion function (right and left)					UYVY (Mipi)	90 (at 30 fps)	21FPC type		

*1 DSP is externally mounted.

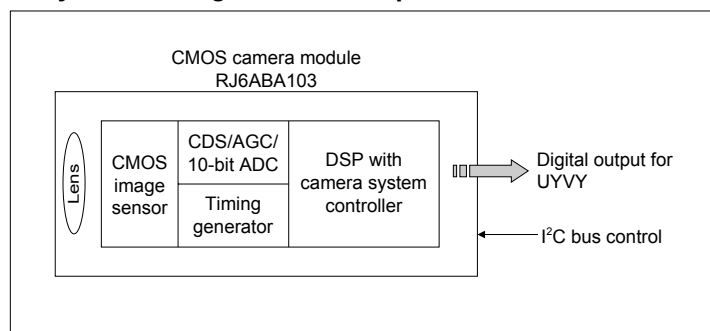
*2 Contact a SHARP sales office regarding FPC type package.

● Outline Dimensions

Model No.	Outline dimensions (D x W x H) TYP. (mm)	Package*1
RJ63SC400	9.5 x 9.5 x 5.9	40FPC type
★RJ63SC500	9.5 x 9.5 x 5.9	34FPC type
★RJ64SC100	8.5 x 8.5 x 5.0	35FPC type
RJ64PC200	8.5 x 8.5 x 5.3	30FPC type
★RJ64PC700	8.5 x 8.5 x 6.0	27FPC type
★RJ64PC800	8.5 x 8.5 x 5.1	
RJ65NC100	7.0 x 7.0 x 4.0	30FPC type
RJ68BA100	6.0 x 5.5 x 2.2	17FPC type
RJ6ABA103	5.0 x 5.0 x 1.95	20LCC type (Socket mounted only)
★RJ6ABA600	5.0 x 5.0 x 1.95	21FPC type

*1 Contact a SHARP sales office regarding FPC type package.

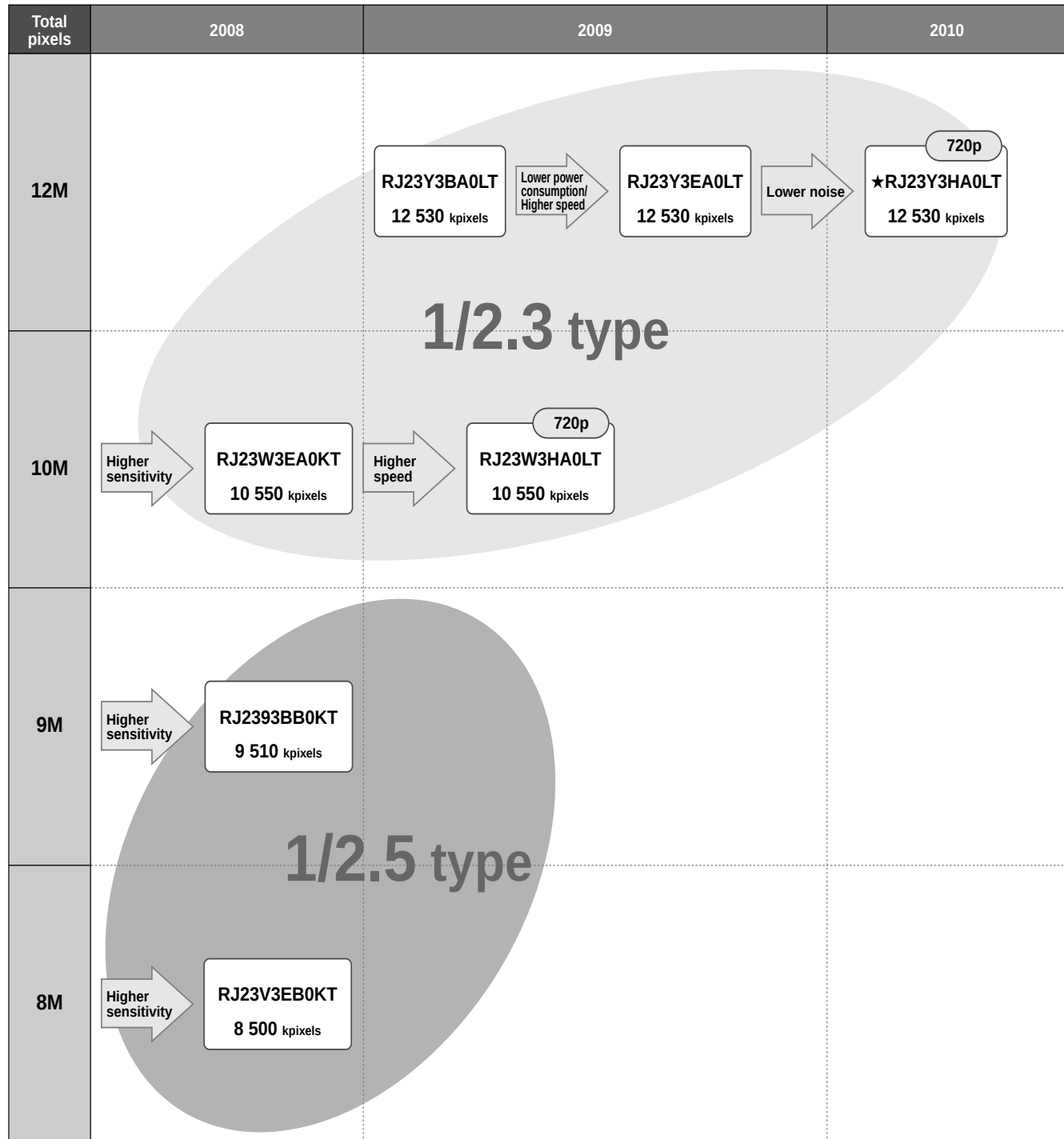
● System Configuration Example



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■ Road Map for High-resolution CCDs for Digital Cameras



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High-resolution CCDs

Optical format	Total pixels	Color f lter	Model No.	Movie function	Resolution	Pixel size H x V (μm ²)	Sensitivity (mV) TYP.	Smear ratio (dB) TYP.	Package
					Image pixels (H x V)				
1/2.3 type	10 550 k	R,G,B primary color mosaic f lters	RJ23W3EA0KT	VGA 30 fps	3 704 x 2 784	1.68 x 1.68	105	-87	N-LCC040-S433A
			RJ23W3HA0LT	720p 30 fps			100		N-LCC040-R350
	12 530 k		RJ23Y3BA0LT	VGA 30 fps	4 040 x 3 032	1.55 x 1.55	100	-83	
			RJ23Y3EA0LT				-86		
			★RJ23Y3HA0LT	720p 30 fps			105	-84	
1/2.5 type	8 500 k		RJ23V3EB0KT	VGA 30 fps	3 320 x 2 496	1.75 x 1.75	100	-85	N-LCC040-S433A
	9 510 k		RJ2393BB0KT	VGA 30 fps	3 512 x 2 640	1.66 x 1.66	100	-83	

1/3-type CCDs

Total pixels	Standard		Model No.	Resolution		Pixel size H x V (μm ²)	Sensitivity (mV) TYP.	Smear ratio (dB) TYP.	Package
				Horizontal TV lines	Image pixels (H x V)				
270 k	Color	NTSC	RJ2311DB0PB*	330	512 x 492	9.6 x 7.5	3 200	−135	P-DIP016-0450
			RJ2312DB0PB*						
320 k		PAL	RJ2321DB0PB*		512 x 582	9.6 x 6.34	3 200	−135	
			RJ2322DB0PB*						
410 k		NTSC	RJ2351CA0PB*	480	768 x 494	6.4 x 7.5	2 000	−120	
			RJ2352CA0PB*						
470 k		PAL	RJ2361CA0PB*		752 x 582	6.5 x 6.3	2 000	−120	
			RJ2362CA0PB*						

* Suitable for intense light exposure.

1/3.8-type CCD

Total pixels	Standard		Model No.	Resolution		Pixel size H x V (μm ²)	Sensitivity TYP. (mV)	Smear ratio TYP. (dB)	Package
				Horizontal TV lines	Image pixels (H x V)				
290 k	Color	NTSC	RJ2411CA0PB*	330	532 x 512	7.2 x 5.6	1 200	−120	P-DIP014-0400A

* Suitable for intense light exposure.

1/4-type CCDs

Total pixels	Standard		Model No.	Resolution		Pixel size H x V (μm ²)	Sensitivity TYP. (mV)	Smear ratio TYP. (dB)	Package
				Horizontal TV lines	Image pixels (H x V)				
270 k	Color	NTSC	RJ2411BA0PB*	330	512 x 492	7.2 x 5.6	1 200	−120	P-DIP014-0400A
			RJ2411BB0PB					−130	
			★RJ2411EA0PB*						
			★RJ2411EB0PB				1 800		
			RJ2411DA0PB*					−130	
			★RJ2411FA0PB*						
320 k		PAL	RJ2421BB0PB	512 x 582	7.2 x 4.73	1 100	−120		
			★RJ2421EB0PB				−130		
			RJ2421DA0PB*			1 650	−120		
			★RJ2421FA0PB*				−130		
410 k		NTSC	RJ2451BA0PB	480	768 x 494	4.9 x 5.6	600	−114	
			RJ2451CA0PB*				900		
470 k	PAL	RJ2461BA0PB	752 x 582	5.0 x 4.77	600	−114			
		RJ2461CA0PB*			900				

* Suitable for intense light exposure.

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■ CCD Peripheral ICs/LSIs

Description	Model No.	Features		Package
V driver	LR366851	Vertical pulse driver for CCDs, 2-level output x 2, 3-level output x 4, 2-level output circuit for electronic shutter		P-SSOP024-0275
CDS/PGA/ADC	IR3Y48B1	Low power consumption [80 mW (TYP.)], high-speed S/H circuit, high-gain PGA circuit, 10-bit ADC (18 MHz), 10-bit digital output		P-QFP048-0707
	IR3Y60U6	Low power consumption [69 mW (TYP.)], high-speed S/H circuit, high-gain PGA circuit, 10-bit ADC (20 MHz), 10-bit digital output		P-VQFN032-0505
	IR3Y50U6	Low power consumption [75 mW (TYP.)], high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC (25 MHz), 12-bit digital output		P-VQFN036-0606
	LR36B03	Low power consumption [81 mW (TYP.)], high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC (25 MHz), mechanical iris control function, 12-bit digital output		P-VQFN036-0606
V driver + CDS/PGA/ADC + DSP	LR38653	For 270-k/320-k/410-k/ 470-kpixel CCDs	<V driver> Vertical pulse driver for CCDs, 2-level output x 2, 3-level output x 2, 2-level output circuit for electronic shutter <CDS/PGA/ADC> 25 MHz, high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC <DSP> 10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, YUV digital output, NTSC/PAL analog output	P-LFBGA171-0811
	LR38654	For 270-k/290-k/320-k/410-k/ 470-kpixel CCDs	<V driver> Vertical pulse driver for CCDs, 2-level output x 2, 3-level output x 2, 2-level output circuit for electronic shutter <CDS/PGA/ADC> 25 MHz, high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC <DSP> 10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, electronic optical axis adjustment function*1, YUV digital output, NTSC/PAL analog output	P-LFBGA171-0811
CDS/PGA/ADC + DSP	★LR38692	For 1 310-kpixel CCDs	<CDS/PGA/ADC> 36 MHz, high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC <DSP> 10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, mechanical iris control function, privacy masking function, Day/Night control function, color rolling suppression function, high resolution function, motion detection function, auto focus control function, NTSC/PAL analog output, Y/C analog output, UYVY digital output (ITU-R BT656 compliant)	P-LFBGA256-1111
	★LR38693	For 410-k/470-kpixel CCDs	<CDS/PGA/ADC> 36 MHz, high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC <DSP> 10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, mechanical iris control function, privacy masking function, Day/Night control function, color rolling suppression function, high resolution function, line lock function, motion detection function, auto focus control function, wide dynamic range function, slow shutter function, NTSC/PAL analog output, Y/C analog output, UYVY digital output (ITU-R BT656 compliant)	

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■ CCD Peripheral ICs/LSIs (cont'd)

Description	Model No.	Features		Package
CDS/PGA/ADC + DSP	★LR38694	For 410-k/470-kpixel CCDs	<CDS/PGA/ADC> 36 MHz, high-speed S/H circuit, high-gain PGA circuit, 12-bit ADC <DSP> 10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, mechanical iris control function, privacy masking function, Day/Night control function, color rolling suppression function, high resolution function, line lock function, motion detection function, auto focus control function, NTSC/PAL analog output, Y/C analog output, UYVY digital output (ITU-R BT656 compliant)	P-LFBGA256-1111
DSP	LR386032	For 270-k/320-k/410-k/470-kpixel CCDs	9-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, mirror image function, YUV digital output, NTSC/PAL analog output	P-LQFP080-1212
	LR38627		10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, YUV digital output, NTSC/PAL analog output	P-TQFP128-1414
	LR38690		10-bit DAC, synchronous signal generation circuit, CCD drive timing generator, AE control function, AWB control function, lens shading correction function, auto white blemish compensation function, mirror image function, mechanical iris control function, privacy masking function, Day/Night control function, color rolling suppression function, high resolution function, NTSC/PAL analog output, Y/C analog output, UYVY digital output (ITU-R BT656 compliant)*2	P-LQFP100-1414
Power supply IC for CCDs and peripheral ICs/LSIs	IR3M59U	For 270-k/320-kpixel CCDs	Input voltage range: 4.5 to 16 V, PWM control + charge pump system, output voltage: three outputs (15 V/12 V, -8 V/-5 V, 3.3 V), power sequencing circuit, overcurrent protection circuit	P-VQFN032-0505
	IR3M63U	For 270-k/290-k/320-k/410-k/470-kpixel CCDs	Input voltage range: 4.5 to 10 V, PWM control + charge pump system, output voltage: four outputs (15 V, -8 V, 3.3 V, 1.8 V), power sequencing circuit, overcurrent protection circuit	

*1 Support for only 290-kpixel CCD.

*2 Support for only 410-k/470-kpixel CCDs.

Notice

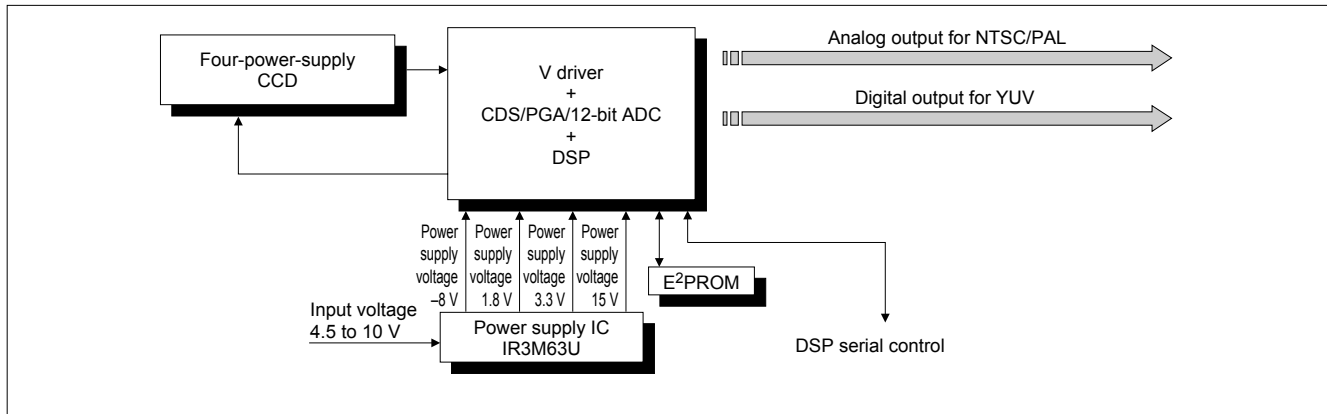
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●System Configuration Examples

<Color Security Camera System with Two-chip Configuration [Low Power Consumption Type]>



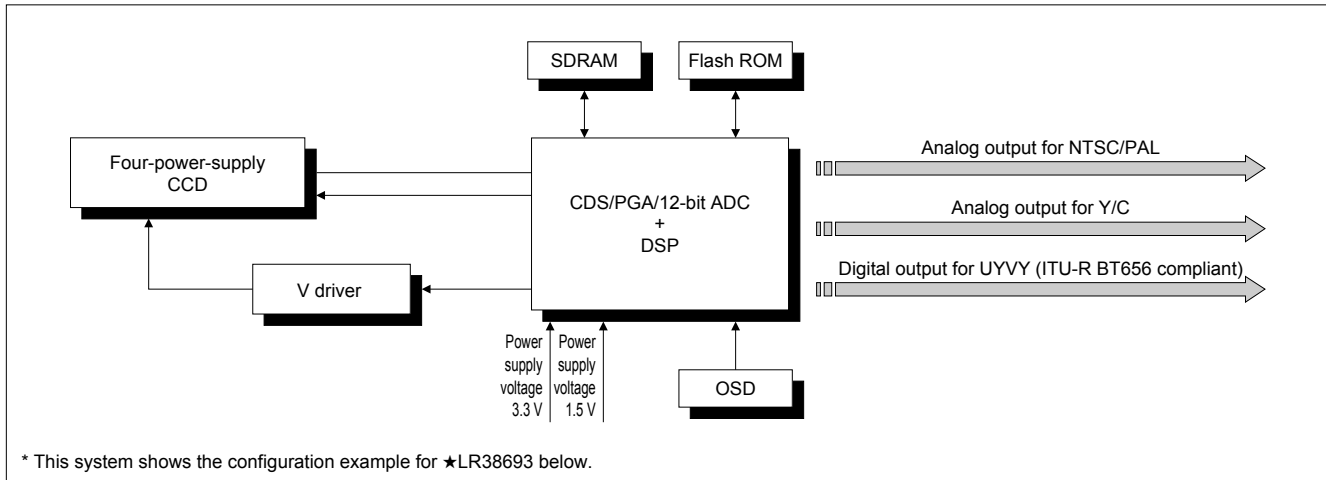
Four-power-supply CCDs and peripheral IC/LSIs

CCD			V driver + CDS/PGA/ADC + DSP	Power supply IC
1/3 type	270 kpixels	RJ2311DB0PB	LR38653/LR38654	—
		RJ2312DB0PB		
	320 kpixels	RJ2321DB0PB		
		RJ2322DB0PB		
	410 kpixels	RJ2351CA0PB		
		RJ2352CA0PB		
1/3.8 type	470 kpixels	RJ2361CA0PB	LR38654	
		RJ2362CA0PB		
1/4 type	270 kpixels	RJ2411BA0PB	LR38653/LR38654	IR3M63U
		RJ2411BB0PB		
		★RJ2411EA0PB		
		★RJ2411EB0PB		
		RJ2411DA0PB		
		★RJ2411FA0PB		
	320 kpixels	RJ2421BB0PB		
		★RJ2421EB0PB		
		RJ2421DA0PB		
		★RJ2421FA0PB		
	410 kpixels	RJ2451BA0PB		
		RJ2451CA0PB		
	470 kpixels	RJ2461BA0PB		
		RJ2461CA0PB		

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<Color Security Camera System with Three-chip Configuration>



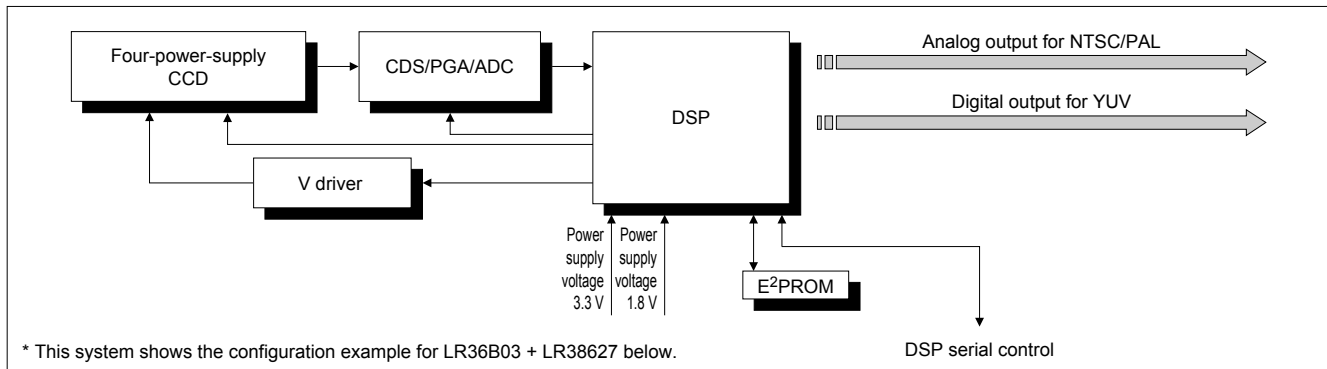
Four-power-supply CCDs and peripheral ICs/LSIs

CCD			CDS/PGA/ADC + DSP
1/3 type	410 kpixels	RJ2351CA0PB	★LR38693/★LR38694
		RJ2352CA0PB	
	470 kpixels	RJ2361CA0PB	
		RJ2362CA0PB	
1/4 type	410 kpixels	RJ2451BA0PB	
		RJ2451CA0PB	
	470 kpixels	RJ2461BA0PB	
		RJ2461CA0PB	

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<Color Security Camera System with Four-chip Configuration (I)>



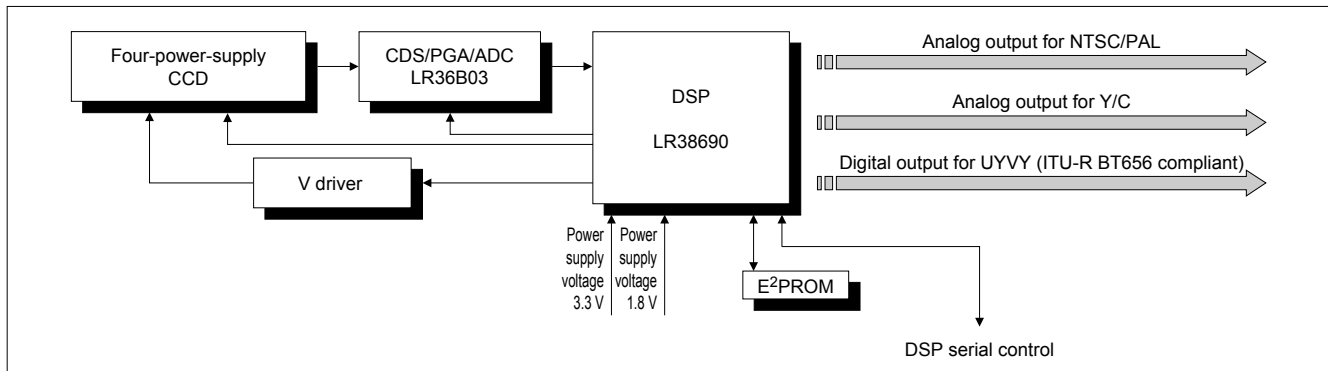
Four-power-supply CCDs and peripheral ICs/LSIs

CCD			CDS/PGA/ADC	DSP
1/3 type	270 kpixels	RJ2311DB0PB	IR3Y48B1 + LR386032/ LR36B03 + LR38627	
		RJ2312DB0PB		
	320 kpixels	RJ2321DB0PB		
		RJ2322DB0PB		
	410 kpixels	RJ2351CA0PB		
		RJ2352CA0PB		
	470 kpixels	RJ2361CA0PB		
		RJ2362CA0PB		
1/4 type	270 kpixels	RJ2411BB0PB		
		★RJ2411EB0PB		
		RJ2411DA0PB		
		★RJ2411FA0PB		
	320 kpixels	RJ2421BB0PB		
		★RJ2421EB0PB		
		RJ2421DA0PB		
		★RJ2421FA0PB		
	410 kpixels	RJ2451BA0PB		
		RJ2451CA0PB		
	470 kpixels	RJ2461BA0PB		
		RJ2461CA0PB		

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<Color Security Camera System with Four-chip Configuration (II)>



Four-power-supply CCDs and peripheral ICs/LSIs

CCD			CDS/PGA/ADC	DSP
1/3 type	270 kpixels	RJ2311DB0PB	LR36B03	LR38690
		RJ2312DB0PB		
	320 kpixels	RJ2321DB0PB		
		RJ2322DB0PB		
	410 kpixels	RJ2351CA0PB		
		RJ2352CA0PB		
	470 kpixels	RJ2361CA0PB		
		RJ2362CA0PB		
1/4 type	270 kpixels	RJ2411BB0PB		
		★RJ2411EB0PB		
		RJ2411DA0PB		
		★RJ2411FA0PB		
	320 kpixels	RJ2421BB0PB		
		★RJ2421EB0PB		
		RJ2421DA0PB		
		★RJ2421FA0PB		
	410 kpixels	RJ2451BA0PB		
		RJ2451CA0PB		
	470 kpixels	RJ2461BA0PB		
		RJ2461CA0PB		

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■ For Notebook PCs, PC Monitors and LCD TVs

● TFT-LCD Drivers

Drive function		Model No.	Gray scale	No. of LCD drive outputs	Display voltage (V) MAX.	Clock frequency (MHz) MAX.	Supply voltage (V)	Description	Package
Source driver	Dot inversion drive	☆LH16CR	256 levels	414	16.5	85	2.7 to 3.6	Low EMI*1 driver using RSDS™*2 interface, built-in reference voltage generation circuit, R-DAC system	SOF
		★LH16DH		804/840/912/960		330		Low EMI*1 driver using mini-LVDS interface, R-DAC system	
		☆LH16DD		630/642/684/720		250			

*1 EMI: Electro-Magnetic Interference

*2 RSDS™: Reduced Swing Differential Signaling

● TFT-LCD Controller

Model No.	Image size	Input interface	Output interface	Function	Clock frequency (MHz) MAX.	Supply voltage (V)			Package
						Core	Digital	Analog	
LR388F5A	1 366 x 768	LVDS 1ch 10/8 bits	RSDS 8/6 bits 2/1ch mini-LVDS 8 bits 2/1ch	- Improves response speed of LCD image by original Quick Shoot technology (with a built-in frame memory) - Register control by external EEPROM (SPI) and I²C I/F - Control by gamma correction IC (SPI)	85	1.1 to 1.3	3.0 to 3.6	2.3 to 2.7	TFBGA204-1212

RSDS and PPDS are trademarks of National Semiconductor Corporation.

■ For Mobile Phones

● TFT-LCD Controllers

Model No.	LCD interface (pixel) MAX.	Display colors MAX.	Display RAM capacity (bit)	Function	CPU interface	Supply voltage (V)		Package
						Core	Host I/F	
LR388D8	480 x 864	16 770 k colors	16 M (Flexibly meets the requirement depending on the panel size)	• MDDI*1-compliant • Built-in IrSimple™ and IrDA communications functions • Main/sub LCD controller • Graphic processing • Built-in SDHC	MDDI*1 for MSM series/ 80-family (8/9/16/ 18-bit parallel)	1.08 to 1.32	1.65 to 3.6	P-WFBGA205-0808
LR388D1	240 x 400	262 144 colors	240 x 400 x 18	• MDDI*1-compliant • Built-in IrSimple™ and IrDA communications functions • Main/sub LCD controller • Graphic processing		1.65 to 1.95		P-VFBGA144-0808
LR38869A				• MDDI*1-compliant • Main/sub LCD controller • Graphic processing • Parallel bus host interface				
LR388692				• MDDI*1-compliant • Main/sub LCD controller • Graphic processing	MDDI*1 for MSM series			

*1 MDDI (Mobile Display Digital Interface): The serial interface standard developed by QUALCOMM

IrSimple™ is a trademark of Infrared Data Association.

QUALCOMM and MSM are trademarks of QUALCOMM Incorporated.



■ Power Supply ICs for TFT-LCDs

Model No.	No. of output circuits	Input voltage range (V)	Output voltage (V)	System	Switching frequency (Hz)	Switching transistor	Switching current (mA) [Built-in SW Tr]	Drive capacity (pF) [External SW Tr]	Package
IR3M58M/U	3	4.5 to 28	External setting	Step-up (MAX. 20 V)/ step-down type PWM	70 k to 500 k	Built-in (for step-up type PWM)	400	1 000	P-QFP048-0707/ P-VQFN032-0505
				Step-down type PWM		External	–		
				Step-down, inverting type PWM		External	–		



System LSIs

Model No.	Function	Features	Supply voltage (V)	Package
LR35501	One-chip graphic controller	- Built-in video encoder (NTSC/PAL) - Composite signal output - Analog RGB signal output - Capable of moving picture transmission/play, thanks to real-time image compression and extension technology - Real images, backgrounds and sprites can be superimposed - Built-in sprite graphic processor - Built-in color object detector - Built-in Bluetooth® HCI controller - Built-in sound generator (ADPCM/PSG) - Built-in CMOS camera interface (9 MHz) - CPU: Z80 compatible, 27 MHz - Peripherals (NAND flash I/F, PIO, SIO, UART, ADC, PWM, etc.)	Core: 1.8 ± 0.18 I/O: 3.3 ± 0.3	P-QFP128-1420
LR35503	One-chip graphic controller	- Digital LCD interface (6-bit RGB) 27 MHz digital YUV video input - Capable of moving picture transmission/play, thanks to real-time image compression and extension technology - Real images, backgrounds and sprites can be superimposed - Built-in sprite graphic processor - Built-in color object detector (Only for CMOS camera input) - Built-in Bluetooth® HCI controller - Built-in sound generator (ADPCM/PSG) - Built-in CMOS camera interface (9 MHz) - CPU: Z80 compatible, 27 MHz - Peripherals (NAND flash I/F, PIO, SIO, UART, ADC, PWM, etc.)	Core: 1.8 ± 0.18 I/O: 3.3 ± 0.3	P-LQFP144-2020
LR35504	One-chip graphic controller	- Digital LCD interface (Capable of being set from 320 x 240 to 1 366 x 768 by increments of 8 dots) 24-bit color - ITU-R BT656 digital video input - Built-in CMOS camera interface (3 Mpixels, 54 MHz) - Built-in JPEG-CODEC - Real images, backgrounds and sprites can be superimposed - Built-in sprite graphic processor (Built-in enlargement, size reduction, rotation, transformation, and α blending effect functions) - Built-in color object detector - Built-in sound generator 16 ch PCM/ADPCM decoder - CPU: ARM926EJ-S, 108/54 MHz - Peripherals (SDRAM, NAND flash, SD card, SDIO, GPIO, EBI, SIO, UART, I²C, I²S, PWM, etc.)	Core: 1.2 I/O: 3.3	P-LFBGA280-1616

Bluetooth is a trademark of Bluetooth SIG, Inc.
Z80 is a trademark of ZILOG, Inc.
ARM926EJ-S is a trademark of ARM Ltd.

Smart Modules

Model No.	Function	Features	Supply voltage (V)	Outline dimensions (W × D) (mm)
LR0G934	3.5-inch smart module with built-in one-chip graphic controller	- LED backlight, QVGA, built-in 3.5-inch color TFT LCD - Built-in one-chip graphic controller (LR35503) - Built-in 64 Mbit NOR flash - Video input (composite NTSC) - Built-in real-time clock - External interface - Video input, digital input/output (shared 2 ch UART), analog input (4 ch ADC), sound output, battery backup terminal	5±0.5 (500 mA or higher)	87.4 × 69.2
LR0G938	3.5-inch smart module with touch panel and built-in one-chip graphic controller	- LED backlight, QVGA, built-in 3.5-inch color TFT LCD - Touch panel function - Built-in one-chip graphic controller (LR35503) - Built-in 64 Mbit NOR flash - Video input (composite NTSC) - Built-in real-time clock - External interface - Video input, digital input/output (shared 2 ch UART), analog input (4 ch ADC), sound output, battery backup terminal	5±0.5 (500 mA or higher)	87.4 × 69.2

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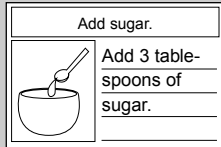


■ One-chip Graphic Controller <LR35501/LR35503>

LR35501/LR35503 are the system LSIs which enable smooth graphic display by graphic controller with built-in microcomputers and device control and graphic display with one chip due to the microcomputers and various I/Os.

Common features

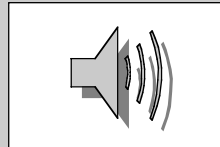
Built-in versatile graphic functions



- Smooth imaging using sprite processor
- Capable of moving picture transmission/play, thanks to real-time image compression technology
- Real images, backgrounds and sprites can be superimposed

Graphic expression with smooth movement is possible

Sound output



- Built-in stereo sound circuit
- ADPCM decoder
- Programmable sound generator

Warning using realistic alarm tone / audio is possible

CMOS camera interface



- CIF/QVGA UYVY input

CIF/QVGA CMOS imager can be connected

Bluetooth®



- Built-in HCI controller
- SPP, HID compliant

Smooth images transmission achieved by using Bluetooth®

General purpose I/O built-in PIO/UART/SIO/NAND flash interface/ADC/PWM/SPI, etc.

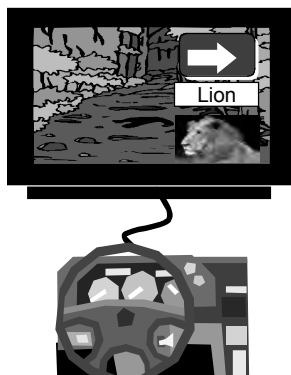
LR35501 features and functions

- Built-in video encoder (NTSC/PAL)
- Built-in analog RGB output
- Built-in composite video output

LR35503 features and functions

- Built-in digital LCD interface (6-bit RGB QVGA [320 x 240])
- Built-in 27 MHz YUV digital video input

Intellectual training toy (Driving game)



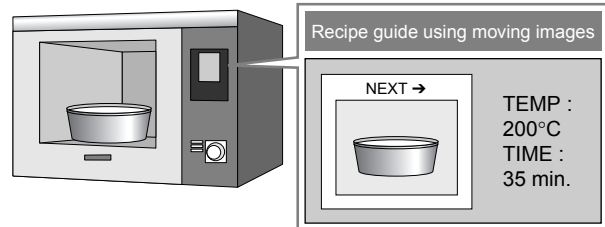
TV

LR35501

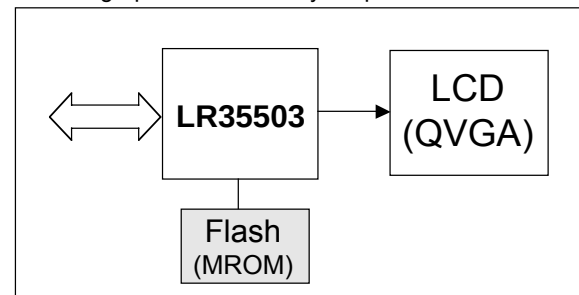
Flash
(MROM)

Directly connected to TV (composite) output

Household electrical appliance



Smooth graphics achieved by simple circuits





■ IrSimple™ Communications Series <LR388D8/LR388D1>

IrSimple™ communications is a communications protocol which makes the Ir communication standard employed in mobile terminals such as mobile phones, IrDA protocol, more efficient. Compared with IrDA, since the data transfer time can be significantly reduced to approximately 1/4th to 1/10th, higher volumes of data can be sent and received. In addition, by incorporating a controller for IrSimple™ communications into mobile equipment or digital home appliances, high-quality image data taken with a digital camera or a mobile phone camera can be readily transferred to a TV or a printer at high speed with a simple operation such as with a remote controller. The image data captured from the camera can be enjoyed on full HD-TV, or by printing the data out.

● Features

● LR388D8 (MDDI*1-compliant WVGA LCD controller for IrSimple™)

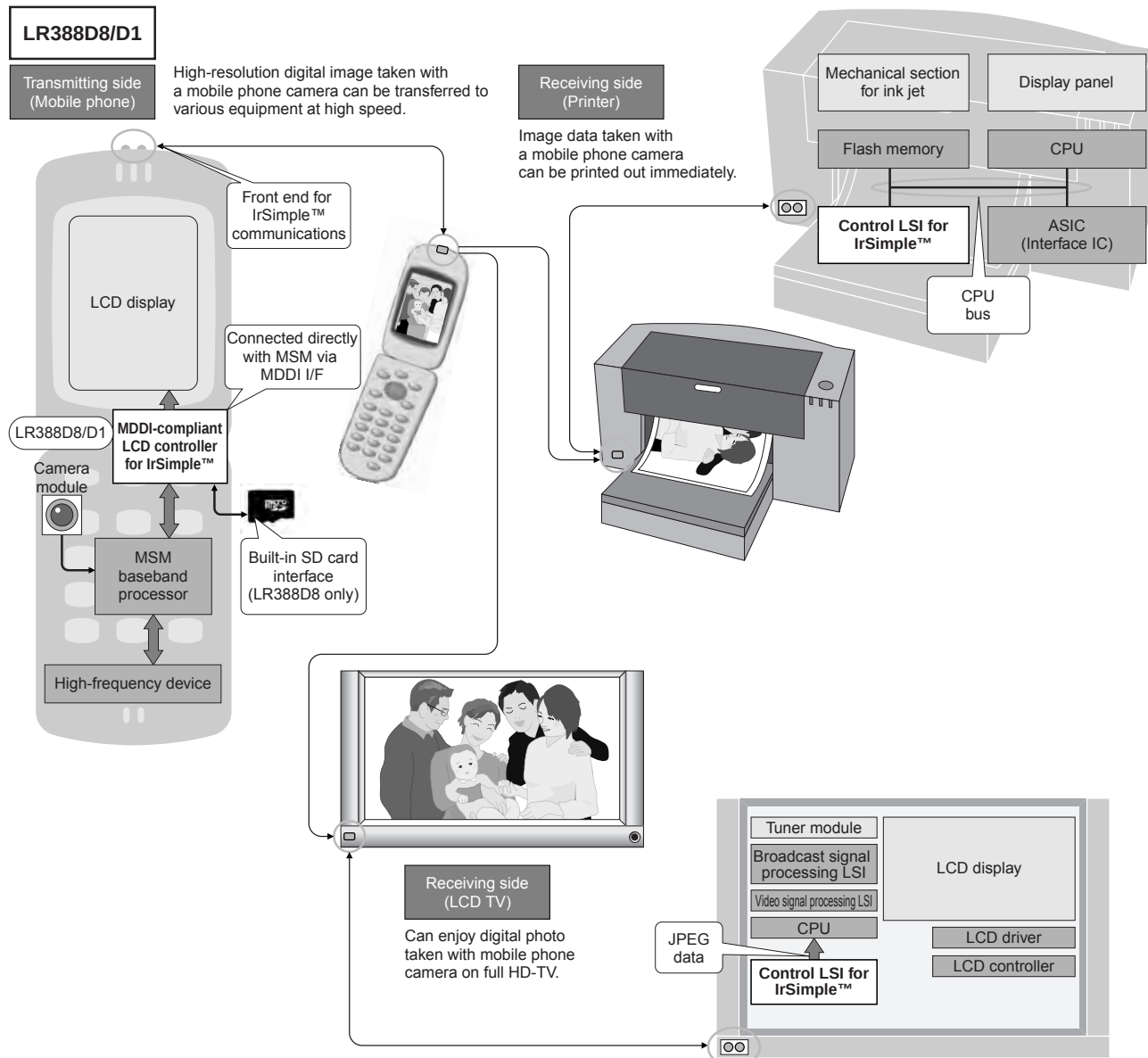
The LR388D1 has been made compatible with full-WVGA LCD displays, with internal memory (16 Mbits) that can hold two screens of data (main and sub). High-resolution display and low power consumption have been realized. Furthermore, a built-in SD card interface supports a reduction in the number of chips.

● LR388D1 (MDDI*1-compliant WQVGA LCD controller for IrSimple™)

Thanks to a built-in IrSimple™ function in the LCD controller, the mounting area of a mobile phone can be decreased; thus it contributes to size reduction in mobile phones. Also, a higher volume of data can be transferred at high speed with 4 fewer signal lines due to the incorporation of an MDDI*1 interface.

*1 MDDI (Mobile Display Digital Interface) : The serial interface standard developed by QUALCOMM

● Application & System Configuration Example



IrSimple™ is a trademark of Infrared Data Association.
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Smart Cards/LSI Modules for Smart Cards

Type		Communication standards	Protocol	Transmission speed (kbps) MAX.	Nonvolatile memory capacity	Cycling capability	CPU	Security system
SJCard 211	Contact	ISO/IEC7816	T = 1	19.2	1 Mbyte (Flash memory)	100 000 times	16 bits	RSA, DES, T-DES, etc. high-speed cryptographic authentication with built-in coprocessor, hardware-based random number generator
	Contactless	ISO/IEC14443 Type B	ISO/IEC14443-4	424				
SJCard 222	Contact	ISO/IEC7816	T = 1	38.4	1 Mbyte (Flash memory)	100 000 times	16 bits	
	Contactless	ISO/IEC14443 Type B	ISO/IEC14443-4	424				



SJCard 211

- Java Card™ 2.1.1 compliance
- Capable of developing applications using Java language



SJCard 222

- Java Card™ 2.2.2 compliance
- Capable of developing applications using Java language

SDK (Software Development Kit) for Smart Cards

SDK type	Contents	Remarks
For SJCard 211	Development kit CD for SJCard SJCard simulator	The sample card is not included in the kit.
For SJCard 222	Development kit CD for SJCard SJCard simulator	The sample card is not included in the kit.

Java and Java Card are trademarks of Sun Microsystems, Inc.

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Highly Functional Flash Memories

● Boot Block Type 3 V Page Mode Flash Memories: LH28FXXXBF Series

Capacity (bit)	Bit configuration	Erasable block size		Operating temp. (°C)	Model No.	Remarks
64 M	x 16	4 Kwords x 8, 32 Kwords x 127	Top boot	–40 to 85	LH28F640BFH-PTTL	• Built-in dual work function • Built-in OTP function [4 words (factory area) + 4 words (user area)]
			Bottom boot	–40 to 85	LH28F640BFH-PBTL	
128 M	x 16	4 Kwords x 8, 32 Kwords x 255	Top boot	–40 to 85	LH28F128BFH-PTTL	
			Bottom boot	–40 to 85	LH28F128BFH-PBTL	

System-Flash for Automotive Use

Capacity (bit)	Bit configuration	Erasable block size		Operating temp. (°C)	Model No.	Remarks
32 M	x 16	4 Kwords x 8, 32 Kwords x 63	Top boot	–40 to 85	LH28F320BFH-PTTL	• Employs copper frame
64 M	x 16	4 Kwords x 8, 32 Kwords x 127	Top boot	–40 to 85	LH28F640BFH-PTTL	
			Bottom boot		LH28F640BFH-PBTL	
128 M	x 16	4 Kwords x 8, 32 Kwords x 255	Top boot	–40 to 85	LH28F128BFH-PTTL	
	x 16	(4 Kwords x 8, 32 Kwords x 127) x 2	Top/Bottom boot		LH28F128BFH-PWTL	
256 M	x 16	(4 Kwords x 8, 32 Kwords x 255) x 2	Top/Top boot	–40 to 85	LH28F256BFH-PTTL	

System-Flash for Network Equipment

Capacity (bit)	Bit configuration	Erasable block size		Operating temp. (°C)	Model No.	Remarks
64 M	x 8/ x 16	64 Kwords x 64 or 128 Kbytes x 64	Symmetrical block	–40 to 85	LH28F640SPH-PL	• 56 TSOP industry standard package
128 M	x 8/ x 16	64 Kwords x 128 or 128 Kbytes x 128	Symmetrical block	–40 to 85	LH28F128SPH-PTL	• 56 TSOP industry standard package

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Highly Functional Flash Memories

Boot Block Type 3 V Page Mode Flash Memories: LH28FXXXBF Series

Supply voltage		64 M: V _{CC} = 2.7 to 3.6 V 128 M: V _{CC} = 2.7 to 3.6 V								
Capacity (bit)	Bit configuration	Erasable block size		Model No.	Access time (ns) MAX.	Page mode access time (ns) MAX.	Read current (mA) MAX. f = 5 MHz (CMOS)	Standby current (μA) MAX. (CMOS)	Operating temp. (°C)	Package
64 M	x 16	Parameter: 4 Kwords x 8	Top boot	LH28F640BFHE-PTTLHFA	70	30	25	20	-40 to 85	P-TSOP048-1220 (Normal bend)
		Main: 32 Kwords x 127	Bottom boot	LH28F640BFHE-PBTLHGA	70	30	25	20		
128 M	x 16	Parameter: 4 Kwords x 8	Top boot	LH28F128BFHT-PTTL75A	75	25	35	40		P-TSOP056-1420 (Normal bend)
		Main: 32 Kwords x 255	Bottom boot	LH28F128BFHT-PBTL75A	75	25	35	40		

Contact a SHARP sales office for other packages and top boot/bottom boot models other than those listed above.

System-Flash for Automotive Use

Supply voltage		V _{CC} = 2.7 to 3.6 V, V _{CCQ} = 2.7 to 3.6 V								
Capacity (bit)	Bit configuration	Erasable block size		Model No.	Access time (ns) MAX.	Page mode access time (ns) MAX.	Read current (mA) MAX. f = 5 MHz (CMOS)	Standby current (μA) MAX. (CMOS)	Operating temp. (°C)	Package
32 M	x 16	Parameter: 4 Kwords x 8 Main: 32 Kwords x 63	Top boot	LH28F320BFHE-PTTLE0	70	25	25	20	−40 to 85	P-TSOP048-1220 (Normal bend)
64 M	x 16	Parameter: 4 Kwords x 8 Main: 32 Kwords x 127	Top boot	LH28F640BFHE-PTTLH1A	70	30	25	20	−40 to 85	P-TSOP048-1220 (Normal bend)
		Parameter: 4 Kwords x 8 Main: 32 Kwords x 127	Bottom boot	LH28F640BFHE-PBTLHK	70	30	25	20	−40 to 85	
128 M	x 16	Parameter: 4 Kwords x 8 Main: 32 Kwords x 255	Top boot	LH28F128BFHT-PTTLT1A	75	25	35	40	−40 to 85	P-TSOP056-1420 (Normal bend)
		Parameter: 4 Kwords x 8 Main: 32 Kwords x 127	x2 Top/ Bottom boot	LH28F128BFHED-PWTLT2	70	30	25	40	−40 to 85	P-TSOP048-1220 (Normal bend)
256 M	x 16	Parameter: 4 Kwords x 8 Main: 32 Kwords x 255	x2 Top/ Top boot	LH28F256BFHTD-PTTLZ3	75	25	40	80	−40 to 85	P-TSOP056-1420 (Normal bend)

System-Flash for Network Equipment

Supply voltage		V _{CC} = 2.7 to 3.6 V								
Capacity (bit)	Bit configuration	Erasable block size		Model No.	Access time (ns) MAX.	Page mode access time (ns) MAX.	Read current (mA) MAX. f = 5 MHz (CMOS)	Standby current (μA) MAX. (CMOS)	Operating temp. (°C)	Package
64 M	x 8/ x 16	64 Kwords x 64 or 128 Kbytes x 64	Symmetrical block	LH28F640SPHT-PL12B	120	25	35	120	−40 to 85	P-TSOP056-1420 (Normal bend)
128 M	x 8/ x 16	64 Kwords x 128 or 128 Kbytes x 128	Symmetrical block	LH28F128SPHT-PTL12B	120	25	35	120	−40 to 85	P-TSOP056-1420 (Normal bend)

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Low Power-Loss Voltage Regulators

TO-220 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings				Electrical characteristics			Built-in functions						Lead forming available	Package				
		Output current I _O (A)	Input voltage V _{IN} (V)	Power dissipation (W)		Output voltage V _O *3 (V) TYP.	Output voltage precision (%)	Dropout voltage V _{I-O} *5 (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	Variable output voltage							
				Pd*1	Pd*2															
PQxxRD08J00H series	ASO protection function	0.8	20	1.25	10	5, 9, 12	±3	0.5	○	○	○				A					
PQ3RD083J00H						3.3			○	○	○			A						
PQ6RD083J00H						6.3			○	○	○									
PQxxRA11J00H series	Low dissipation current at OFF state (I _{qs} : 1 μA (MAX.))	1	35	1.5	15	5, 9, 12	±2.5	0.5	○	○	○	○				B				
PQ3RD13J000H	ASO protection function		20	1.4		3.3	±3		○	○	○			A						
PQxxRD11J00H series	ASO protection function					5, 9, 12	±3		○	○	○		○		A					
PQxxxRDA1SZH series	ASO protection function, low dissipation current at OFF state (I _{qs} : 5 μA (MAX.))	24	3.3, 5, 8, 9, 12		±3	○	○	○	○			A								
PQxxxRDA2SZH series		2	20	1.4	15	3.3, 5, 9, 12	±2.5	1.0	○	○	○		○				A			
PQxxxEF01SZH series	Minimum operating input voltage: 2.35 V (4 terminals)	1	10	1.4	15	1.5, 1.8, 2.5, 3.3	±2.5	0.5	○	○	○		○			A				
PQxxxEF02SZH series		2				○			○	○	○			A						
PQxxRF11J00H series	General purpose	1	35	1.5	18	5, 9, 12	±2.5	0.5	○	○	○				○	B				
PQxxRH11J00H series		1.5				○			○	○			B							
PQ3RD23J000H	ASO protection function	2	20	1.4	15	3.3	±3	0.5	○	○	○					A				
PQxxRD21J00H series						5, 9, 12			○	○	○			A						
PQxxRF21J00H series	General purpose		35	1.5	18	3.3	±2.5		○	○	○				○	B				
PQ3RF23J000H	General purpose								○	○	○			B						
PQ3RF33J000H	High output current	3.5	1.8					○	○	○						B				
PQ070XF01SZH	Minimum operating input voltage: 2.35 V (4 terminals)	1	10	1.4	15	1.5 to 7	±2*4	0.5	○	○			○		A					
PQ070XF02SZH		2							○	○			○			A				
PQ070VK01FZH	Minimum operating input voltage: 2.35 V (5 terminals)	1												○	○		○	○	○	○
PQ070VK02FZH		2													○	○	○	○	○	
PQ15RW08J00H	ASO protection function, minimum operating input voltage: 3.5 V	0.8	20	1.25	10	3.0 to 15	±2.5*4	1.0	○	○			○		A					
PQ15RW11J00H		1		1.4	15				○	○			○			A				
PQ15RW21J00H		2		1.4	15				○	○			○							
PQ150RWA2SZH	ASO protection function	0.5	24	1.25	10	3.0 to 20	0.5	0.5	○	○	○	○	○	○	C					
PQ20RX05J00H	Variable output voltage, output ON/OFF control	1		1.5	15				○	○	○	○	○	○		C				
PQ20RX11J00H		17	1.25	12.5	1.5 to 15	±2*4	0.5		○	○	○	○	○	E						
PQ150VB01FZH	2		2		1.5 to 30				○	○	△*6		○		○	B				
PQ30RV11J00H		Variable output voltage	1	35	1.5			15	1.5 to 30	±2*4	0.5	○	○	△*6			○	○	B	
PQ30RV21J00H	2		18		○	○	△*6					○	○	B						
PQ30RV31J00H	3		20		○	○	△*6					○	○							
PQ7RV4J0000H		4.6	10	1.8	18	1.5 to 7			○	○	△*6		○		B					

*1 At self-cooling

*2 With infinite heat sink attached

*3 The xx/xxx in the model No. refer to the output voltage values of the model (e.g. 05/050 for 5 V, 12/120 for 12 V, 015 for 1.5 V).

*4 Reference voltage precision

*5 Current ratings are defined individually.

*6 △ : Available by adding circuit

*7 Refer to page 53

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■ Surface Mount Type Low Power-Loss Voltage Regulators

● SOT-23-5 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electrical characteristics				Built-in functions				Package
		Input voltage Vin (V)	Power dissipation Pd*1 (W)	Output current Io (A)	Output voltage Vo*2 (V) TYP.	Output voltage precision (%)	Dropout voltage Vi-o (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	
PQ1Uxx1M2ZPH series	Compact, low output current	16	0.35	0.18	1.8, 2.5, 2.8, 3.0, 3.3, 3.5, 5.0	±2.0 (3.0 V output)	0.26 (Io = 60 mA)	○	○	○	○	SOT-23-5
PQ1Xxx1M2ZPH series	Compact, ceramic capacitor compatible	9			*3			○	○	○	○	

*1 When mounted on a board

*2 The xx in the model No. refer to the output voltage values of the model (e.g. 50 for 5.0 V, 18 for 1.8 V).

*3 1.5, 1.8, 2.5, 2.6, 2.7, 2.8, 2.9, 3.0, 3.3, 3.5, 3.7, 4.0, 4.5, 5.0

● SOT-23L type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings			Electrical characteristics				Built-in functions				Package
		Output current Io (A)	Input voltage Vin (V)	Power dissipation Pd*1 (W)	Output current Io (A)	Output voltage Vo*2 (V) TYP.	Output voltage precision (%)	Dropout voltage Vi-o (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	
PQ1RxxJ0000H series	Compact, surface mount type, low dissipation current at OFF state (Iqs: 0.1 μA (MAX.))	—	16	0.4	0.18	*3	±2.7 (3.0 V output)	0.26 (Io = 60 mA)	○	○	○	○	SOT-23L
PQ1Kxx3M2ZPH series	Compact, surface mount type, high ripple rejection, output current of up to 300 mA	0.3	9		—	1.8, 2.5, 3.0, 3.3, 3.6, 5.0	±2.0 (3.0 V output)	0.7 (Io = 300 mA)	○	○	○	○	

*1 When mounted on a board

*2 The xx in the model No. refer to the output voltage values of the model (e.g. 25 for 2.5 V, 47 for 4.7 V, 50 for 5.0 V).

*3 1.8, 2.0, 2.3, 2.5, 2.7, 2.8, 2.9, 3.0, 3.2, 3.3, 3.4, 3.5, 3.7, 3.8, 4.0, 4.2, 4.4, 4.7, 4.9, 5.0, 5.2

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● SOT-89 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings			Electrical characteristics			Built-in functions					Package
		Output current I _o (A)	Input voltage V _{in} (V)	Power dissipation P _d *1 (W)	Output voltage V _o *2 (V) TYP.	Output voltage precision (%)	Dropout voltage V _{i-o} *3 (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	Variable output voltage	
PQ1Lxx3M2SPQ	Compact, high radiation package, low dissipation current at OFF state (I _{qs} : 1 μA (MAX.))	0.3	16	0.9	1.5, 1.8, 2.5, 3.0, 3.2, 3.3, 5.0	±2.0 (3.0 V output)	0.7	○	○	○	○		SOT-89
PQ1LAXx5MSPQ	Compact, high radiation package, ceramic capacitor compatible	0.5	15		1.2, 1.5, 1.8, 2.5, 3.3, 5.0	±2.0		○	○	○	○		
PQ1LAX95MSPQ	Ceramic capacitor compatible, variable output voltage				1.5 to 9.0	±2.0*6		○	○	○	○	○	
PQ1Mxx5M2SPQ	Compact, high output current, ceramic capacitor compatible		9		1.5, 1.8, 2.5, 3.3, 5.0	±2.0 (5.0 V output)	0.7	○	○	○	○		
PQ1MX55M2SPQ	Ceramic capacitor compatible, variable output voltage	1.3 to 5.0			±2.0*6	○		○	○	○	○		
PQ1Nxx3MxSPQ	Reset signal output function*4, ceramic capacitor compatible	0.35			2.5, 3.3	±2.0		○	○				
PQ2Lxxx2MSPQ	Compact, high radiation package, 2 outputs	0.25/ch	9		*5	—	0.4	○	○				

*¹ When mounted on a board*² The xx in the model No. refer to the output voltage values of the model (e.g. 25 for 2.5 V, 50 for 5.0 V). [Except PQ2Lxxx2MSPQ]*³ Current ratings are defined individually.*⁴ Reset detection voltage: 4.2 V, 3.8 V*⁵ Output voltage combination: 3.3/3.3 V, 3.3/2.5 V, 3.3/1.8 V, 3.3/1.5 V, 2.5/1.8 V, 2.5/1.5 V*⁶ Reference voltage precision**Notice**

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●SC-63 type (1) Output voltage fixed type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings				Electrical characteristics				Built-in functions						Package		
		Output current I _O (A)			Input voltage V _{IN} (V)	Power dissipation Pd*1 (W)	Output voltage Vo*2 (V) TYP.	Output voltage precision (%)	Dropout voltage V _{I-O} *5 (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	Variable output voltage	Taped package			
		0.5	1	1.5													Package shape type*6	
PQ07VR5MAZPH series	Reset signal generation function (input voltage drop detection)	○			10	8	1.5 to 7	±2.0*3	0.5	○	○			○	○	SC-63	F	
PQ3DZ53J000H	ASO protection function, low dissipation current at OFF state (I _{qs} : 5 μA (MAX.))	○			24		3.3	±3.0		○	○	○	○		○			F
PQ3DZ13J000H			○				○			○	○	○		○			F	
PQxxDZ51J00H series		○					○			○	○	○		○			F	
PQxxDZ11J00H series			○				○			○	○	○		○			F	
PQxxxDNA1ZPH series	Ceramic capacitor compatible, ASO protection function, low dissipation current at OFF state (I _{qs} : 5 μA (MAX.)), solder dip compatible lead shape			○		8	3.3, 5, 8, 9, 12	±2.5	0.3	○	○	○	○		○		G	
PQxxxDZ01ZPH series	Low dissipation current at OFF state (I _{qs} : 5 μA (MAX.))		○		9, 10		5	3.3, 5		±3.0	○	○	○	○			○	F
PQxxxEZ5MZPH series	Minimum operating input voltage: 2.35 V	○			10		8	1.5, 1.8, 2.5, 3.0, 3.3		±2.5*4	○	○	○	○			○	F
PQxxxEZ01ZPH series			○								○	○	○	○			○	F
PQxxxEN01ZPH series	Minimum operating input voltage: 2.35 V, solder dip compatible lead shape		○					1.5, 1.8, 2.5, 3.3		±2.0		○	○	○	○			○
PQxxxENA1ZPH series	Minimum operating input voltage: 2.35 V, ceramic capacitor compatible, solder dip compatible lead shape		○			○			○			○	○		○		G	
PQxxxENB1ZPH series			○			5		8	1.5, 1.8, 2.5, 3.3	±2.5*4	0.9	○	○	○	○			○
PQxxxENAHZPH series				○	○		○					○		○	F			
PQxxxEZ1HZPH series	Minimum operating input voltage: 2.35 V			○	8	8	1.5, 1.8, 2.5, 3.0, 3.3	±2.5*4	1.0	○	○	○	○		○		F	
PQxxxEZ02ZPH series				○ (2A)					1.5, 1.8, 2.5	0.5	○	○	○	○			○	F
PQxxxFZ5MZPH series	Minimum operating input voltage: 1.7 V (Dual power supply type)	○			3.7	8	1.0, 1.2	±30 mV	—	○	○	○	○		○	F		
PQxxxGN01ZPH series	Minimum operating input voltage: 1.7 V (Dual power supply type), ceramic capacitor compatible, solder dip compatible lead shape		○		5.5		0.8, 1.0, 1.2			○	○					○	G	
PQxxxGN1HZPH series				○							○	○					○	G

*1 With infinite heat sink attached

*2 The xx/xxx in the model No. refer to the output voltage values of the model (e.g. 033 for 3.3 V, 05/050 for 5 V, 12/120 for 12 V).

*3 Reference voltage precision

*4 The value is defined as ±50 mV in some models.

*5 Current ratings are defined individually.

*6 Refer to page 53

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●SC-63 type (2) Output voltage variable type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings				Electrical characteristics				Built-in functions							Package	
		Output current Io (A)			Input voltage Vin (V)	Power dissi- pation Pd*1 (W)	Output voltage Vo (V) TYP.	Output voltage preci- sion (%)	Dropout voltage VI-o*3 (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	Variable output voltage	Taped package	Package shape type*4		
		0.5	1	1.5														
PQ070XZ5MZPH	Minimum operating input voltage: 2.35 V	○			10	8	1.5 to 7	±2.0*2	0.5	○	○	○	○	○	○	SC-63	F	
PQ070XZ01ZPH			○							○	○	○	○	○	F			
PQ070XN01ZPH	Minimum operating input voltage: 2.35 V, solder dip compatible lead shape		○							○	○	○	○	○	G			
PQ070XNA1ZPH			○							○	○	○	○	G				
PQ070XNAHZPH	Minimum operating input voltage: 2.35 V, ceramic capacitor compatible, solder dip compatible lead shape			○		5	1.2 to 7		0.9	○	○	○	○	○	○		G	
PQ070XNA2ZPH				○ (2 A)						0.5	○	○	○	○	○		G	
PQ070XNB1ZPH			○			0.3	○				○	○	○	○	G			
PQ070XZ1HZPH		Minimum operating input voltage: 2.35 V					○			1.5 to 7	1.0	○	○	○	○		○	○
PQ070XZ02ZPH				○ (2 A)	0.5	○	○	○	○			○	F					
PQ015YZ5MZPH	Reference voltage (Vref): 1.0 V, minimum operating input voltage: 1.7 V (Dual power supply type)	○				5.5	1.0 to 1.5	±3.0*2	-	○	○				○		○	F
PQ035ZN01ZPH	Reference voltage (Vref): 0.6 V, minimum operating input voltage: 1.7 V (Dual power supply type), ceramic capacitor compatible, solder dip compatible lead shape		○		0.8 to 3.5		±30 mV	○		○				○	○	G		
PQ035ZN1HZPH					○			○		○				○	○	G		
PQ20VZ51J00H	Minimum operating input voltage: 4.5 V	○			24	8	1.5 to 20	±2.0*2	0.5	○	○	○	○	○	○	G	F	
PQ20VZ11J00H			○							○	○	○	○	○	○		F	
PQ20WZ51J00H	Minimum operating input voltage: 3.5 V, ASO protection function, low dissipation current at OFF state (Iqs: 5 μA (MAX.))	○								○	○	○	○	○	○		F	
PQ20WZ11J00H				○							○	○	○	○	○		F	
PQ200WNA1ZPH	Minimum operating input voltage: 3.5 V, ASO protection function, low dissipation current at OFF state (Iqs: 5 μA (MAX.)), ceramic capacitor compatible, solder dip compatible lead shape			○		3.0 to 20	±2.5*2		○	○	○	○	○	○	○		G	
PQ200WN3MZPH	Minimum operating input voltage: 5.5 V, low dissipation current at OFF state (Iqs: 5 μA (MAX.)), ceramic capacitor compatible, current limit: 800 mA	○ (0.3)							6.8	5.0 to 20	○	○	○	○	○			○

*1 With infinite heat sink attached

*2 Reference voltage precision

*3 Current ratings are defined individually.

*4 Refer to page 53

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●TO-263 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings			Electrical characteristics			Built-in functions						Taped package	Package
		Output current I _O (A)	Input voltage V _{IN} (V)	Power dissipation P _D *1 (W)	Output voltage V _O *2 (V) TYP.	Output voltage precision (%)	Dropout voltage V _{I-O} *4 (V)	Overheat protection	Overcurrent protection	ON/OFF control	Low dissipation current at OFF state	Variable output voltage			
PQxxxY053ZPH	High output current (minimum operating input voltage: 2.35 V)	5.0	7	35	1.5, 2.5, 3.3	±1.0	0.5	○	○	○			○	TO-263	
PQ05VY053ZPH					1.5 to 5	±1.0*3		○	○	○		○	○		
PQxxxY3H3ZPH		3.5			1.5, 2.5, 3.3	±1.0		○	○	○			○		
PQ05VY3H3ZPH					1.5 to 5	±1.0*3		○	○	○		○	○		
PQxxxEH02ZPH	2 A output (minimum operating input voltage: 2.35 V)	2.0	10		1.5, 1.8, 2.5	±2.5*5			○	○	○	○			○
PQ070XH02ZPH					1.5 to 7	±2.0*3			○	○	○	○	○		
PQ070XHA2ZPH	2 A output (minimum operating input voltage: 2.35 V), ceramic capacitor compatible				1.5 to 7	±2.0*3			○	○	○	○	○		
PQxxxEH01ZPH	1 A output (minimum operating input voltage: 2.35 V)	1.0			1.5, 1.8, 2.5	±2.5*5			○	○	○	○			○
PQ070XH01ZPH					1.5 to 7	±2.0*3			○	○	○	○	○		○

*1 With infinite heat sink attached

*2 The xxx in the model No. refer to the output voltage values of the model (e.g. 015 for 1.5 V, 025 for 2.5 V, 033 for 3.3 V).

*3 Reference voltage precision

*4 Current ratings are defined individually.

*5 The value is defined as ±50 mV in some models.

●SOP-8 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings			Electrical characteristics		Built-in functions		Taped package	Package
		Output current I _O (A)	Input voltage V _{IN} (V)	Power dissipation P _D * ¹ (W)	Output voltage V _O (V) TYP.	Output voltage precision* ² (mV)	Overheat protection	Overcurrent protection		
PQ1DX095MZIPQ	Built-in sink source function (For DDR II memory)	±0.8	6	0.6	V _{DD} x 1/2 (V _{DDQ} : 1.5 V (MIN.))	±25	○	○	○	SOP-8
PQ1DX125MZIPQ	Built-in sink source function (For DDR memory)				V _{DD} x 1/2 (V _{DDQ} : 2.3 V (MIN.))	±35	○	○	○	

*1 When mounted on a board

*2 Reference voltage precision

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■ Surface Mount Type Chopper Regulators (DC-DC Converters) (1)

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electrical characteristics					Package	
		Switching current Isw (A)	Power dissipation Pd*1 (W)	Input voltage range Vin (V)	Output voltage*2 Vo (V)	Output type	Oscillation frequency fo (Hz) TYP.	Output saturation voltage Vsat (V) TYP.	Outline shape type*6	
PQ6CU12X2APQ	- High switching voltage: 40 V (MAX.) - For tuner power supply - Variable oscillation frequency - Ceramic capacitor compatible	0.25	0.35	3.0 to 5.5	up to 36	Step-up	300 k to 800 k	Ron TYP. 1.7Ω		SOT-23-6W
PQ1CN38M2ZPH	- PWM chopper regulator (high oscillation frequency) - Output ON/OFF control function - Overcurrent/overheat protection circuits - For light load	0.8	8	4.5 to 40	*3 VREF to 35 (step-down type)/ -VREF to -30 (inverting type)	Step-down	300 k	0.9	SC-63	G
PQ1CN41H2ZPH	- PWM chopper regulator (high oscillation frequency) - Overcurrent/overheat protection circuits	1.5	8			Step-down	300 k	0.9		G
PQ1CZ21H2ZPH	- PWM chopper regulator - Output ON/OFF control function - Overcurrent/overheat protection circuits - Low dissipation current at OFF state (Standby current <Isd>: 1 μA (MAX.))		8			Step-down	100 k	0.9		F
PQ1CX12H2ZPQ	- Bootstrap system for high efficiency (Efficiency 88% (TYP.)) - Low dissipation current	2.5	0.9 When mounted on board	4.5 to 30	*3 VREF to 24	Step-down	150 k	0.25	SOP-8	
PQ1CX22H2ZPQ	- Bootstrap system for high efficiency (Efficiency 88% (TYP.)) - Low dissipation current - Low voltage output: 1.2 V (MIN.)				*4 VREF to 24 (step-down type)			0.25		
PQ1CX41H2ZPQ	- Bootstrap system for high efficiency (Efficiency 90% (TYP.)) - Low voltage output: 0.8 V (MIN.) - Ceramic capacitor compatible	1.5	0.8 When mounted on board	4.75 to 27	0.8 to 20	Step-down	400 k	RDSon TYP. 0.45Ω	USB-8	
☆PQ1CX53H2MPQ	- Bootstrap system for high efficiency (Efficiency 89% (TYP.)) - Low voltage output: 0.8 V (MIN.) - Ceramic capacitor compatible	3.5	2 When mounted on board	4.75 to 27	0.8 to 16	Step-down	400 k	RDSon TYP. 0.15Ω		
☆PQ1CX61H1ZPQ	- Bootstrap system for high efficiency (Efficiency 88% (TYP.)) - Low voltage output: 1.0 V (MIN.) - Ceramic capacitor compatible	1.5	0.8 When mounted on board	4.75 to 28	1.0 to 18.9	Step-down	900 k	RDSon TYP. 0.55Ω		
PQ1CY1032ZPH	- PWM chopper regulator - Output ON/OFF control function - Overheat protection/overcurrent shutdown circuits - High output current type	3.5	35	4.5 to 40	*3 VREF to 35 (step-down type)/ -VREF to -30 (inverting type)	Step-down	150 k	1.4	TO-263	
PQ1CYxx3HZPH series PQ1CYxx3LZPH series*5	- PWM chopper regulator - Fixed output voltage: 3.3 V or 5 V - Overheat protection circuit - Output ON/OFF control function		35					1.4		

*1 With infinite heat sink attached or when mounted on a board listed in the specification sheets.

*2 Output variable range (step-down/inversion).

*3 VREF nearly equal to 1.26 V

*4 VREF nearly equal to 1 V

*5 PQ1CYxx3HZPH series is "H" active, and PQ1CYxx3LZPH series is "L" active.

*6 Refer to page 53

■ Surface Mount Type Chopper Regulators (DC-DC Converters) (2)

Model No.	No. of output circuits	Input voltage range (V)	Output voltage (V)	System	Switching frequency (Hz)	Switching transistor	Switching current (mA) [Built-in SW Tr]	Drive capacity (pF) [External SW Tr]	Package
IR3M58M/U	3	4.5 to 28	External setting	Step-up (MAX. 20 V)/ step-down type PWM	70 k to 500 k	Built-in	400	1 000	P-QFP048-0707/ P-VQFN032-0505
				Step-down type PWM		External	—		
				Step-down, inverting type PWM		External	—		

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■ Chopper Regulators (DC-DC Converters)

● TO-220 type

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electrical characteristics						Package				
		Switching current Isw (A)	Power dissipation Pd*1 (W)	Input voltage range Vin (V)	Output voltage Vo*2 (V)	Output type	Oscillation frequency fo (kHz) TYP.	Output saturation voltage Vsat (V) TYP.		Outline shape type*5				
PQ1CG38M2FZH	• PWM chopper regulator (high oscillation frequency)	0.8*3	14	40	VREF*4 to 35 (step-down type)/ -VREF*4 to -30 (inverting type)	Step-down	300	0.95	TO-220	E				
PQ1CG38M2RZH	• Built-in overcurrent/overheat protection circuits									D				
PQ1CG21H2FZH	• For light load									E				
PQ1CG21H2RZH	• Output ON/OFF control function	D												
PQ1CG41H2FZH	• PWM chopper regulator (high oscillation frequency)	1.5*3					E							
PQ1CG41H2RZH	• Built-in overcurrent/overheat protection circuits						D							
	• Output ON/OFF control function													
PQ1CG2032FZH	• PWM chopper regulator	3.5*3					E							
PQ1CG2032RZH	• Built-in overcurrent/overheat protection circuits						D							
	• Output ON/OFF control function													
PQ1CG3032FZH	• PWM chopper regulator (high oscillation frequency)													
PQ1CG3032RZH	• Built-in overcurrent/overheat protection circuits													
	• Output ON/OFF control function													
PQ2CF1J0000H	• PWM chopper regulator	2.5*3					15	35		4.5 to 35 (step-up type)	Step-up	50	0.6	E
	• Built-in overcurrent/overheat protection circuits													

*1 With infinite heat sink attached

*2 Output voltage variable range

*3 Peak current

*4 V_{REF} nearly equal to 1.26 V (TYP.)

*5 Refer to page 53

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■ Power Supply ICs for CCDs/CCD Camera Modules

Model No.	No. of output circuits	Input voltage range (V)	Output voltage (V)	System	Switching frequency (Hz)	Switching transistor	Switching current (mA) [Built-in SW Tr]	Drive capacity (pF) [External SW Tr]	Package
IR3M63U	4	4.5 to 10	15	Charge pump	200 k	–	12 (DC)	–	P-VQFN032-0505
			–8	Negative charge pump			2.5 (DC)	–	
			3.3	Step-down type PWM + REG	1 M	Built-in	120 (DC)	–	
			1.8	Step-down type PWM + REG			50 (DC)	–	
IR3M59U	3	4.5 to 16	15/12	Charge pump	200 k	–	12/20 (DC)	–	P-VQFN032-0505
			–8/–5	Negative charge pump			2.5/5 (DC)	–	
			3.3	Step-down type PWM + REG	1 M	Built-in	150 (DC)	–	

■ Power Supply ICs for TFT-LCDs

Model No.	No. of output circuits	Input voltage range (V)	Output voltage (V)	System	Switching frequency (Hz)	Switching transistor	Switching current (mA) [Built-in SW Tr]	Drive capacity (pF) [External SW Tr]	Package
IR3M58M/U	3	4.5 to 28	External setting	Step-up (MAX. 20 V)/ step-down type PWM	70 k to 500 k	Built-in	400 (for step-up type PWM)	1 000	P-QFP048-0707/ P-VQFN032-0505
				Step-down type PWM		External	–		
				Step-down, inverting type PWM		External	–		

■ LED Drivers

● Built-in step-up circuit (1)

Model No.	Function	Features	No. of output circuits	Number of LEDs	Booster method	Constant current circuit	Switching transistor	Input voltage range (V)	Output ^{*3} current (mA) MAX.	Oscillation frequency (Hz) TYP.	Package
PQ6CB11X1CP	White LED driver for backlight (for small panels)	- High voltage CMOS output: 30 V (MAX.) - Output ON/OFF control function - Overvoltage/overcurrent protection circuits - Soft start function	1	6 (Series connection)	PWM	*1	○	2.7 to 5.5	250 ^{*2}	1.2 M	USB-6
PQ7L2020BP		- High voltage CMOS output: 37 V (MAX.) - Output ON/OFF control function - Overvoltage/overcurrent protection circuits - Soft start function - Possible to use a low-capacity (0.1 μF) output capacitor	1	9 (Series connection)		*1	○	2.9 to 5.5	500	1.0 M	USB-6
☆PQ7L3010QPF	White LED driver for flashlight	- Automatic-switching (between 1x/2x) charge pump system - Non-external coil - Built-in fail-safe function - Short-circuit LED protection function/overheat protection function/soft start function	1	1	Charge pump	*1	–	2.6 to 4.4	800	0.9 M	16QFN

*1 LED constant current value can be set by external resistors.

*2 Peak switching current

*3 Constant current (MAX.)

*4 Use this IC within the range of power dissipation.

*5 Selectable oscillation frequency range

*6 3.57 mm x 3.57 mm x 0.82 mm (TYP.)

*7 3.57 mm x 3.57 mm x 0.65 mm (TYP.)

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■ LED Drivers

● Built-in step-up circuit (2)

Model No.	Function	Features	No. of output circuits	Number of LEDs	Booster method	Constant current circuit	Switching transistor	Input voltage range (V)	Output ^{*3} current (mA) MAX.	Oscillation frequency (Hz) TYP.	Package
IR2E49U/ IR2E49M	White LED driver for backlight	- Capable of driving a maximum of 40 LEDs with 8 LEDs (in series) per channel - Built-in step-up DC-DC controller - Capable of controlling brightness using PWM control - Step-up output control according to LED-Vf	5	40	PWM	○	External	6 to 28	150/ch ^{*4}	100 k to 1 M ^{*5}	P-VQFN036-0606/ P-QFP048-0707
IR2E51Y6	LED driver for backlight and call alert display (auto brightness adjustment)	- Capable of direct connection of ambient light sensor - Brightness adjustment by ambient illuminance feedback (16-step ambient illuminance/128-level illuminance) (for main LCDs) - Non-external coil thanks to charge pump drive - Capable of driving 4 main-LEDs, 2 sub-LEDs, and 3 call alert LEDs with a single device. - I²C interface-compatible - Standby function/power on reset function/soft start function	9	4 + 2 + 3	Charge pump	○	—	3.0 to 4.5 (for drive)/2.3 to 3.2 (for control)	27.4/ch	660 k	35WL-CSP ^{*6}
IR2E55Yx	LED driver for backlight and call alert display (auto brightness adjustment)	- Capable of driving 7 main-LEDs (series) and 6 call alert LEDs - Auto brightness adjustment and PWM brightness adjustment - Power supply for EL panel and LCD controller - LDO 2ch - Built-in GPIO interface - I²C/SPI interface-compatible	7	13	PWM + charge pump	○	○	3 to 4.2 (for drive)/2.7 to 3.2 (for control)	Main 25.6/ch Call alert 12.8/ch	1 M	48WL-CSP ^{*7}
☆IR2E56U6	White LED driver for backlight	- Capable of driving a maximum of 72 LEDs with 12 LEDs (in series) per channel - Built-in step-up DC-DC controller - High oscillation frequency (1.5 MHz) makes use of a small coil possible - Capable of controlling brightness using PWM control - Step-up output control according to LED-Vf - Built-in sequential drive mode for output current	6	72	PWM	○	External	5 to 28	25/ch	200 k to 1.5 M	32VQFN
★IR2E58U		- Capable of driving a maximum of 96 LEDs with 12 LEDs (in series) per channel - Built-in step-up DC-DC converter - High oscillation frequency (1.5 MHz) makes use of a small coil possible - Capable of controlling brightness using PWM control - Step-up output control according to LED-Vf	8	96		○	○	4.5 to 28	40/ch	500 k to 1.5 M	24HQFN
★IR2E62U		- Capable of driving a maximum of 96 LEDs with 12 LEDs (in series) per channel - Built-in step-up DC-DC converter - High oscillation frequency (1.5 MHz) makes use of a small coil possible - Capable of controlling brightness using PWM control - Step-up output control according to LED-Vf - Built-in sequential drive mode for output current - Brightness control and operation mode settings carried out using an I²C-bus, making use of an internal monitor possible	8	96		○	○	4.5 to 28	35/ch	500 k to 1.5 M	24HQFN

*1 LED constant current value can be set by external resistors.

*2 Peak switching current

*3 Constant current (MAX.)

*4 Use this IC within the range of power dissipation.

*5 Selectable oscillation frequency range

*6 3.57 mm x 3.57 mm x 0.82 mm (TYP.)

*7 3.57 mm x 3.57 mm x 0.65 mm (TYP.)

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☆New product
★Under development



●Built-in step-up circuit (3)

Model No.	Function	Features	No. of output circuits	Number of LEDs	Booster method	Constant current circuit	Switching transistor	Input voltage range (V)	Output* ³ current (mA) MAX.	Oscillation frequency (Hz) TYP.	Package
☆IR2E65U	White LED driver for backlight	- Capable of driving a maximum of 120 LEDs with 12 LEDs (in series) per channel - Built-in step-up DC-DC controller - High oscillation frequency (1.5 MHz) makes use of a small coil possible - Wider range of PWM brightness control possible, from simultaneous total output control to local dimming - Step-up output control according to LED-Vf	10	120	PWM	○	External	10 to 28	100/ch	500 k to 1.5 M	52HQFN
★IR2E66M		- Capable of driving a maximum of 48 LEDs with 12 LEDs (in series) per channel - Relationship between input voltage and LED anode voltage sizes not relevant, thanks to built-in DC-DC converter - High oscillation frequency (2 MHz) makes use of a small coil possible - Capable of controlling brightness using PWM control - Step-up output control according to LED-Vf	4	48		○	○	6 to 28	100/ch	100 k to 2 M	48QFP

*1 LED constant current value can be set by external resistors.

*2 Peak switching current

*3 Constant current (MAX.)

*4 Use this IC within the range of power dissipation.

*5 Selectable oscillation frequency range

*6 3.57 mm x 3.57 mm x 0.82 mm (TYP.)

*7 3.57 mm x 3.57 mm x 0.65 mm (TYP.)

●External power supply for LEDs

Model No.	Function	Features	Supply voltage (V)	Package
IR2D20U	24-dot LED panel driver with constant-current sink outputs	- Output current (constant current sink output): 30 mA (MAX.) (setup by external resistor) - Gradation function (clock cycle setting or external synchronization) - Independent current control for three systems (for RGB LED) - LED drive voltage: 15 V - Rated output voltage: 20 V (MAX.) - fCLK: 20 MHz (MAX.)/16.6 MHz (MAX.) (at cascade connection)	4.5 to 5.5	P-HQFN052-0707
IR2D071	16-dot LED panel driver with constant current sink outputs	- Output current (constant-current sink output): 60 mA (MAX.) (setup by external resistor) - Rated output voltage: 7 V (MAX.) - fCLK: 20 MHz (MAX.)/16.6 MHz (MAX.) (at cascade connection)	3.0 to 5.5	P-SDIP028-0400

■ Power Supply Modules for LED Lighting (AC Direct Drive)

Model No.	Features	Input voltage range Vin (rms)	Input frequency Freq (Hz)	Output voltage range Vo (V)	Output current Iop (mA)	Output power W (W)	Operating temperature range (°C)
★PQ1AS10C1KA	- Can be connected to the existing light controllers - No electrolytic capacitor	AC100 V±10%	50/60	87 to 113	MAX. 150	8	0 to +60
★PQ1AS10C1KB		AC110 V±10% AC120 V±10%		102 to 116	MAX. 150	8	



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Power Amplifiers for Wireless LAN

Model No.	Application	Operating frequency (GHz)	Supply voltage Vcc (V) TYP.	Control voltage Vbb (V) TYP.	Linear output power*1 (dBm)	Dissipation current (mA) TYP.	Gain (dB) TYP.	Detection function	Matching circuit	Package (W × D × H mm)
IRM046U7	For 2.4/5 GHz dual-band wireless LAN (IEEE802.11a/b/g/n)	2.4 to 2.5	3.3	2.8	18	105	30	○	—	P-HQFN024-0404 (4.2 × 4.2 × 1.0)
		4.9 to 5.9			18	140	25		—	
IRM065U7	For 2.4/5 GHz dual-band wireless LAN (IEEE802.11a/b/g/n)	2.4 to 2.5		2.8	18	130	30	○	Built-in (IN/OUT)	P-HQFN016-0303 (3 × 3 × 0.4)
		4.9 to 5.9			18	160	30		Built-in (IN/OUT)	
IRM067U6	For 2.4/5 GHz dual-band wireless LAN (IEEE802.11a/b/g/n)	2.4 to 2.5		2.9	17	100	28	○*2	Built-in (IN/OUT)	P-HQFN016-0303 (3 × 3 × 0.4)
		4.9 to 5.9			17	140	30		Built-in (IN/OUT)	
IRM063U7	For 2.4 GHz single-band wireless LAN (IEEE802.11b/g/n)	2.4 to 2.5		2.8	18	130	30	○	Built-in (IN/OUT)	P-HQFN010-0202A (2 × 2 × 0.4)
IRM068U7	For 2.4 GHz single-band wireless LAN (IEEE802.11b/g/n)	2.4 to 2.5		2.8	18	115	27	○*2	Built-in (IN)	HS0N06-P-1515 (1.5 × 1.5 × 0.4)
IRM053U7	For 5 GHz single-band wireless LAN (IEEE802.11a/n)	4.9 to 5.9		2.8	18	170	30	○	Built-in (IN/OUT)	P-HQFN010-0202A (2 × 2 × 0.4)

*1 At time of OFDM 64QAM modulating wave input.

*2 Load fluctuation stabilization and detection output type

Fail Safe ICs

Model No.	Features	Operating voltage			Dissipation current (μA) TYP.	Operating temp. (°C)	Package
		VBAT (V)	VBAC (V)	VIO (V)			
IR3T46U6	- Malfunction detection - Built-in 8-bit ADC - Built-in timer circuit - Built-in key detection output OR gate	3.2 to 4.5	3.0 to 3.3	2.6 to 3.0	10	-20 to +85	P-HQFN024-0404
IR3T48Y6	- Small package - Built-in 3-STATE buffer - Malfunction detection - Built-in 8-bit ADC - Built-in timer circuit - Built-in key detection output OR gate			1.6 to 3.0			35WL-CSP*

* 3.0 (W) × 3.0 (D) × 0.975 (H) mm (TYP.)

Solar Modules for Mobile Devices

Model No.	Features	Maximum output power* TYP. (mW)	Maximum output voltage* TYP. (V)	Maximum output current* TYP. (mA)	Outline dimensions (mm)
☆LR0GC02	Module thickness: 0.8 mm	300	4.5	67	67.5 × 41.0 × 0.8

* Measuring conditions: AN 1.5; irradiance: 1000 W/m² ± 50 mW; module temperature: at 25°C



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■ CSP

●CSP (Chip Size Package)

The FBGA (commonly known as CSP) has an area array terminal structure with solder balls on the bottom, to give it a near chip-size footprint. This high-density, compact and low-profile package technology will greatly help in the design of compact mobile equipment, such as mobile phones and digital cameras.



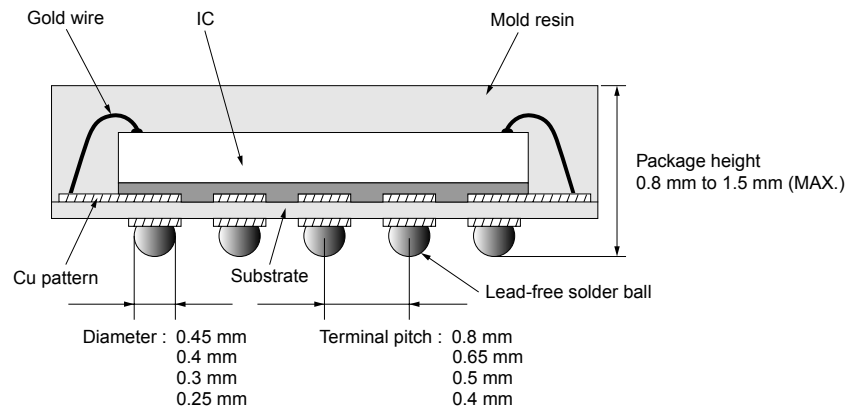
FBGA (CSP)

Features

- **Compact and lightweight**
Ability to create a near-chip size and lighter-weight package in comparison with conventional plastic packages.
- **High reliability**
Comparable high reliability with that of conventional plastic packages.
- **Mountability**
Conventional mounting system is available for CSP. SOP and QFP can be mounted together with CSP.

Terminal pitch	0.8 mm	0.65 mm	0.5 mm	0.4 mm
Maximum terminal counts	352 (16 mm x 16 mm)	352 (16 mm x 16 mm)	372 (16 mm x 16 mm)	264 (10 mm x 10 mm)
Nominal dimensions	6 mm x 6 mm to 16 mm x 16 mm			5 mm x 5 mm to 10 mm x 10 mm

Cross section example



●Wafer-level CSP

The wafer-level CSP (WL-CSP) is a kind of chip-size package which is manufactured by assembling directly onto the finished wafer.

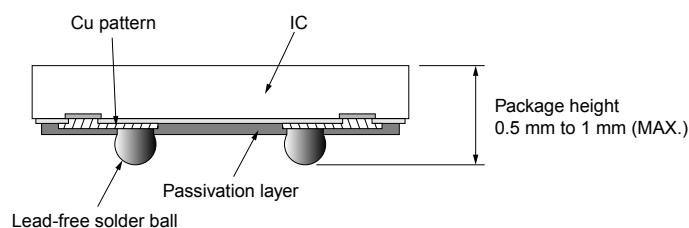
Features

- **Compact and thinner size**
It makes it possible to create an almost IC-size and lighter-weight package.
- **Mountability**
The conventional CSP mounting system can be also used in that of wafer-level CSP, which facilitates chip mounting more than bare-chip mounting does. It can be mounted together with other existing packages and passive components. (The use of underfill is recommended to improve the reliability of assembly.)

Chip size*	4 mm x 4 mm		3.5 mm x 3.5 mm		3 mm x 3 mm		★ 2.5 mm x 2.5 mm	
Pad pitch	0.5 mm	0.4 mm	0.5 mm	0.4 mm	0.5 mm	0.4 mm	0.5 mm	0.4 mm
Maximum terminal counts	49 (7 x 7)	81 (9 x 9)	36 (6 x 6)	49 (7 x 7)	25 (5 x 5)	36 (6 x 6)	16 (4 x 4)	25 (5 x 5)

* Rectangular chip form is also available.

Cross section example





■ SiP (System in Package)

System in Package is SHARP's original high-density mounting technology that achieves high-density memory capacity and multiple functions by stacking multiple ICs or multiple packages. The System in Package technology means chip-stacked package technology that can achieve up to 5-chip mounting by stacking ICs in a single package. The System in Package technology contributes to higher functionality of applications, such as mobile phones and digital cameras, as well as to reduction in size and weight.

● Chip Stacked CSP

Features	● Wide variety of lineup It is possible to provide a wide lineup of stacked CSPs, including 2-chip, 3-chip, 4-chip and 5-chip stacked CSPs, to respond to customer needs. ● Compact and thinner size Encapsulating multiple ICs into an existing plastic package contributes to decreasing the mounting area. In addition, SHARP's wafer thinning technology makes it possible to achieve 1.4 mm (MAX.) package height. ● Multiple functions Multiple ICs of different sizes and functions, such as logic LSIs and memories, can be incorporated in a single package, making possible multiple functions. ● Same-size IC stacking technology SHARP's stacking technology enables stacking of multiple same-size ICs, contributing to higher memory density. (4-chip stacked CSP) When using a SHARP four-chip stacked CSP, the mounting area and weight of a package can be decreased by half in comparison with using two 2-chip stacked CSPs, or a 3-chip stacked CSP and a conventional CSP.
Cross section example	(5-chip stacked CSP) Gold wire IC Mold resin Package height 1.4 mm (MAX.)* 1.6 mm (MAX.)* Cu pattern Substrate Lead-free solder ball Diameter : 0.45 mm 0.30 mm Terminal pitch : 0.8 mm 0.5 mm * At 0.8 mm terminal pitch

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●Chip Stacked TSOP/QFP*/VQFN/HQFN

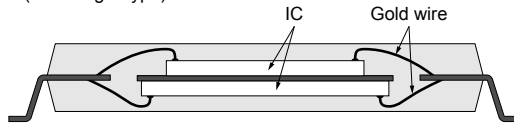
Features

- **Decreased mounting area**
By encapsulating two identical or different types of ICs into a single conventional plastic package, the mounting area of the package can be decreased.
- **Multiple functions**
Thanks to the incorporation of different sizes and functions of multiple ICs, such as logic LSIs and memories, the functionality increases.
- **Higher memory density**
When incorporating two identical memory ICs into a single package, memory density doubles on the same mounting area.

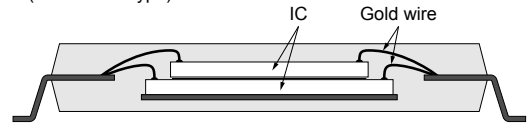
Cross section example

(TSOP, QFP*)

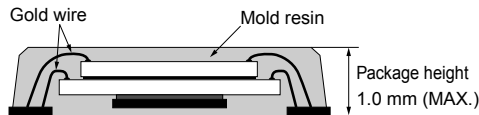
(Hamburger type)



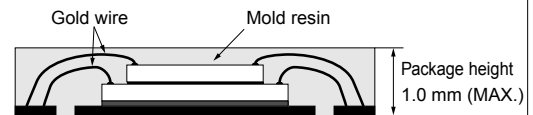
(Turtle stack type)



(VQFN)



(HQFN)



* Including TQFP and LQFP.

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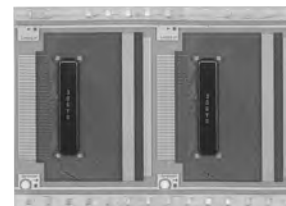
■ SOF

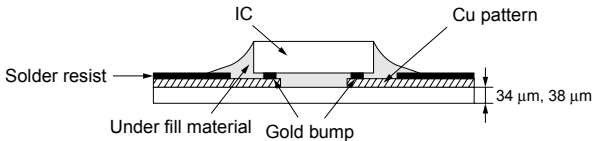
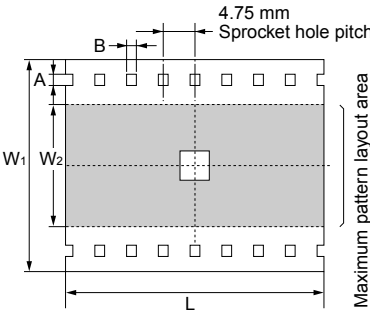
● SOF (System On Film)

SOF is a highly flexible thin film package, created from SHARP's TCP technologies.

It can be easily bent, and contributes to thin and compact design of products.

Peripheral circuit components can also be mounted.



Features	● Highly flexible and thin film package By using highly flexible and thin film, SOF contributes to creating thin and compact products. It can also achieve finer terminal pitches and multiple outputs easily, and pattern layout on a film under the chip makes it possible to improve the flexibility of the pattern layout. ● Multiple chip mounting Multiple chip mounting with peripheral chip components contribute to the higher functionality of products.																																				
Cross section example																																					
Film specifications	<table><tr><td>Film width : W₁</td><td>35 mm super wide</td><td>48 mm super wide</td><td>70 mm wide</td></tr><tr><td>Maximum pattern layout area : W₂</td><td>28.6 mm</td><td>41.6 mm</td><td>59.0 mm</td></tr><tr><td>Maximum device pitch : L</td><td colspan="3">15 sprockets</td></tr><tr><td>Pattern thickness</td><td colspan="3">8 μm</td></tr><tr><td>Pattern layer</td><td colspan="3">Electro-deposited Cu</td></tr><tr><td>Pattern layer finish</td><td colspan="3">Tin (Sn)</td></tr><tr><td>Minimum pattern pitch</td><td colspan="3">0.025 mm</td></tr><tr><td>Sprocket hole : A</td><td colspan="3">1.981 mm (wide) / 1.42 mm (super wide)</td></tr><tr><td>Sprocket hole : B</td><td colspan="3">1.981 mm (wide) / 1.42 mm (super wide)</td></tr></table> 	Film width : W ₁	35 mm super wide	48 mm super wide	70 mm wide	Maximum pattern layout area : W ₂	28.6 mm	41.6 mm	59.0 mm	Maximum device pitch : L	15 sprockets			Pattern thickness	8 μm			Pattern layer	Electro-deposited Cu			Pattern layer finish	Tin (Sn)			Minimum pattern pitch	0.025 mm			Sprocket hole : A	1.981 mm (wide) / 1.42 mm (super wide)			Sprocket hole : B	1.981 mm (wide) / 1.42 mm (super wide)		
Film width : W ₁	35 mm super wide	48 mm super wide	70 mm wide																																		
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Sprocket hole : A	1.981 mm (wide) / 1.42 mm (super wide)																																				
Sprocket hole : B	1.981 mm (wide) / 1.42 mm (super wide)																																				
Other components	Bare chips and peripheral chip components can be mounted on the film.																																				

In addition to the SOF described above, a conventional TCP (Tape Carrier Package) is also available.

Notice

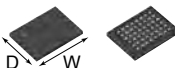
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Package Lineup

●Surface-mount Type

Package type	Appearance (Package material)	Package code	No. of terminals	Terminal pitch mm	Nominal dimensions mm	Package depth & width (D x W) x (seated height [MAX.]) mm	
FBGA (CSP)		P-LFBGA048-0606	48	0.8	6 x 6	6.0 x 6.0 x (1.4)	
		P-TFBGA048-0608			6 x 8	6.0 x 8.0 x (1.2)	
		P-TFBGA048-0808			8 x 8	8.0 x 8.0 x (1.2)	
		P-TFBGA056-0808	56		8 x 11	8.0 x 11.0 x (1.2)	
		P-TFBGA060-0811	60 (48)*				
		P-TFBGA064-0811	64				
		P-TFBGA072-0811	72 (64)*		8 x 8	8.0 x 11.0 x (1.4) / (1.6)	
		P-LFBGA072-0811					
		P-TFBGA081-0808	81		8 x 11	8.0 x 11.0 x (1.4) / (1.6)	
		P-LFBGA085-0811	85				
		P-LFBGA087-0811	87				
		P-LFBGA088-0811	88		9 x 12	9.0 x 12.0 x (1.4) / (1.6)	
		P-LFBGA088-0912					
		P-LFBGA090-0811	90		8 x 11	8.0 x 11.0 x (1.4) / (1.6)	
		P-TFBGA096-1010	96		10 x 10	10.0 x 10.0 x (1.2)	
		P-LFBGA107-0912	107		9 x 12	9.0 x 12.0 x (1.4) / (1.6)	
		P-TFBGA111-1010	111		10 x 10	10.0 x 10.0 x (1.2)	
		P-TFBGA112-1010	112				
		P-LFBGA115-0914	115		9 x 14	9.0 x 14.0 x (1.4) / (1.6)	
		P-LFBGA116-1010	116		10 x 10	10.0 x 10.0 x (1.4) / (1.6)	
		P-LFBGA130-1013	130		10 x 13	10.0 x 13.0 x (1.4) / (1.6)	
		P-TFBGA144-1111	144		11 x 11	11.0 x 11.0 x (1.2)	
		P-TFBGA160-1212	160				
		P-LFBGA168-1212	168				
		P-TFBGA180-1212	180		12 x 12	12.0 x 12.0 x (1.2)	
		P-TFBGA184-1212	184				
		P-TFBGA240-1414	240		14 x 14	14.0 x 14.0 x (1.2)	
		P-LFBGA280-1616	280				
		P-LFBGA352-1616	352		16 x 16	16.0 x 16.0 x (1.5)	
	(Plastic)	P-TFBGA064-0606	64		0.65	6 x 6	6.0 x 6.0 x (1.2)
		P-LFBGA140-0909	140			9 x 9	9.0 x 9.0 x (1.4)
		P-LFBGA160-1010	160			10 x 10	10.0 x 10.0 x (1.4) / (1.6)
		P-TFBGA180-1313	180			13 x 13	13.0 x 13.0 x (1.2)
		P-LFBGA192-1010	192			10 x 10	10.0 x 10.0 x (1.4) / (1.6)
		P-LFBGA208-1212	208			12 x 12	12.0 x 12.0 x (1.4) / (1.6)
		P-LFBGA224-1313	224			13 x 13	13.0 x 13.0 x (1.4) / (1.6)
		P-TFBGA260-1313	260				

* Figures in brackets indicate available terminal counts.

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●Surface-mount Type (cont'd)

Package type	Appearance (Package material)	Package code	No. of terminals	Terminal pitch mm	Nominal dimensions mm	Package depth & width (D x W) x (seated height [MAX.]) mm
FBGA (CSP)		P-VFBGA057-0505	57	0.5	5 x 5	5.0 x 5.0 x (0.9)
		P-VFBGA075-0505	75			
		P-TFBGA064-0606	64		6 x 6	6.0 x 6.0 x (1.1)
		P-TFBGA068-0606	68			
		P-VFBGA081-0606	81			6.0 x 6.0 x (0.9)
		P-TFBGA084-0606	84			6.0 x 6.0 x (1.1)
		P-VFBGA100-0606				6.0 x 6.0 x (0.9)
		P-VFBGA100-0707	100			7.0 x 7.0 x (0.9)
		P-TFBGA100-0707				7.0 x 7.0 x (1.1)
		P-VFBGA108-0707			7 x 7	7.0 x 7.0 x (0.9)
		P-TFBGA108-0707	108			7.0 x 7.0 x (1.1)
		P-VFBGA120-0707				7.0 x 7.0 x (0.9)
		P-TFBGA120-0707	120			7.0 x 7.0 x (1.1)
		P-TFBGA132-0707	132			
		P-TFBGA133-0808	133		8 x 8	8.0 x 8.0 x (1.1)
		P-VFBGA144-0808				8.0 x 8.0 x (0.9)
		P-LFBGA144-0808	144			8.0 x 8.0 x (1.3) / (1.5)
		P-LFBGA144-0811			8 x 11	8.0 x 11.0 x (1.3)
		P-TFBGA152-0808	152		8 x 8	8.0 x 8.0 x (1.1)
		P-VFBGA171-0811			8 x 11	8.0 x 11.0 x (0.9)
		P-LFBGA171-0811	171			8.0 x 11.0 x (1.3) / (1.5)
		P-VFBGA176-0909				9.0 x 9.0 x (0.9)
		P-TFBGA176-0909	176		9 x 9	9.0 x 9.0 x (1.1)
		P-TFBGA180-0909	180			
		P-TFBGA188-0909				
		P-VFBGA188-1111	188		11 x 11	11.0 x 11.0 x (0.9)
		P-VFBGA208-1010				10.0 x 10.0 x (0.9)
		P-TFBGA208-1010	208		10 x 10	10.0 x 10.0 x (1.1)
		P-TFBGA245-1010				10.0 x 10.0 x (1.3)
		P-LFBGA245-1010	245			10.0 x 10.0 x (1.3)
		P-FBGA424-1414	424		14 x 14	14.0 x 14.0 x (1.8)
		P-WFBGA144-0606	144	0.4	6 x 6	6.0 x 6.0 x (0.75)
		P-WFBGA121-0606	121			6.0 x 6.0 x (0.8)
		P-WFBGA145-0606	145			
		P-TFBGA168-0707	168		7 x 7	7.0 x 7.0 x (1.0)
		P-TFBGA204-0808	204		8 x 8	8.0 x 8.0 x (1.0)
		P-WFBGA205-0808	205			8.0 x 8.0 x (0.8)

(Plastic)

Notice

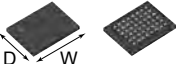
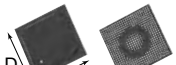
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●Surface-mount Type (cont'd)

Package type	Appearance (Package material)	Package code	No. of terminals	Terminal pitch mm	Nominal dimensions mm	Package depth & width (D x W) x (seated height [MAX.]) mm
FBGA (CSP)		P-TFBGAXXX-0606	to 36	0.8	6 x 6	6.0 x 6.0 x (1.2)
		P-TFBGAXXX-0707	to 49		7 x 7	7.0 x 7.0 x (1.2)
		P-TFBGAXXX-0808	to 81		8 x 8	8.0 x 8.0 x (1.2)
		P-TFBGAXXX-0909	to 100		9 x 9	9.0 x 9.0 x (1.2)
		P-TFBGAXXX-1010	to 121		10 x 10	10.0 x 10.0 x (1.2)
		P-TFBGAXXX-1111	to 144		11 x 11	11.0 x 11.0 x (1.2)
		P-TFBGAXXX-1212	to 196		12 x 12	12.0 x 12.0 x (1.2)
		P-TFBGAXXX-1313	to 216		13 x 13	13.0 x 13.0 x (1.2)
		P-TFBGAXXX-1414	to 240		14 x 14	14.0 x 14.0 x (1.2)
		P-TFBGAXXX-1515	to 352		15 x 15	15.0 x 15.0 x (1.2)
		P-TFBGAXXX-1616	to 352		16 x 16	16.0 x 16.0 x (1.2)
		P-TFBGAXXX-0606	to 49	0.65	6 x 6	6.0 x 6.0 x (1.2)
		P-TFBGAXXX-0707	to 81		7 x 7	7.0 x 7.0 x (1.2)
		P-TFBGAXXX-0808	to 121		8 x 8	8.0 x 8.0 x (1.2)
		P-TFBGAXXX-0909	to 144		9 x 9	9.0 x 9.0 x (1.2)
		P-TFBGAXXX-1010	to 196		10 x 10	10.0 x 10.0 x (1.2)
		P-TFBGAXXX-1111	to 224		11 x 11	11.0 x 11.0 x (1.2)
		P-TFBGAXXX-1212	to 256		12 x 12	12.0 x 12.0 x (1.2)
		P-TFBGAXXX-1313	to 272		13 x 13	13.0 x 13.0 x (1.2)
		P-TFBGAXXX-1414	to 304		14 x 14	14.0 x 14.0 x (1.2)
		P-TFBGAXXX-1515	to 320		15 x 15	15.0 x 15.0 x (1.2)
		P-TFBGAXXX-1616	to 352		16 x 16	16.0 x 16.0 x (1.2)
		P-TFBGAXXX-0606	to 100	0.5	6 x 6	6.0 x 6.0 x (1.1)
		P-TFBGAXXX-0707	to 132		7 x 7	7.0 x 7.0 x (1.1)
		P-TFBGAXXX-0808	to 164		8 x 8	8.0 x 8.0 x (1.1)
		P-TFBGAXXX-0909	to 192		9 x 9	9.0 x 9.0 x (1.1)
		P-TFBGAXXX-1010	to 216		10 x 10	10.0 x 10.0 x (1.1)
		P-TFBGAXXX-1111	to 244		11 x 11	11.0 x 11.0 x (1.1)
		P-TFBGAXXX-1212	to 268		12 x 12	12.0 x 12.0 x (1.1)
		P-TFBGAXXX-1313	to 296		13 x 13	13.0 x 13.0 x (1.1)
		P-TFBGAXXX-1414	to 320		14 x 14	14.0 x 14.0 x (1.1)
		P-TFBGAXXX-1515	to 348		15 x 15	15.0 x 15.0 x (1.1)
		P-TFBGAXXX-1616	to 372		16 x 16	16.0 x 16.0 x (1.1)
		P-TFBGAXXX-0505	to 100	0.4	5 x 5	5.0 x 5.0 x (1.0)
		P-TFBGAXXX-0606	to 144		6 x 6	6.0 x 6.0 x (1.0)
		P-TFBGAXXX-0707	to 168		7 x 7	7.0 x 7.0 x (1.0)
		P-TFBGAXXX-0808	to 204		8 x 8	8.0 x 8.0 x (1.0)
		P-TFBGAXXX-0909	to 228		9 x 9	9.0 x 9.0 x (1.0)
		P-TFBGAXXX-1010	to 264		10 x 10	10.0 x 10.0 x (1.0)
PBGA (BGA)		P-BGA0356-2121	356	1.0	21 x 21	21.0 x 21.0 x (2.2)
		P-BGA0476-3535	476	1.27	35 x 35	35.0 x 35.0 x (2.63)
		P-BGA0528-3535	528			

XXX: Terminal counts

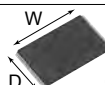
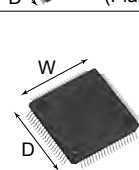
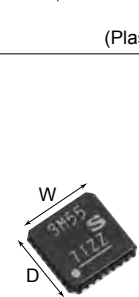
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●Surface-mount Type (cont'd)

Package type	Appearance (Package material)	Package code	No. of terminals	Terminal pitch mm (mil)	Nominal dimensions mm (mil)	Package depth & width (D x W) x (seated height [MAX.]) mm	Lead frame material	
							Alloy42	Copper alloy
SSOP	 (Plastic)	P-SSOP008-0150	8	0.65	4.5 (150)	3.0 x 3.0 x (1.1)	—	○
		P-SSOP024-0275	24		7.0 (275)	6.0 x 7.8 x (1.27)	—	○
TSOP	 (Plastic)	P-TSOP040-1020	40	0.5	10 x 20	10.0 x 18.4 x (1.2)	○	○
		P-TSOP048-1220	48		12 x 20	12.0 x 18.4 x (1.2)	○	○
		P-TSOP056-1420	56		14 x 20	14.0 x 18.4 x (1.2)	○	○
QFP	 (Plastic)	P-QFP048-0707	48	0.5	7 x 7	7.0 x 7.0 x (1.65)	○	○
P-QFP072-1010		72	10 x 10		10.0 x 10.0 x (1.8)	○	—	
LQFP		P-LQFP080-1212	80	0.5	12 x 12	12.0 x 12.0 x (1.7)	○	—
		P-LQFP100-1414	100		14 x 14	14.0 x 14.0 x (1.7)	○	—
TQFP		P-TQFP048-0707	48	0.5	7 x 7	7.0 x 7.0 x (1.2)	○	—
		P-TQFP100-1414	100		14 x 14	14.0 x 14.0 x (1.2)	○	—
		P-TQFP128-1414	128	0.4	14 x 14	14.0 x 14.0 x (1.2)	○	—
VQFN	 (Plastic)	P-VQFN020-0404	20	0.5	4 x 4	4.2 x 4.2 x (1.0)	—	○
		P-VQFN024-0404	24				—	○
		P-VQFN028-0505	28				—	○
		P-VQFN032-0505	32				—	○
		P-VQFN036-0606	36	0.4	6 x 6	6.2 x 6.2 x (1.0)	—	○
		P-VQFN048-0707	48		7 x 7	7.2 x 7.2 x (1.0)	—	○
		P-VQFN036-0505	36		5 x 5	5.2 x 5.2 x (1.0)	—	○
		P-VQFN052-0707	52		7 x 7	7.2 x 7.2 x (1.0)	—	○
HQFN*	 (Plastic)	P-HQFN020-0404	20	0.5	4 x 4	4.0 x 4.0 x (1.0)	—	○
		P-HQFN024-0404	24			4.0 x 4.0 x (0.85)	—	○
		P-HQFN028-0505	28			5 x 5	5.0 x 5.0 x (1.0)	—
		P-HQFN052-0707	52	0.4	7 x 7	7.2 x 7.2 x (1.0)	—	○

* HQFN is a higher heat dissipation package of VQFN.

100 mil = 2.54 mm

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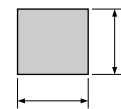


●For CCDs

Package type	Appearance (Package material)	Package code	No. of terminals	Terminal pitch mm	Nominal dimensions mm (mil)	Package depth & width (D x W) x (seated height [TYP.]) mm
DIP	 (Plastic)	P-DIP014-0400A	14	1.27	10.16 (400)	10.0 x 10.0
		P-DIP016-0450	16	1.27	11.43 (450)	11.4 x 12.2
		P-DIP016-0500C		1.78	12.7 (500)	12.4 x 14.0
SOP	 (Plastic)	P-SOP028-0400	28	0.69	10.16 (400)	10.0 x 10.0 x (3.5)
		P-SOP032-0525	32	0.78	13.3 (525)	12.0 x 13.8 x (3.92)
LCC	 (Ceramic)	N-LCC040-R350	40	0.65	8.9	8.3 x 8.9 x (1.52)
		N-LCC040-S433A		0.80	11.0	11.0 x 11.0 x (1.62)

100 mil = 2.54 mm

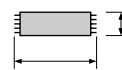
Nominal dimensions



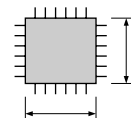
FBGA (CSP)
PBGA (BGA)



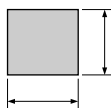
SOP
SSOP
MFP



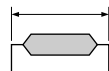
TSOP



QFP
LQFP
TQFP



VQFN
HQFN



DIP



LCC

FBGA : fine-pitch ball grid array package
PBGA : plastic ball grid array package
SOP : small outline package
SSOP : shrink small outline package
MFP : mini flat package
TSOP : thin small outline package

QFP : quad flat package
LQFP : low profile quad flat package
TQFP : thin quad flat package
VQFN : very thin quad flat non-leaded package
HQFN : heat sink quad flat non-leaded package
DIP : dual inline package
LCC : leadless chip carrier

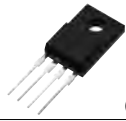
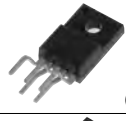
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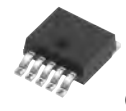
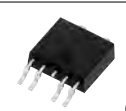
●Lead-inserting Type Packages [For regulators: PQ series]

Package type	Appearance (Package material)	No. of terminals	Terminal pitch mm	Outline dimensions (Width x Thickness x Height) mm	Lead frame material
TO-220	 (Plastic)	4	2.54	10.2 (MAX.) x 4.5 x 29.1 ^{*2}	Cu
TO-220 (Full mold)	 (Plastic)	4	2.54	10.2 (MAX.) x 4.5 x 29.1 ^{*2}	Cu
TO-220 (Full mold) [Lead forming type]	 (Plastic)	5	(1.7) ^{*1}	10.2 (MAX.) x 4.5 x 24.6 ^{*2}	Cu
TO-220 [Lead forming type]	 (Plastic)	5	(1.7) ^{*1}	10.2 (MAX.) x 4.5 x 24.6 ^{*2}	Cu
TO-220 [Lead forming type]	 (Plastic)	5	(1.7) ^{*1}	10.2 (MAX.) x 4.5 x 24.6 ^{*2}	Cu

*1 The figure in parentheses indicates reference value.

*2 Including lead length

●Surface-mount Type Packages [For regulators/LED drivers: PQ series]

Package type	Appearance (Package material)	No. of terminals	Terminal pitch mm	Outline dimensions (Width x Height x Thickness) mm	Lead frame material
TO-263	 (Plastic)	5 (Heat sink not included)	(1.7) ^{*1}	10.6 (MAX.) x 13.7 (MAX.) ^{*2} x 3.5	Cu
SC-63	 (Plastic)	5 (Heat sink not included)	(1.27) ^{*1}	6.6 (MAX.) x 9.7 (MAX.) ^{*2} x 2.3	Cu
SC-63	 (Plastic)	5 (Heat sink included)	(1.27) ^{*1}	6.6 (MAX.) x 9.7 (MAX.) ^{*2} x 2.1	Cu
SOP-8	 (Plastic)	8	1.27	5 x 6.2 ^{*2} x 1.55 ^{*2}	Cu

*1 The figure in parentheses indicates reference value.

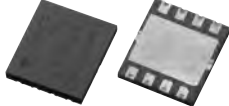
*2 Including lead length

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●Surface-mount Type Packages [For regulators/LED drivers: PQ series] (cont'd)

Package type	Appearance (Package material)	No. of terminals	Terminal pitch mm	Outline dimensions (Width x Height x Thickness) mm	Lead frame material
SOT-89	 (Plastic)	6	1.5	4.5 x 4.3*2 x 1.5	Cu
SOT-23-6	 (Plastic)	6	0.95	2.9 x 2.8*2 x 1.3	Cu
SOT-23-6W	 (Plastic)	6	0.95	2.9 x 2.8*2 x 1.3	Cu
SOT-23-L	 (Plastic)	6	(0.95)*1	(3.4)*1 x 3.3*2 x 1.4 (MAX.)	Cu
SOT-23-5	 (Plastic)	5	(0.95)*1	(2.9)*1 x 2.8*2 x 1.3 (MAX.)	Cu
USB-6		6	0.5	2.0 x 1.8 x 0.8	Cu (Terminal material)/ Au plating (Terminal finish)
USB-8		9 (Including radiating fin)	1.0	5.0 x 4.5 x 0.75 (MAX.)	Cu

*1 The figure in parentheses indicates reference value.

*2 Including lead length

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■ Photocoupler Lineup

<Phototransistor output type>

Package type	Output type	Features	Model No. (series)	Page
4-pin SOP Compact, SMT type 	Single phototransistor	General purpose, High collector-emitter voltage, etc.	PC35x series/PC451J00000F	56
		Low input current	PC367NJ0000F	56
	Darlington phototransistor	AC input response	PC354NJ0000F	56
		High sensitivity, High collector-emitter voltage	PC364NJ0000F	56
		Low input current	PC355NJ0000F	56
		Low input current	PC365NJ0000F	56
Compact, Half pitch (lead space), SMT type 	Single phototransistor	General purpose, High collector-emitter voltage, etc.	PC3Hx series	57
		Reinforced insulation	PC3HU72YIP0B	57
		Low input current	PC3H71xNIP0F	57
		High collector-emitter voltage	PC4H510NIP0F	57
	Darlington phototransistor	AC input response	PC3H3J00000F/PC3H4J00000F	57
		Low input current	PC3H41xNIP0F	57
		General purpose	PC3H5J00000F	57
		Low input current	PC3H510NIP0F	57
DIP type (4-pin) (4-pin, DIP type) 	Single phototransistor	Reinforced insulation	PC123XNNSZ0F	58
		Low input current	PC1231xNSZ0X	58
		General purpose, High collector-emitter voltage, etc.	PC817XNNSZ0F/PC851XNNSZ0F	58
		Low input current	PC817xxNSZ0X	58
	Darlington phototransistor	Built-in SBD/High response speed	PC81100NSZ0X	58
		General purpose, High collector-emitter voltage	PC815XNNSZ0F/PC852XNNSZ0F/ PC853XNNSZ0F	58
		Low input current	PC81510NSZ0X	58
DIP type (6-pin) 	Single phototransistor	General purpose, High collector-emitter voltage, etc.	PC7xxV0NSZXf	59
	Darlington phototransistor	General purpose, High collector-emitter voltage, etc.	PC7x5V0NSZXf	59

<OPIC output type>

Package type	Output type	Features	Model No. (series)	Page
Compact, SMT type 	Digital output	General purpose, High response speed, 2ch, etc.	PC40xJ00000F/PC456L0NIP0F/ PC41xS0NIP0F/PC4D10SNIP0F	60
	Analog/Digital output	High CMR	PC457S0NIP0F/PC457L0NIP0F	60
DIP type, SMT type 	Digital output	General purpose, High response speed, etc.	PC90xV0NSZXf	61
	Built-in base amplifier	For inverter control	PC925LENSZ0F/PC942J00000F	61



■ Photocouplers

◆ Phototransistor Output Type

<Compact, SMT type>

○: Approved, △: Under application

(Ta = 25°C)

Output type	Model No.	Internal connection diagram	Features	Approved by safety standards*2 UL	Package	Absolute maximum ratings			Electro-optical characteristics						
						Forward current I _F (mA)	Isolation voltage (AC) Viso (rms) (kV)	Collector-emitter voltage V _{CEO} (V)	Current transfer ratio			Response time			
									CTR (%) MIN.	I _F (mA)	V _{CE} (V)	t _r (μs) TYP.	I _C (mA)	R _L (Ω)	V _{CE} (V)
Single phototransistor output	PC357NJ0000F		General purpose	○*	Mini-flat 4-pin	50	3.75	80	50	5	5	4	2	100	2
	PC352NJ0000F		General purpose, high resistance to noise*1	○		50	3.75	80	90	5	5	4	2	100	2
	PC451J00000F		High collector-emitter voltage	○*		50	3.75	350	40	5	5	4	2	100	2
	PC367NJ0000F		Low input current, high resistance to noise*1	○		10	3.75	80	100	0.5	5	4	2	100	2
	PC354NJ0000F		AC input response	○*		±50	3.75	80	20	±1	5	4	2	100	2
	PC364NJ0000F		Low input current, AC input response, high resistance to noise*1	○		±10	3.75	70	50	±0.5	5	4	2	100	2
Darlington phototransistor output	PC355NJ0000F		High sensitivity	○*	Mini-flat 4-pin	50	3.75	35	600	1	2	60	2	100	2
	PC365NJ0000F		High sensitivity, low input current	○		10	3.75	35	600	0.5	2	60	2	100	2

*1 CMR: MIN.10 kV/μs

*2 Please refer to Specification Sheets for model numbers approved by safety standards.

* A VDE approved type is optionally available.



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◆ Phototransistor Output Type

<Compact, half pitch (lead space) SMT type>

○: Approved, △: Under application

(Ta = 25°C)

Output type	Model No.	Internal connection diagram	Features	Approved by safety standards*3	Package	Absolute maximum ratings			Electro-optical characteristics						
						Forward current IF (mA)	Isolation voltage (AC) Viso (rms) (kV)	Collector-emitter voltage VCEO (V)	Current transfer ratio			Response time			
				UL					CTR (%) MIN.	IF (mA)	VCE (V)	tr (μs) TYP.	IC (mA)	RL (Ω)	VCE (V)
Single phototransistor output	PC3HU72YIP0B		Reinforced insulation (internal insulation distance: MIN. 0.4 mm), low-profile package	○*4, 5	Low-profile mini-f at 4-pin	50	3.75	80	50	5	5	4	2	100	2
	PC3H2J00000F		High resistance to noise*1	○	Mini-f at 4-pin	50	2.5	80	20	1	5	4	2	100	2
	PC3H7J00000F		Standard	○		50	2.5	80	20	1	5	4	2	100	2
	PC3H71xNIP0F		High resistance to noise*1, low input current	○		10	2.5	80	100	0.5	5	4	2	100	2
	PC3H3J00000F		AC input response, high resistance to noise*1	○		±50	2.5	80	20	±1	5	4	2	100	2
	PC3H4J00000F		AC input response	○*2		±50	2.5	80	20	±1	5	4	2	100	2
	PC3H41xNIP0F		AC input response, high resistance to noise*1, low input current	○		±10	2.5	80	50	±0.5	5	4	2	100	2
	PC4H510NIP0F		High collector-emitter voltage	○		50	2.5	350	40	5	5	4	2	100	2
Darlington phototransistor output	PC3H5J00000F		High sensitivity	○	Mini-f at 4-pin	50	2.5	35	600	1	2	60	2	100	2
	PC3H510NIP0F		High sensitivity, low input current	○		10	2.5	35	600	0.5	2	60	2	100	2

*1 CMR: MIN. 10 kV/μs

*2 A VDE approved type is optionally available.

*3 Please refer to Specification Sheets for model numbers approved by safety standards.

*4 VDE, CSA approved

*5 In conformance with BSI, SEMKO, DEMKO, NEMKO, and FIMKO


PC3HU72YIP0B


PC3H2J00000F
(Mini-flat 4-pin)

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◆ Phototransistor Output Type <DIP type (4-pin)>

○: Approved, △: Under application

(Ta = 25°C)

Output type	Model No.	Internal connection diagram	Features	Approved by safety standards*8			Package	Absolute maximum ratings			Electro-optical characteristics			
				UL	VDE *2	Others *3		Forward current I _F (mA)	Isolation voltage (AC) V _{iso} (rms) (kV)	Collector-emitter voltage V _{CEO} (V)	Current transfer ratio CTR (%) MIN.	I _F (mA)	t _r (μs) TYP.	R _L (Ω)
Single phototransistor output	PC123XNNSZ0F*1		High isolation voltage, reinforced insulation	○	○	○	4-pin DIP	50	5.0	70	50	5	4	100
	PC1231xNSZ0X		High isolation voltage, reinforced insulation, low input current, high resistance to noise*4	○	○	○		10	5.0	70	50	0.5	4	100
	PC817XNNSZ0F*5, *6, *7		High isolation voltage	○	○	—		50	5.0	80	50	5	4	100
	PC8171xNSZ0X		High isolation voltage, low input current, high resistance to noise*4	○	—	—		10	5.0	70	100	0.5	4	100
	PC851XNNSZ0F		High isolation voltage, high collector-emitter voltage	○	—	—		50	5.0	350	40	5	4	100
	PC81100NSZ0X		Built-in schottky barrier diode, toff: 35μs TYP. (In saturation, R _L = 100kΩ)	○	—	—		50	5.0	70	50	5	ton: TYP. 9	100
Darlington phototransistor output	PC815XNNSZ0F		High isolation voltage, high sensitivity	○	—	—	4-pin DIP	50	5.0	35	600	1	60	100
	PC81510NSZ0X		High isolation voltage, high sensitivity, low input current	○	—	—		10	5.0	35	600	0.5	60	100
	PC852XNNSZ0F*5, *6		High isolation voltage, high collector-emitter voltage	○	○	—		50	5.0	350	1 000	1	100	100
	PC853XNNSZ0F*5, *6		High isolation voltage, high collector-emitter voltage	○	○	—		50	5.0	350	1 000	1	100	100

*1 Wide lead spacing type is also available. Creepage distance: 6.4 mm or more, wide lead spacing type: 8 mm or more.

*2 Optionally available.

*3 BSI, SEMKO, DEMKO, NEMKO, FIMKO, CSA

*4 CMR: 10 kV/μs MIN.

*5 Lead forming type is also available for surface mounting.

*6 Taped package of lead forming type for surface mounting is also available.

*7 Wide lead spacing type is also available. Compatible with wide lead spacing type lead-forming models for surface-mount use. Also compatible with taped packages for wide lead spacing type lead-forming models for surface-mount use.

*8 Please refer to Specification Sheets for model numbers approved by safety standards.



PC817XNNSZ0F
(4-pin DIP)

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◆ Phototransistor Output Type <DIP type (6-pin)>

○: Approved, △: Under application

(Ta = 25°C)

Output type	Model No.	Internal connection diagram	Features	Approved by safety standards*2		Package	Absolute maximum ratings			Electro-optical characteristics			
				UL	VDE*1		Forward current I _F (mA)	Isolation voltage (AC) Viso (rms) (kV)	Collector-emitter voltage V _{CEO} (V)	Current transfer ratio CTR (%) MIN.	I _F (mA)	t _r (μs) TYP.	R _L (Ω)
Single phototransistor output	PC714V0NSZXF		High isolation voltage	○	○	6-pin DIP	50	5.0	80	50	5	4	100
	PC724V0NSZXF		High isolation voltage, large input current	○	—		150	5.0	35	20	100	4	100
	PC713V0NSZXF		High isolation voltage, with base terminal	○	○		50	5.0	80	50	5	4	100
Darlington phototransistor output	PC715V0NSZXF		High isolation voltage, high sensitivity	○	○		50	5.0	35	600	1	60	100
	PC725V0NSZXF		High isolation voltage, high sensitivity, high collector-emitter voltage, high power	○	○		50	5.0	300	1 000	1	100	100

*1 Optionally available.

*2 Please refer to Specification Sheets for model numbers approved by safety standards.



PC713V0NSZXF
(6-pin DIP)

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◆ **OPIC Output** (“OPIC” (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<Compact, SMT type> (1-1)

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*2		Package	Absolute maximum ratings		Electro-optical characteristics*1						
			UL	VDE*3		Forward current I _F (mA)	Isolation voltage (AC) V _{iso} (rms) (kV)	Low level output voltage			Threshold input current			
								V _{OL} (V) MAX.	T _a (°C)	I _{OL} (mA)	I _F (mA)	I _{FHL} (mA) MAX.	I _{FLH} (mA) MAX.	R _L (Ω)
PC400J00000F		Digital output, normal-off operation	○	—	Mini-f at 5-pin	50	3.75	0.4	0 to +70	16	4	2.0	—	280
PC401J00000F		Digital output, normal-on operation	○	—		50	3.75	0.4	0 to +70	16	0	—	2.0	280
PC456L0NIP0F		Built-in preamplif er, high speed transmission (2 Mb/s), for f ow soldering	○	○		25	3.75	0.6	−40 to +85	4.4	10	5.0	—	20 k
PC410S0NIP0F		High speed (10 Mb/s), high CMR (10 kV/μs), for f ow soldering, Solder heat resistance: 270°C	○	○	SOP 8-pin	20	3.75	0.6	−40 to +85	13	5	5.0	—	350
PC4D10SNIP0F		High speed (10 Mb/s), for f ow soldering, Solder heat resistance: 270°C 2ch output	○	—	SOP 8-pin	20	3.75	0.6	−40 to +85	13	5	5.0	—	—

A: Rated voltage circuit

*1 Each item is measured at Vcc=5V. (PC400, PC401)

*2 Please refer to Specification Sheets for model numbers approved by safety standards.

*3 Optionally available.

*4 No forward current rating for voltage input (rated input voltage: −0.5 to 6.0 V).

<Compact, SMT type> (1-2)

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*1		Package	Absolute maximum ratings		Electro-optical characteristics							
			UL	VDE*2		Forward current I _F (mA)	Isolation voltage (AC) V _{iso} (rms) (kV)	Current transfer ratio				Propagation delay time			
								CTR (%) MIN.	I _F (mA)	V _O (V)	V _{CC} (V)	t _{PHL} (μs) TYP.	t _{PLH} (μs) TYP.	R _L (Ω)	I _F (mA)
PC457L0NIP0F		High speed (1 Mb/s), high CMR (15 kV/μs), for fow soldering	○	○	Mini-f at 5-pin	25	3.75	19	16	0.4	4.5	0.2	0.6	1 900	16
PC457S0NIP0F		High speed (1 Mb/s), high CMR (15 kV/μs), for fow soldering, Solder heat resistance: 270°C	○	○	SOP 8-pin	25	3.75	19	16	0.4	4.5	0.2	0.6	1 900	16

*1 Please refer to Specification Sheets for model numbers approved by safety standards.

*2 Optionally available.



PC400J00000F
(Mini-flat 5-pin)



PC410S0NIP0F
(SOP 8-pin)

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◆OPIC Output ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<DIP type, digital output>

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*5		Package	Absolute maximum ratings		Electro-optical characteristics*1						
			UL	VDE *4		Forward current IF (mA)	Isolation voltage (AC) Viso (rms) (kV)	Low level output voltage			Threshold input current			
								VOL (V) MAX.	Ta (°C)	IoL (mA)	IF (mA)	IFHL (mA) MAX.	IFLH (mA) MAX.	RL (Ω)
PC900V0NSZXF*2, *3		Digital output, normal-off operation	○	○	6-pin DIP	50	5.0	0.4	0 to +70	16	4	2.0	—	280
PC901V0NSZXF*2, *3		Digital output, normal-on operation	○	○		50	5.0	0.4	0 to +70	16	0	—	2.0	280

A: Rated voltage circuit

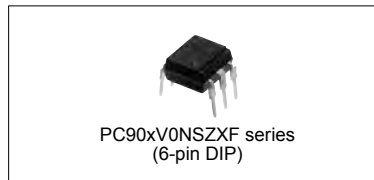
*1 Each item is measured at Vcc=5V.

*2 Lead forming type is also available for surface mounting.

*3 Taped package of lead forming type for surface mounting is also available.

*4 Optionally available.

*5 Please refer to Specification Sheets for model numbers approved by safety standards.



◆OPIC Output ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<DIP type, Gate drive type>

○: Approved, △: Under application

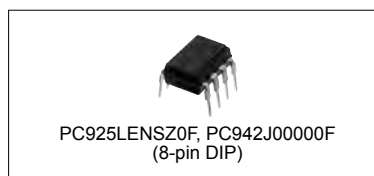
(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*3		Package	Absolute maximum ratings			Electro-optical characteristics					
			UL	VDE *2		Forward current If (mA)	Isolation voltage (AC) Viso (rms) (kV)	Output current Io1 (A)	Propagation delay time					
									tPHL (μs) TYP.	tPLH (μs) TYP.	VCC (V)	If (mA)	RL1 (Ω)	RL2 (Ω)
PC925LENSZ0F*1		- Built-in drive circuit directly connectable to MOS-FET and IGBT - Peak output current: 2.5 A - Low dissipation current (Icc = TYP. 5 mA) - High resistance to noise (CMR: MIN. 15 kV/μs)	○	○	8-pin DIP	25	5.0	2.5	MAX. 0.5	MAX. 0.5	15 to 30	7 to 16	R _G = 10	—
PC942J00000F		For controlling inverter-controlled air-conditioner	○	○		25	5.0	0.5	2.0	2.0	6	5	5	10

*1 Lead forming type is also available for surface mounting. Taped package of lead forming type for surface mounting is also available.

*2 A VDE approved type is optionally available.

*3 Please refer to Specification Sheets for model numbers approved by safety standards.



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■ Phototriac Coupler Lineup

Package	Applied voltage	ON-state current (rms)	Features		Model No.	Page
Mini-fat (SMD) 	AC 200 V lines (V _{DRM} = 600V)	0.05 A	General purpose		S2S3000F* ⁴ / S2S5A00F* ⁴	63
				Built-in zero-cross circuit	S2S4000F* ⁴	64
DIP type (4-pin) 	AC 200 V lines (V _{DRM} = 600V)	0.1 A	General purpose		PC3ST11NSZAF* ⁴	63
				Built-in zero-cross circuit	PC3ST21NSZBF* ³	64
			Reinforced isolation		PC3SH11YFZAF* ⁴ / PC3SH13YFZAF* ⁴	63
				Built-in zero-cross circuit	PC3SH21YFZBF* ³	64
DIP type (6-pin package, 5th-pin cut) 	AC 100 V lines (V _{DRM} = 400V)	0.1 A	General purpose		PC2SD11NTZAF* ⁴	63
	AC 200 V lines (V _{DRM} = 600V)	0.1 A	General purpose		PC3SD12NTZAF* ⁴ / PC3SD11NTZBF* ³ / PC3SD11NTZCF* ² / PC3SD11YTZDF* ¹ / PC3SD21YTZEF* ⁵	63/64
				Built-in zero-cross circuit	PC3SD21NTZAF* ⁴ / PC3SD21NTZBF* ³ / PC3SD21NTZCF* ² / PC3SD21NTZDF* ¹ / PC3SD23YTZCF* ²	64
			Reinforced isolation		PC3SF11YVZAF* ⁴ / PC3SF11YVZBF* ³ / PC3SF13YVZBF* ³	63
				Built-in zero-cross circuit	PC3SF21YVZAF* ⁴ / PC3SF21YVZBF* ³ / PC3SF23YVZSF* ³	64
			General purpose		PC4SD11NTZBF* ³ / PC4SD11NTZCF* ²	63
				Built-in zero-cross circuit	PC4SD21NTZCF* ² / PC4SD21NTZDF* ¹	64
			Reinforced isolation		PC4SF11YVZAF* ⁴ / PC4SF11YVZBF* ³	63
				Built-in zero-cross circuit	PC4SF21YVZBF* ³ / PC4SF21YVZCF* ²	64
	AC 200 V lines (V _{DRM} = 800V)	0.1 A	General purpose			

Minimum trigger current: *1 I_{FT} ≤ 3 mA, *2 I_{FT} ≤ 5 mA, *3 I_{FT} ≤ 7 mA, *4 I_{FT} ≤ 10 mA, *5 I_{FT} ≤ 2 mA



■ Phototriac Couplers

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*4			Package	Absolute maximum ratings			Electro-optical characteristics	
			UL, CSA	VDE	Others		ON-state current I _T (rms) (A)	Repetitive peak OFF-state voltage V _{DRM} (V)	Isolation voltage (AC) V _{iso} (rms) (kV)	Min. trigger current I _{FT} (mA) MAX. V _D = 6 V, R _L = 100Ω	
S2S3000F		200 V lines, compact	○	○*6	—	Mini-f at 4-pin	0.05	600	3.75	10	
S2S5A00F		200 V lines, compact	○	○*6	—					10	
PC3ST11NSZAF		200 V lines, compact	○	○*6	—	4-pin DIP*1	0.1	600	5.0	10	
PC3SH11YFZAF		200 V lines, compact, reinforced isolation	○	○	○*2					10	
PC3SH13YFZAF	200 V lines, compact, reinforced isolation, high noise resistance	○	○	○*2	10						
PC2SD11NTZAF*7		100 V lines	○	—	—	6-pin DIP*1, 3	0.1	400	5.0	10	
PC3SD12NTZAF*8		200 V lines	○	○*6	—			600		10	
PC3SD11NTZBF		200 V lines	○	○*6	—			800		7	
PC4SD11NTZBF		200 V lines, repetitive peak-OFF-state voltage	○	○*6	—			600		7	
PC3SD11NTZCF		200 V lines	○	○*6	—			800		5	
PC3SD11YTZDF		200 V lines, low input drive	○	○	—			600		3	
PC4SD11NTZCF		200 V lines, repetitive peak-OFF-state voltage	○	○*6	—			800		5	
PC3SF11YVZAF		200 V lines, reinforced isolation	○	○	○*2			600		10	
PC3SF11YVZBF		200 V lines, reinforced isolation	○	○	○*2					7	
PC3SF13YVZBF		200 V lines, reinforced isolation, high noise resistance	○	○	○*2			800		7	
PC4SF11YVZAF		200 V lines, reinforced isolation, repetitive peak-OFF-state voltage	○	○	○*2					10	
PC4SF11YVZBF		200 V lines, reinforced isolation, repetitive peak-OFF-state voltage	○	○	○*2					7	

For the notes *1 to *9, see next page.

Notice

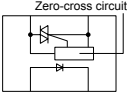
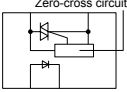
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Phototriac Couplers (Built-in zero-cross circuit type)

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*4			Package	Absolute maximum ratings			Electro-optical characteristics
			UL, CSA	VDE	Others		ON-state current I _T (rms) (A)	Repetitive peak OFF-state V _{DRM} (V)	Isolation voltage (AC) V _{iso} (rms) (kV)	Min. trigger current I _{FT} (mA) MAX. V _D = 4 V, R _L = 100Ω
S2S4000F		200 V lines, compact	○	○*6	—	Mini-f at 4-pin	0.05	600	3.75	10*5
PC3ST21NSZBF		200 V lines, compact	○	○*6	—	4-pin DIP*1	0.1	600	5.0	7
PC3SH21YFZBF		200 V lines, compact, reinforced isolation	○	○	○*2					7
PC3SD21NTZAF		200 V lines, low zero-cross voltage: MAX. 20 V	○	○*6	—	6-pin DIP*1,3	0.1	600	5.0	10
PC3SD21NTZBF		200 V lines, low zero-cross voltage: MAX. 20 V	○	○*6	—					7
PC3SD21NTZCF*9		200 V lines, low zero-cross voltage: MAX. 20 V	○	○*6	—					5
PC3SD23YTZCF		200 V lines, high pulse/noise resistance (TYP. 2 kV)	○	○	—					5
PC3SD21NTZDF		200 V lines, low zero-cross voltage: MAX. 20 V	○	○*6	—					3
PC3SD21YTZEF		200 V lines, Low input drive	○	○	—					2
PC4SD21NTZCF		200 V lines, repetitive peak-OFF-state voltage	○	○*6	—		800	5		
PC4SD21NTZDF		200 V lines, repetitive peak-OFF-state voltage	○	○*6	—					3
PC3SF21YVZAF		200 V lines, reinforced isolation	○	○	○*2		600	10		
PC3SF21YVZBF		200 V lines, reinforced isolation	○	○	○*2					7
PC3SF23YVZSF		200 V lines, reinforced isolation, high pulse/noise resistance (TYP. 2 kV)	○	○	○*2		800	7		
PC4SF21YVZBF		200 V lines, reinforced isolation, repetitive peak-OFF-state voltage	○	○	○*2					7
PC4SF21YVZCF		200 V lines, reinforced isolation, repetitive peak-OFF-state voltage	○	○	○*2					5

*1 Lead forming type for surface mounting is also available.

*2 In conformance with BSI, SEMKO, DEMKO, and FIMKO

*3 These are molded pin No. 5.

*4 Please refer to Specification Sheets for model numbers approved by safety standards.

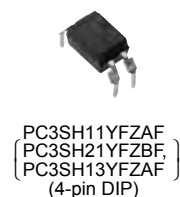
*5 V_D = 6 V, R_L = 100Ω

*6 Optionally available

*7 An equivalent model (I_{FT} MAX.: 15 mA) with overseas brand compatibility is also available. (PC1S3021NTZF)

*8 An equivalent model with overseas brand compatibility is also available. (PC1S3052NTZF)

*9 An equivalent model with overseas brand compatibility is also available. (PC1S3063NTZF)



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■ Solid State Relay Lineup

Package	Applied voltage	ON-state current (rms)	Features	Model No.	Page
DIP 6-pin	AC 100 V lines	0.06 A	General purpose	PR22MA11NTZF	66
	AC 200 V lines	0.15 A	General purpose	PR31MA11NTZF / PR32MA11NTZF	66
DIP 8-pin	AC 100 V lines	0.3/0.6/0.9 A	General purpose	PR23MF11NSZF / PR26MF series / PR29MF series	66
		0.6/0.9 A	Built-in zero-cross circuit	PR26MF21NSZF / PR29MF21NSZF	66
	AC 200 V lines	0.3/0.6/0.9/1.2 A	General purpose	PR33MF51NSZF / PR36MF series / PR39MF series / PR3BMF51NSKF	66
		0.6/0.9/1.2 A	Built-in zero-cross circuit	PR36MF series / PR39MF series / PR3BMF21NSZF	66
SIP 4-pin	AC 100 V lines	2/8 A 3 to 16 A	General purpose	S102T01F / S108T01F / S101S05F / S102S01F / S112S01F / S116S01F	67
		2/8 A 3 to 16 A	Built-in zero-cross circuit	S102T02F / S108T02F / S101S06F / S102S02F / S116S02F	67
Low profile		8 A	Built-in snubber circuit	S102S11F	67
		3/8 A	Built-in zero-cross circuit	S101S16F / S102S12F	67
	AC 200 V lines		General purpose	S202T01F / S208T01F / S202S01F / S212S01F / S216S01F	67
		2/8 A 3 to 16 A	Built-in zero-cross circuit	S202T02F / S208T02F / S201S06F / S202S02F / S216S02F	67/68
		8/8 A	Built-in snubber circuit	S202S15F / S202S11F	68
		8 A	Built-in zero-cross circuit	S202S12F	68



■ Solid State Relays

<DIP type>

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*1			Package	Absolute maximum ratings			Electrical characteristics	
			UL	CSA	VDE*2		ON-state current I _T (rms) (A)	Repetitive peak OFF-state voltage V _{DRM} (V)	Isolation voltage (AC) V _{iso} (rms) (kV)	Min. trigger current I _{FT} (mA) MAX. V _D = 6 V, R _L = 100Ω	
PR31MA11NTZF		200 V lines, compact	○	○	○	6-pin DIP	0.06	600	5.0	10	
PR22MA11NTZF		100 V lines, 150 mA model in a small package	○	○	○		0.15	400		10	
PR32MA11NTZF		200 V lines, 150 mA model in a small package	○	○	○			600		10	
PR23MF11NSZF		100 V lines, compact	○	○	—	8-pin DIP	0.3	400	4.0	10	
PR33MF51NSZF		200 V lines, compact	○	○	○			600		10	
PR26MF11NSZF		100 V lines, compact	○	○	—		0.6	400		10	
PR26MF12NSZF		100 V lines, compact, low input current	○	○	—					5	
PR29MF11NSZF		100 V lines, compact	○	○	—		0.9			10	
PR29MF12NSZF		100 V lines, compact, low input current	○	○	—					5	
PR36MF51NSZF		200 V lines, compact	○	○	○		0.6	600		10	
PR36MF12NSZF		200 V lines, compact, low input current	○	○	○					5	
PR39MF12NSZF		200 V lines, compact, low input current	○	○	○		0.9			5	
PR39MF51NSZF		200 V lines, compact	○	○	○					10	
PR3BMF51NSKF		200 V lines, compact	○	○	○		1.2			10	
PR26MF21NSZF			100 V lines, compact (built-in zero-cross circuit)	○	○		—	0.6		400	10
PR29MF21NSZF			100 V lines, compact (built-in zero-cross circuit)	○	○		—	0.9			10
PR36MF22NSZF	200 V lines, compact (built-in zero-cross circuit), low input current		○	○	○	0.6	600	5			
PR39MF22NSZF	200 V lines, compact (built-in zero-cross circuit), low input current		○	○	○	0.9		5			
PR36MF21NSZF	200 V lines, compact (built-in zero-cross circuit)		○	○	○	0.6		10			
PR39MF21NSZF	200 V lines, compact (built-in zero-cross circuit)		○	○	○	0.9		10			
PR3BMF21NSZF	200 V lines, compact (built-in zero-cross circuit)		○	○	○	1.2		10			

*1 Please refer to Specification Sheets for model numbers approved by safety standards.

*2 Optionally available.



PR22MA11NTZF
(6-pin DIP)



PR26MF21NSZF
(8-pin DIP)

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<SIP type> (1)

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*6		Package	Absolute maximum ratings			Electrical characteristics		
			UL	CSA		ON-state current I _T (rms) (A)	Repetitive peak OFF-state voltage V _{DRM} (V)	Isolation voltage (AC) V _{iso} (rms) (kV)	Min. trigger current I _{FT} (mA) MAX.	V _D (V)	R _L (Ω)
S102T01F		100 V lines, low profile	○	○	Low profile 4-pin SIP	2		3.0	8	12	30
S108T01F		100 V lines, low profile	—	—		8*2			8	12	30
S102T02F		100 V lines, low profile (built-in zero-cross circuit)	○	○		2			8	12	30
S108T02F		100 V lines, low profile (built-in zero-cross circuit)	—	—		8*2			8	12	30
S101S05F		100 V lines	○	○	4-pin SIP	3*3	400	4.0	15	12	30
S102S01F		100 V lines	○	○		8*2			8	12	30
S112S01F		100 V lines	○	○		12*4			8	12	30
S116S01F		100 V lines	○	○		16*5			8	12	30
S101S06F		100 V lines (built-in zero-cross circuit)	○	○		3*3		3.0	15	6	30
S102S02F		100 V lines (built-in zero-cross circuit)	○	○		8*2		4.0	8	6	30
S116S02F		100 V lines (built-in zero-cross circuit)	○	○		16*5			8	6	30
S102S11F		100 V lines (built-in snubber circuit)	○	○		8*1		3.0	8	12	30
S101S16F		100 V lines (built-in snubber circuit, built-in zero-cross circuit)	○	○		3*3			15	6	30
S102S12F		100 V lines (built-in snubber circuit, built-in zero-cross circuit)	○	○		8*1		4.0	8	6	30
S202T01F		200 V lines, low profile	○	○	Low profile 4-pin SIP	2	600	3.0	8	12	30
S208T01F		200 V lines, low profile	—	—		8*2			8	12	30
S202T02F		200 V lines, low profile (built-in zero-cross circuit)	○	○		2			8	12	30
S208T02F		200 V lines, low profile (built-in zero-cross circuit)	—	—		8*2			8	12	30
S202S01F		200 V lines	○	○	4-pin SIP	8*2		4.0	8	12	30
S212S01F		200 V lines	—	—		12*4			8	12	30
S216S01F		200 V lines	—	—		16*5			8	12	30

For the notes *1 to *6, see next page.

Notice

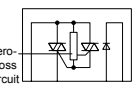
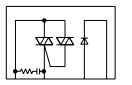
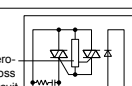
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<SIP type> (2)

○: Approved, △: Under application

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Approved by safety standards*6		Package	Absolute maximum ratings			Electrical characteristics		
			UL	CSA		ON-state current I _T (rms) (A)	Repetitive peak OFF-state voltage V _{DRM} (V)	Isolation voltage (AC) V _{iso} (rms) (kV)	Min. trigger current I _{FT} (mA) MAX.	V _D (V)	R _L (Ω)
S201S06F		200 V lines (built-in zero-cross circuit)	○	○	4-pin SIP	3*3	600	3.0	15	6	30
S202S02F		200 V lines (built-in zero-cross circuit)	○	○		8*2		4.0	8	6	30
S216S02F		200 V lines (built-in zero-cross circuit)	—	—		16*5		3.0	8	6	30
S202S15F		200 V lines (built-in snubber circuit)	—	—		8*2		4.0	15	12	30
S202S11F		200 V lines (built-in snubber circuit)	○	○		8*1		3.0	8	12	30
S202S12F		200 V lines (built-in snubber circuit, built-in zero-cross circuit)	○	○		8*1		4.0	8	6	30

*1 T_c ≤ 88°C

*2 T_c ≤ 80°C

*3 T_c ≤ 100°C

*4 T_c ≤ 70°C

*5 T_c ≤ 60°C

*6 Please refer to Specification Sheets for model numbers approved by safety standards.



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■ Photointerrupter Lineup

<Transmissive type>

Output type	Package type	Outline	Mounting method	Model No. (series)	Page
Single phototransistor	Compact	High resolution	PWB mounting type/ Soldering ref ow	GP1S296HCPSF/GP1S092HCPIF/ GP1S09xHCZ0F/GP1S19xHCZ0F/ GP1S19xHCxSF	70
High response speed	Case type	High resolution	PWB mounting type, etc.	GP1S5x series	71
		Horizontal slit, High resolution	PWB mounting type	GP1S59J0000F	71
	With connector	General purpose	Snap-in	GP1S173LCS2F/GP1S74PJ000F/ GP1S273LCS1F	71
Darlington phototransistor	Case type	General purpose	PWB mounting type, etc.	GP1L5x series	72
High sensitivity		Wide gap	PWB mounting type	GP1L57J0000F	72
Digital output	Compact	High voltage	PWB mounting type	GP1A98HCZ0F	72
(OPIC output)	Case type	High resolution	With screw hole/ PWB mounting type	GP1A5x series	73
		Wide gap	PWB mounting type	GP1A57HRJ00F	73
	With connector	General purpose	Screw mounting type/Snap-in	GP1A173LCS2F/GP1A273LCS1F/ GP1A7x series/GP1A07x series	74

<Reflective type>

Output type	Package type	Outline	Mounting method	Model No. (series)	Page
Single phototransistor	Leadless	Long focal distance	Surface-mount type	GP2S700HCP	74
High response speed	Compact, thin (leadless)	General purpose	Surface-mount type	GP2S60	74
OPIC output	With connector	Light modulation type, Sensitivity adjusted	Screw mounting type/ Compact snap-in/ Inverter light countermeasures	GP2A25 series/GP2A28 series/ GP2A200LCS0F/GP2A231LRSF/ GP2A240LCS0F/GP2A250LCS0F	75

<Application-specific photointerrupter lineup>

Detection type	Outline (Output type etc.)		Mounting method	Model No. (series)	Page
Transmissive type	Case type With encoder function Digital output (phase A/B)	Resolution: 45 LPI Linear scale slit pitch: 0.56 mm	PWB mounting type	GP1A057SGKLF	76
		Resolution: 150 LPI Linear scale slit pitch: 0.17 mm	PWB mounting type/	GP1A057RBKLF	76
Resolution: 180 LPI Linear scale slit pitch: 0.14 mm		Screw mounting type	GP1A058SCK0F	76	
Resolution: 300 LPI Linear scale slit pitch: 0.0847 mm		PWB mounting type	GP1A054RDKLF	76	
Case type With encoder function Digital output (Multiplying output)		Resolution for reading: 180 LPI Pitch: 0.14 mm Output resolution: 360 LPI	PWB mounting type	GP1A101C2KSF	76
	For amusement use		Screw mounting	GP1A204HCS0	76
Ref ective type	Injection For prism system (Single phototransistor)		Screw mounting	GP2S29SVJ00F	76
	For amusement use (Pachinko ball sensor)		—	GP2A224P0KA	77



■ Photointerrupters

<Transmissive type>

◆ Single phototransistor output

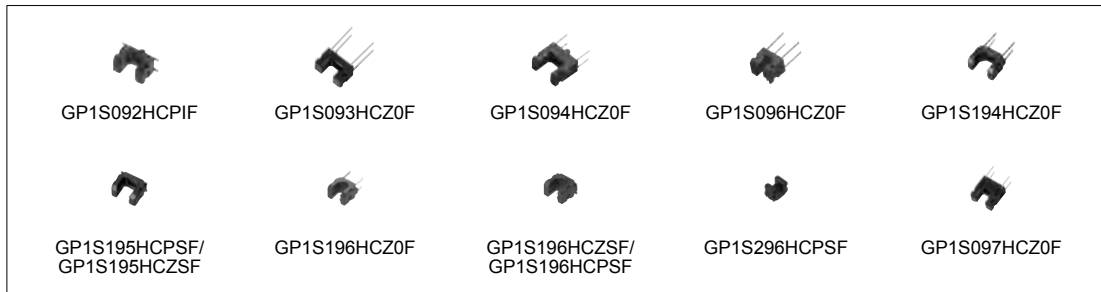
<Compact type>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics						
					Current transfer ratio			Response time			
					CTR (%) MIN.	IF (mA)	VCE (V)	tr (μs) TYP.	IC (mA)	RL (kΩ)	VCE (V)
GP1S092HCPIF		Wide gap, for soldering ref ow, surface mount compatible, with positioning boss (4.5 × 2.6 × 2.9 [height] mm)	2.0	0.3	2.0	5	5	50	0.1	1	5
GP1S093HCZ0F		Wide gap (4.5 × 2.6 × 2.9 [height] mm)	2.0	0.3	2.0	5	5	50	0.1	1	5
GP1S094HCZ0F		Wide gap, with positioning pin, (5.5 × 2.6 × 4.8 [height] mm)	3.0	0.3	0.8	5	5	50	0.1	1	5
GP1S096HCZ0F		Narrow gap (3.5 × 2.6 × 2.9 [height] mm)	1.0	0.3	2.0	5	5	50	0.1	1	5
GP1S194HCZ0F		Compact, wide gap, size: 3.6 × 2.0 × 2.7 (height) mm	1.7	0.3	3.0	5	5	50	0.1	1	5
GP1S195HCZSF GP1S195HCPSF		Compact, wide gap, surface mount compatible, size: 3.4 × 2.0 × 2.7 (height) mm	1.5	0.3	3.0	5	5	50	0.1	1	5
GP1S196HCZ0F		Compact, Low prof le (3.1 × 2.0 × 2.7 [height] mm)	1.1	0.3	2.0	5	5	50	0.1	1	5
GP1S196HCZSF GP1S196HCPSF		Surface mount, for soldering ref ow, compact, low prof le (3.1 × 2.0 × 2.7 [height] mm)	1.1	0.3	2.0	5	5	50	0.1	1	5
GP1S296HCPSF		Surface mount, for soldering ref ow, compact, Low prof le (2.5 × 1.8 × 1.9 [height] mm)	1.0	0.2	3.0	5	5	50	0.1	1	5
GP1S097HCZ0F		High resolution, wide gap, with mounting hole (4.5 × 2.6 × 4.5 [height] mm)	2.0	0.3	2.0	5	5	50	0.1	1	5

* Topr: -25 to +85 °C

** GP1SxxxHCZxF: Sleeve package, GP1SxxxHCPxF: Taped package



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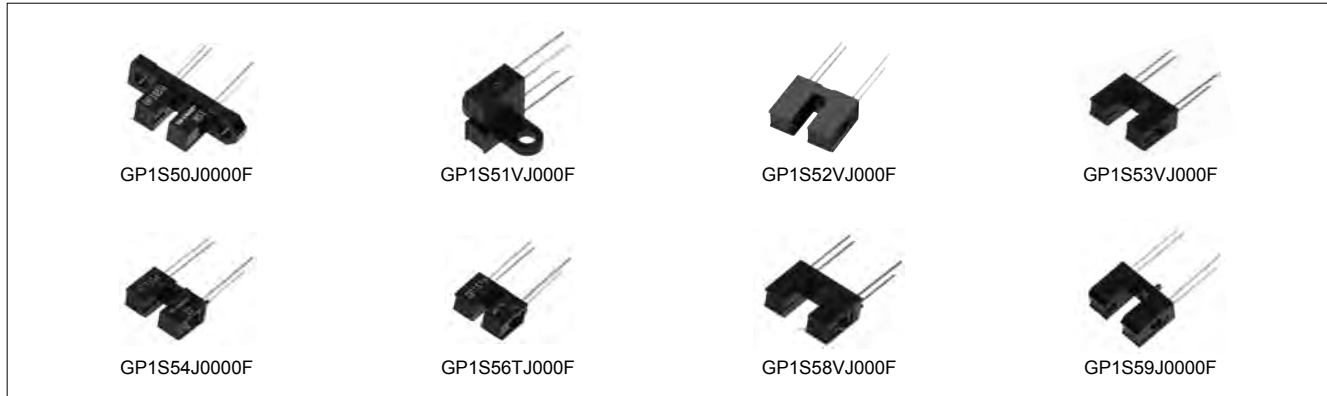
<Case type>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics						
					Current transfer ratio			Response time			
					CTR (%) MIN.	IF (mA)	VCE (V)	tr (μs) TYP.	Ic (mA)	RL (Ω)	VCE (V)
GP1S50J0000F		High resolution, both-side mounting type	3.0	0.5	2.5	20	5	3	2	100	2
GP1S51VJ000F*1		High resolution, side mounting type	3.0	0.5	2.5	20	5	3	2	100	2
GP1S52VJ000F*1		High resolution, PWB mounting type	3.0	0.5	2.5	20	5	3	2	100	2
GP1S53VJ000F		High resolution, PWB mounting type	5.0	0.5	2.5	20	5	3	2	100	2
GP1S54J0000F		High resolution, with positioning pin, PWB mounting type	3.0	0.5	2.5	20	5	3	2	100	2
GP1S56TJ000F		High resolution, with positioning pin, PWB mounting type	2.0	0.15	2.0	20	5	38	0.5	1 000	2
GP1S58VJ000F		High resolution, with positioning pin, PWB mounting type	5.0	0.5	2.5	20	5	3	2	100	2
GP1S59J0000F		High resolution, horizontal slit, with positioning pin, PWB mounting type	4.2	0.5	2.5	20	5	3	2	100	2

※ Topr: -25 to +85 °C

*1 Highly reliable types: GP1SQ51VJ00F, GP1SQ52J000F, and GP1SQ53VJ00F are also available.



<With connector>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics						
					Current transfer ratio			Response time			
					CTR (%) MIN.	IF (mA)	VCE (V)	tr (μs) TYP.	Ic (mA)	RL (Ω)	VCE (V)
GP1S74PJ000F		Snap-in mounting type with connector Applicable to 3 kinds of thickness of mounting boards	5.0	0.5	2.5	20	5	3	2	100	2
GP1S173LCS2F		Snap-in mounting integrated connector type Applicable to 3 kinds of thickness of mounting boards	5.0	0.5	2.5	20	5	3	2	100	2
☆GP1S273LCS1F		Snap-in mounting integrated connector type Applicable to 3 kinds of thickness of mounting boards Compact (Compatible with 1.5 mm pitch connector)	5.0	0.7	2.5	20	5	3	2	100	2

※ Topr: -25 to +85 °C, -30 to +95 °C (GP1S173LCS2F, GP1S273LCS1F)



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◆Darlington phototransistor output

<Case type>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics						
					Current transfer ratio			Response time			
					CTR (%) MIN.	IF (mA)	VCE (V)	tr (μs) TYP.	IC (mA)	RL (Ω)	VCE (V)
GP1L50J0000F		High sensitivity, both-side mounting type	3.0	0.5	50	1	2	80	2	100	2
GP1L51J0000F		High sensitivity, side mounting type	3.0	0.5	50	1	2	80	2	100	2
GP1L52VJ000F		High sensitivity, PWB mounting type	3.0	0.5	50	1	2	80	2	100	2
GP1L53VJ000F		High sensitivity, PWB mounting type	5.0	0.5	30	1	2	80	2	100	2
GP1L57J0000F		High sensitivity, wide gap, PWB mounting type	10.0	1.8	70	1	2	130	2	100	2

* Topr: -25 to +85 °C



GP1L50J0000F



GP1L51J0000F



GP1L52VJ000F



GP1L53VJ000F



GP1L57J0000F

◆OPIC type ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<Compact type>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics							
					Threshold input current			Propagation delay time				
					I _{FLH} (mA) MAX.	I _{FHL} (mA) MAX.	V _{CC} (V)	t _{PLH} (μs) TYP.	t _{PHL} (μs) TYP.	I _F (mA)	R _L (kΩ)	V _{CC} (V)
GP1A98HCZ0F		Compact, PWB mounting	3.2	0.5	8	—	3.3 to 24	2.0	10.0	10	3.9 to 20	3.3 to 24

* Topr = -25 to +85°C



GP1A98HCZ0F

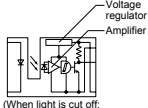
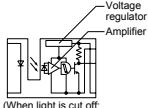
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<Case type>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics							
					Threshold input current			Propagation delay time				
					IFLH (mA) MAX.	IFHL (mA) MAX.	VCC (V)	tPLH (μs) TYP.	tPHL (μs) TYP.	IF (mA)	RL (Ω)	VCC (V)
GP1A50HRJ00F		Both-side mounting, with screw hole	3.0	0.5	5	—	5	3	5	5	280	5
GP1A51HRJ00F		Side mounting, with screw hole	3.0	0.5	5	—	5	3	5	5	280	5
GP1A52HRJ00F		PWB mounting type	3.0	0.5	5	—	5	3	5	5	280	5
GP1A53HRJ00F		PWB mounting type	5.0	0.5	8	—	5	3	5	8	280	5
GP1A57HRJ00F		PWB mounting type, with positioning pin	10.0	1.8	7	—	5	3	5	7	280	5
GP1A58HRJ00F		PWB mounting type, with positioning pin	5.0	0.5	8	—	5	3	5	8	280	5
GP1A52LRJ00F		PWB mounting type	3.0	0.5	—	5	5	5	3	5	280	5

* Topr = -25 to +85°C



GP1A50HRJ00F



GP1A51HRJ00F



GP1A52LRJ00F
(GP1A52HRJ00F)



GP1A53HRJ00F
(GP1A58HRJ00F with positioning pin)



GP1A57HRJ00F

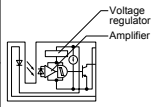
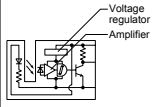
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◆OPIC type ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<With 3-pin connector terminal>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics					
					Supply voltage V _{CC} (V)		Low level output voltage			
					MIN.	MAX.	V _{OL} (V) MAX.	Light cut-off	I _{OL} (mA)	V _{CC} (V)
GP1A173LCS2F		Snap-in mounting integrated connector type*1	5.0	0.5	4.5	5.5	0.35	No	4	5
☆GP1A273LCS1F		Integrated connector, compatible with 1.5 mm pitch connector, snap-in mounting type*1	5.0	0.7	4.5	5.5	0.35	No	4	5
GP1A73AJ000F		Compact, snap-in mounting type*1	5.0	0.5	4.5	5.5	0.35	No	4	5
GP1A073LCS		Compact, snap-in mounting type*1, low voltage operation	5.0	0.5	2.7	5.5	0.35	No	4	3
GP1A75EJ000F		Either-side mounting type Screw mounting type	5.0	0.5	4.5	5.5	0.35	Yes	16	5

※ Topr: -20 to +75°C, -30 to +95 °C (GP1A173LCS2F)

*1 Applicable to 3 kinds of thickness of mounting boards.



GP1A73AJ000F,
GP1A073LCS



GP1A173LCS2F



GP1A273LCS1F



GP1A75EJ000F

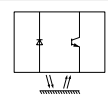
■ Photointerrupters

<Reflective type>

◆Single phototransistor output

<Compact>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Standard detecting distance (mm)	Electro-optical characteristics						
				Current transfer ratio			Response time			
				CTR (%) MIN.	I _F (mA)	V _{CE} (V)	t _r (μs) TYP.	I _C (mA)	R _L (kΩ)	V _{CE} (V)
GP2S700HCP		Compact (4 × 3 × 2 [height] mm), long focal distance, surface mounting leadless type	3	1.5	4	2	20	0.1	1	2
GP2S60		Thin (3.2 × 1.7 × 1.1 [height] mm), surface mounting leadless type	0.5	1.0	4	2	20	0.1	1	2

※ Topr: -25 to +85°C



GP2S700HCP



GP2S60

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◆OPIC output ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

<With 3-pin connector terminal>

(Ta = 25°C)

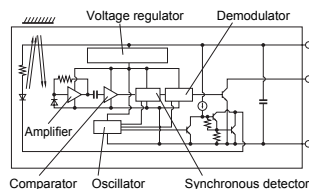
Model No.	Internal connection diagram	Features	Optimum detecting distance (mm)	Electro-optical characteristics					
				Supply voltage V _{CC} (V)		Dissipation current I _{CC} (mA) MAX.	V _{CC} (V)	Low level output voltage	
				MIN.	MAX.			V _{OL} (V) MAX.	V _{CC} (V)
GP2A200LCS0F	(Following diagram [A])	Multi types of paper detectable, light modulation type, with connector, sensitivity adjusted	5 to 15	4.75	5.25	30*1	5	0.4	5
GP2A240LCS0F		Improved light-resistance characteristic for inverter lighting, light modulation type, with connector, sensitivity adjusted	5 to 15	4.75	5.25	30*1	5	0.4	5
GP2A250LCS0F		Static electricity resistant, improved light-resistance characteristic for inverter lighting, light modulation type, with connector, sensitivity adjusted	2.5 to 12.5	4.75	5.25	30*1	5	0.4	5
GP2A25J0000F		Multi types of paper detectable, light modulation type, with connector, sensitivity adjusted	3 to 7	4.75	5.25	30*1	5	0.4	5
GP2A231LRSAF	(Following diagram [B])	Compact, hook type, multi types of paper detectable, light modulation type, with connector, sensitivity adjusted	3 to 7	4.75	5.25	20*1	5	0.4	5
GP2A25NJJ00F	(Following diagram [A])	Multi types of paper detectable, light modulation type, sensitivity adjusted, applicable to inverter fluorescent lamp, built-in visible light cut filter	3 to 7	4.75	5.25	30*1	5	0.4	5
GP2A25DJ000F		Multi types of paper detectable, light modulation type, with connector, sensitivity adjusted	3 to 7	4.75	5.25	30*1	5	0.4	5
GP2A28AJ000F		Multi types of paper detectable, light modulation type, with connector, sensitivity adjusted, hook type	3 to 7	4.75	5.25	30*1	5	0.4	5

※ Topr: -10 to +60°C (GP2A25J0000F, etc.)
-10 to +70°C (GP2A200LCS0F, GP2A240LCS0F, GP2A250LCS0F)

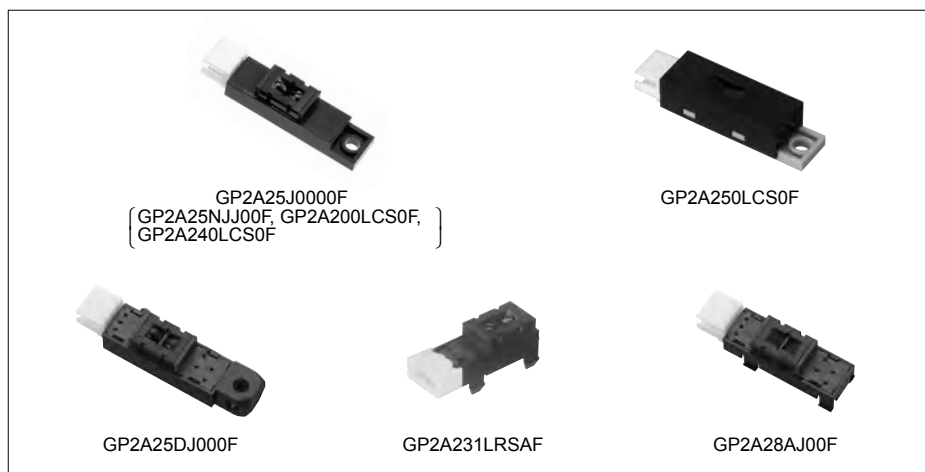
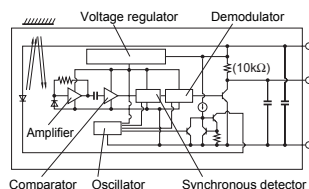
*1 Smoothing value R_L = ∞

[Internal connection diagram]

[A]



[B]



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■ Photointerrupters for Specific Applications

◆ Transmissive type

<Case type, with encoder function>

(Ta = 25°C)

Model No.	Absolute maximum ratings			Electro-optical characteristics				
	Vcc (V)	Topr (°C)	Operating voltage Vcc (V) TYP.	Output signal	Resolution	Response frequency (kHz) MAX.	If (mA)	Dissipation current (output side) Icc (mA) MAX.
GP1A057RBKLF	6	-10 to +70	3.3	Digital output (Phase A/B)	Linear scale slit pitch 0.17 (mm) (150LPI)	60	20	7
GP1A054RDKLF	6	-10 to +70	3.3		Linear scale slit pitch 0.0847 (mm) (300LPI)	40	20	5.5
GP1A057SGKLF	6	-10 to +70	3.3		Linear scale slit pitch 0.56 (mm) (45LPI)	25	20	5.5
GP1A058SCK0F	6	-10 to +70	3.3		Linear scale slit pitch 0.14 (mm) (180LPI)	40	20	5.5
GP1A101C2KSF	6.5	-10 to +70	3.3	Digital output (Multiplying output)	Resolution for reading: 180 LPI (Pitch: 0.14 mm) Output resolution: 360 LPI	120	20	20

* High precision read and low affection of angle error from vibration thanks to the multi-segment PD system.
Duty ratio: 50±15%, phase difference: 90±45°



GP1A054RDKLF



GP1A057RBKLF
(GP1A057SGKLF)



GP1A058SCK0F



GP1A101C2KSF

<For amusement use>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Detecting and emitting gap (mm)	Slit width (mm)	Electro-optical characteristics					
					Operating voltage Vcc (V)		Low level output voltage			
					MIN.	MAX.	VOL (V) MAX.	Light cut-off	IOL (mA)	VCC (V)
GP1A204HCS0		Connector with lock, screw mounting type, high resistant to noise	4.0	0.5	10.8	24	0.4	Yes	5	10.8 to 24



GP1A204HCS0

◆ Reflective type

<Case type, phototransistor output>

(Ta = 25°C)

Model No.	Internal connection diagram	Features	Electro-optical characteristics					
			Peak photocurrent			Response time		
			ICP (mA)	If (mA)	VCE (V)	tr (μs) TYP.	Ic (mA)	RL (kΩ)
GP2S29SVJ00F		Long focal distance (with prism system*1), compact, screw mounting type	0.4 to 3.0*1	20	5	38	0.5	1

* Topr: -25 to +85°C

*1 Space between prism and sensor is 8 mm.



GP2S29SVJ00F

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<For amusement use>

(Ta = 25°C)

Model No.	Features	Electro-optical characteristics		
		Supply voltage Vcc (V)	Dissipation current Icc (mA)	Response frequency f (Hz)
☆GP2A224P0KA	Reflection-type ball detection sensor, connector (2-wire output) with lock, Disconnection detection when combined with ICs*1	8 to 24	MAX. 12	MAX. 500

*1 Shared with interface IC for control (IR3N340)



■ Proximity Sensor

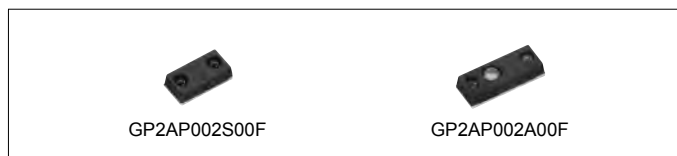
(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electro-optical characteristics				
		Vcc (V)	Topr (°C)	Dissipation current Icc (μA) TYP.	Detecting distance Lon (mm) MIN.	Non-detecting distance Loff (mm) MAX.	Maximum acceptable illuminance Ev (lx) MIN.	Peak emission wavelength λp (nm)
☆GP2AP002S00F	Compact size (4.0 × 2.0 × 1.2 t mm) Disparities in detecting distance results are greatly reduced using a built-in circuit for reduction of light-detecting sensitivity disparities Built-in LEDs for simple optical design and I ² C output	3.8	−25 to +85	240	25	150	3 000	940

■ Proximity Sensor with Integrated Ambient Light Sensor

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electro-optical characteristics							
		Vcc (V)	Topr (°C)	Dissipation current Icc (μA) TYP.	Proximity sensor portion				Ambient light sensor portion		
					Detecting distance Lon (mm) MIN.	Non-detecting distance Loff (mm) MAX.	Maximum acceptable illuminance Ev (lx) MIN.	Peak emission wavelength λp (nm)	Recommended illuminance range Ev (lx) MIN.	Peak sensitivity wavelength λp (nm)	Output current
☆GP2AP002A00F	LED and ambient light sensor combined in a single package (5.6 × 2.1 × 1.2 t mm) Disparities in detecting distance results are greatly reduced using a built-in circuit for reduction of light-detecting sensitivity disparities Built-in LEDs for simple optical design Proximity sensor: I ² C output Ambient light sensor: logarithmic current output	3.8	−25 to +85	270	25	150	3 000	940	3 to 55 000	555	30 (at Ev = 1 000 lx) 1 (at Ev = 0 lx)



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■ Ambient Light Sensors

(Ta = 25°C)

Model No.	Type	Package	Absolute maximum ratings			Electro-optical characteristics					
			V _{CC} (V)	I _O (mA)	T _{opr} (°C)	Recommended supply voltage V _{CC} (V)	Recommended illuminance range E _v (lx)	Dissipation current I _{CC} (μA) TYP.	Peak sensitivity wavelength λ _p (nm)	Output current	
										I _{O1} (μA) TYP.	I _{O2} (μA) TYP.
GA1A2S100SS	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Linear current output for illuminance Lead frame (straight) type	Transparent epoxy resin (3 × 4 mm)	7.0	5	−40 to +85	2.7 to 3.6	10 to 10 000	500	555	480 (at E _v = 1 000 lx)	48 (at E _v = 100 lx)
GA1A2S100LY	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Linear current output for illuminance Lead frame (L bend) type		7.0	5	−40 to +85	2.7 to 3.6	10 to 10 000	500	555	480 (at E _v = 1 000 lx)	48 (at E _v = 100 lx)
GA1A1S202WP	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Logarithmic current output for illuminance	Compact SMD (2.0 × 1.6 × 0.6 mm) Leadless	7.0	1	−40 to +85	2.3 to 3.2	3 to 55 000	70	555	20 (at E _v = 100 lx)	30 (at E _v = 1 000 lx)
☆GA1A1S203WP	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Logarithmic current output for illuminance Thin type	Compact SMD (2.0 × 1.6 × 0.42 mm) Leadless	7.0	1	−40 to +85	2.3 to 3.2	3 to 55 000	70	555	20 (at E _v = 100 lx)	30 (at E _v = 1 000 lx)
☆GA1A1S204WP	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Logarithmic current output for illuminance Back-mount-available type	Compact SMD (3.3 × 2.0 × 0.6 mm) Back-mount available, leadless	7.0	1	−40 to +85	2.3 to 3.2	3 to 55 000	70	555	20 (at E _v = 100 lx)	30 (at E _v = 1 000 lx)
GA1A1S100WP	Built-in amplification circuit Peak sensitivity characteristic close to human visual sensitivity Output characteristic: Linear current output for illuminance	Compact SMD (2.0 × 1.6 × 0.6 mm) Leadless	7.0	10	−40 to +85	2.7 to 3.6	10 to 5 000	1 460	555	1420 (at E _v = 1 000 lx)	142 (at E _v = 100 lx)



GA1A2S100SS



GA1A2S100LY



GA1A1S202WP
(GA1A1S100WP)



GA1A1S203WP



GA1A1S204WP

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■ OPIC Light Detectors ("OPIC" (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.)

(Ta = 25°C)

Model No.	Type	Package	Absolute maximum ratings				Electro-optical characteristics							
			V _{CC} (V)	P (mW)	I _O (mA)	T _{opr} (°C)	EV _{LH} (lx) MAX.	EV _H (lx) MAX.	V _{CC} (V)	t _{PLH} (μs) TYP.	t _{PHL} (μs) TYP.	V _{CC} (V)	E _v (lx)	R _L (Ω)
IS485E	Built-in schmidt trigger circuit, amplifier and voltage regulator	Transparent epoxy resin with condenser (lens)	-0.5 to +17	175	50	-25 to +85	—	35	5	5	3	5	50	280
IS486E			-0.5 to +17	175	50	-25 to +85	35	—	5	3	5	5	50	280



<Low-voltage operation>

(Ta = 25°C)

Model No.	Type	Package	Absolute maximum ratings			Electro-optical characteristics								
			P (mW)	I _O (mA)	T _{opr} (°C)	Operating supply voltage (V)	EvLH (lx) MAX.	EvHL (lx) MAX.	V _{CC} (V)	t _{PHL} (μs) TYP.	t _{PLH} (μs) TYP.	V _{CC} (V)	Ev (lx)	R _L (Ω)
IS489E	Built-in Schmidt trigger circuit and amplifier	Transparent epoxy resin with condenser (lens)	80	2	−25 to +85	1.4 to 7.0	—	15	3	1.3	8.5	3	125	3 000



<Model employing a light modulation system>

(Ta = 25°C)

Model No.	Type	Package	Absolute maximum ratings				Electro-optical characteristics*2						External disturbing light illuminance E _{VDX} (lx) TYP.
			V _{CC} (V)	P (mW)	I _O (mA)	T _{opr} (°C)	V _{OL} (V) MAX.	V _{OH} (V) MIN.	t _{PLH} (μs) TYP.	t _{PHL} (μs) TYP.	V _{CC} (V)	R _L (Ω)	
IS471FE*1, *3	Built-in pulse driver circuit at the emitter side, synchronous detector circuit, amplifier circuit and demodulator circuit	Visible light cut-off epoxy resin	-0.5 to +16	250	50	-25 to +60	0.35	4.97	400	400	5	280	7 000

*1 IS471FE is less susceptible to disturbing effects thanks to the light modulation system

*2 V_{CC} = 5 V

*3 Straight lead type (IS471FSE) is also available.



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<For laser beam printers (laser beam origin detection)>

(Ta = 25°C)

Model No.	Type	Package	Electro-optical characteristics			
			Recommended supply voltage V _{CC} (V)	V _{OH} (V) MIN.	V _{OL} (V) MAX.	H → L delay time variation Δt _{PHL} (ns) MAX.
GA220T2L1IZ	2-PD, differential type	Transparent epoxy resin 18-pin	4.5 to 5.5	4.9	0.6	±8.5



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■ Phototransistor Lineup

Package	Output type	Features	Half sensitivity angle	Model No.	
				Standard	Visible light cut-off
Epoxy resin with lens (ø3 mm)	Single phototransistor	General purpose	±20°	PT380	PT380F
	Darlington phototransistor	High sensitivity	±20°	PT381	PT381F
Epoxy resin with lens	Single phototransistor	General purpose/Narrow acceptance	±13°	PT480E0000F	PT480FE0000F
		Compact, thin	±35°	PT4800E0000F	PT4800FE000F / PT4850FE000F
	Darlington phototransistor	High sensitivity/Narrow acceptance	±13°	PT481E00000F	PT481FE0000F
		High sensitivity/Narrow acceptance/Long lead	±13°	—	PT483F1E000F
		High sensitivity/Compact, thin	±35°	PT4810E0000F	PT4810FJE00F
		High sensitivity/Intermediate acceptance	±40°	—	PT491FE0000F
		High sensitivity/Intermediate acceptance/Long lead	±40°	—	PT493FE0000F
Surface mounting leadless type	Single phototransistor	Compact (side view/top view mounting possible)	±15°	PT100MC0MP	PT100MF0MP
	Darlington phototransistor	Compact (side view/top view mounting possible)	±15°	—	PT100MF1MP



Phototransistors

Type	Model No.	Package	Absolute maximum ratings			Ic (mA)				ICEO(A)		$\Delta\theta$ (°) TYP.	λ_p (nm) TYP.
			VCEO (V)	Pc (mW)	Topr (°C)	MIN.	MAX.	VCE (V)	Ee (mW/cm ²)	MAX.	VCE (V)		
Single	PT380*2	ø3 epoxy resin	35	50	-25 to +85	0.16	1.17	5	Ev, 100 lx	1×10^{-7}	20	±20	800
	PT380F*1, 2		35	50	-25 to +85	0.095	0.9	5	Ev, 100 lx	1×10^{-7}	20	±20	860
	PT100MCOMP	Surface mounting leadless type with lens	35	75	-30 to +85	1.7	5.1	5	1	1×10^{-7}	20	±15	900
	PT100MF0MP*1		35	75	-30 to +85	1.15	3.45	5	1	1×10^{-7}	20	±15	910
	PT480E00000F	Epoxy resin with lens	35	75	-25 to +85	0.4	TYP. 1.7	5	1	1×10^{-7}	20	±13	800
	PT480FE0000F*1		35	75	-25 to +85	0.25	TYP. 0.8	5	1	1×10^{-7}	20	±13	860
	PT4800E0000F		35	75	-25 to +85	0.12	TYP. 0.4	5	1	1×10^{-7}	20	±35	800
	PT4800FE000F*1		35	75	-25 to +85	0.08	TYP. 0.25	5	1	1×10^{-7}	20	±35	860
	PT4850FE000F*1		35	75	-25 to +85	0.12	0.56	5	1	1×10^{-7}	20	±35	860
Darlington	PT381*2	ø3 epoxy resin	35	50	-25 to +85	0.12	1.5	10	Ev, 2 lx	1×10^{-6}	10	±20	800
	PT381F*1, 2		35	50	-25 to +85	0.07	1.08	10	Ev, 2 lx	1×10^{-6}	10	±20	860
	PT481E00000F	Epoxy resin with lens	35	75	-25 to +85	1.5	25	2	0.1	1×10^{-6}	10	±13	800
	PT481FE0000F*1		35	75	-25 to +85	0.9	27	2	0.1	1×10^{-6}	10	±13	860
	PT4810E0000F		35	75	-25 to +85	0.45	7.0	2	0.1	1×10^{-6}	10	±35	800
	PT4810FE000F*1		35	75	-25 to +85	0.27	6.0	2	0.1	1×10^{-6}	10	±35	860
	PT483F1E000F*1		35	75	-25 to +85	1.5	4.0	2	0.1	1×10^{-6}	10	±13	860
	PT491FE0000F*1		35	75	-25 to +85	0.2	0.8	2	Ev, 2 lx	1×10^{-6}	10	±40	860
	PT493FE0000F*1		35	75	-25 to +85	0.2	0.8	2	Ev, 2 lx	1×10^{-6}	10	±40	860
	PT100MF1MP*1	Surface mounting leadless type with lens	35	75	-30 to +85	0.2	1.2	5	0.01	1×10^{-6}	10	±15	860

*1 Visible light cut-off type

*2 Handled by the System Device Division III.



PT100MF0MP
(PT100MF1MP, PT100MCOMP:)
Transparent resin



PT380
(PT380F, PT381 PT381F)



PT480E00000F
(PT480FE0000F, PT481E00000F,
PT481FE0000F)



PT4800E0000F
(PT4800FE000F, PT4810E0000F,
PT4810FE000F, PT4810FJE00F,
PT4850FE000F)



PT483F1E000F



PT491FE0000F



PT493FE0000F

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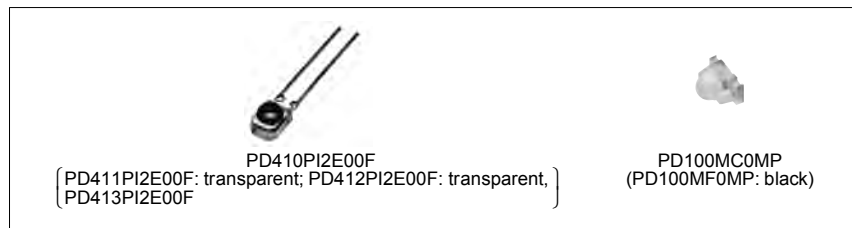


■ PIN Photodiodes

(Ta = 25°C)

Model No.	Features	Package (Material)	Active area (mm ²)	Topr (°C)	Isc (μA) MIN.	Ev (lx)	Id (A) MAX.	V _R (V)	tr, tf (μs) TYP.	V _R (V)	R _L (kΩ)	λ _p (nm) TYP.
PD410PI2E00F*1	PIN type	Visible light cut-off epoxy resin with condenser (lens)	3.31	-25 to +85	2.5	100	1 × 10 ⁻⁸	10	0.2	10	1	1 000
PD411PI2E00F		Transparent epoxy resin with condenser (lens)	3.31	-25 to +85	5.0	100	1 × 10 ⁻⁸	10	0.2	10	1	960
PD412PI2E00F		Transparent epoxy resin with condenser (lens)	3.31	-25 to +85	3.5	100	1 × 10 ⁻⁸	10	0.25	10	1	800
PD413PI2E00F*1	PIN type IrDA1.0	Visible light cut-off epoxy resin with condenser (lens)	3.31	-25 to +85	MIN. 4.5 (TYP. 5.4)	100	1 × 10 ⁻⁸	10	0.2	10	1	960
PD100MC0MP	Surface mounting leadless type	Transparent epoxy resin board with lens	—	-30 to +85	0.6	100	1 × 10 ⁻⁸	10	0.01	15	0.18	820
PD100MF0MP*1	Surface mounting leadless type	Visible light cut-off epoxy resin board with lens	—	-30 to +85	0.4	100	1 × 10 ⁻⁸	10	0.01	15	0.18	850

*1 Visible light cut-off type



■ Laser Power Monitoring Photodiodes for Optical Disc System

(Ta = 25°C)

Model No.	Features	Package (Material)	Active area (mm)	Topr (°C)	Isc (mA) TYP.	Ev (lx)	Id (A) MAX.	V _R (V)	λ _p (nm) TYP.
PD101SC0SS1F	High response speed (cut-off frequency: 400 MHz)	Transparent epoxy resin	ø0.8	-25 to +85	450	100	1 × 10 ⁻⁹	5	820
PD102TS0MP0F	High response speed (cut-off frequency: 400 MHz) For blue-violet laser diode (Light receiving sensitivity: TYP. 0.25 A/W at λ = 405 nm)	Silicon resin	ø0.7	-40 to +80	217	Ee = 54 μW/cm ²	1.5 × 10 ⁻⁹	5	760



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■ Infrared Emitting Diode Lineup

Type	Package	Features	Half intensity angle	Model No.
Single-end lead (Top view type)	Epoxy resin with lens (ø3 mm type)	General purpose	±13°	GL380
		High output type	±13°	GL381
		High speed signal transmission (12 MHz)	±17°	GL382
Single-end lead (Side view type)	Epoxy resin with lens	General purpose/Narrow beam angle	±13°	GL480E0000F
		Compact and thin	±30°	GL4800E0000F
	Flat epoxy resin	Wide beam angle	±90°	GL4100E0000F
Single-end lead (Top view type)	Epoxy resin with lens (ø5 mm type)	Low forward voltage type	±21°	GL560
		Low forward voltage type/Narrow beam angle	±13°	GL561
		High output type	±25°	GL537
		High output type/Narrow beam angle	±13°	GL538
Surface mount type	Epoxy resin with lens/ leadless (Mountable for Top view/ Side view type)	Compact/Narrow beam angle	±10°	GL100MN0MP
		High output type (Output: radiant flux/ radiant intensity indicated)	±10°/ ±9°	GL100MN1MP / GL100MN3MP
		Compact/Wide beam angle	±80°	GL100MD1MP1



■ Infrared Emitting Diodes

(Ta = 25°C)

Model No.	Package, features	Absolute maximum ratings				Radiant flux Φe (mW)			VF (V)			Δθ (°) TYP.	λp (nm) TYP.
		IF (mA)	VR (V)	P (mW)	Topr (°C)	MIN.	TYP.	IF (mA)	TYP.	MAX.	IF (mA)		
GL380*2	ø3 epoxy resin	60	6	150	-25 to +85	4.5*1	11*1	50	1.3	1.5	50	±13	950
GL381*2		60	6	150	-25 to +85	8.5*1	20*1	50	1.3	1.5	50	±13	950
GL382*2	ø3 epoxy resin, for high speed signal transmission:12 MHz	60	4	—	-25 to +85	6	18	50	1.5	1.7	50	±17	880
GL480E0000F	Epoxy resin with lens	50	6	75	-25 to +85	0.7	—	20	1.2	1.4	20	±13	950
GL4800E0000F		50	6	75	-25 to +85	0.7	1.6	20	1.2	1.4	20	±30	950
GL4100E0000F	Side-view flat type, epoxy resin	50	6	75	-25 to +85	1.0	—	20	1.2	1.4	20	±90	950
GL560*2	ø5 epoxy resin	100	6	150	-25 to +85	5*1	14*1	50	1.25	1.37	50	±21	940
GL561*2		100	6	150	-25 to +85	12*1	25*1	50	1.25	1.37	50	±13	940
GL537*2		100	6	150	-25 to +85	6*1	13*1	50	1.3	1.5	50	±25	950
GL538*2		100	6	150	-25 to +85	15*1	30*1	50	1.3	1.5	50	±13	950
GL100MN0MP	Surface mounting leadless type, epoxy resin board with lens	50	6	75	-30 to +85	1.0	3.0 (MAX.)	20	1.2	1.4	20	±10	940
GL100MN1MP	Surface mounting leadless type, epoxy resin board with lens, high output type	50	6	75	-30 to +85	2.0	6.0 (MAX.)	20	1.2	1.5	20	±10	940
GL100MN3MP	Surface mounting leadless type, epoxy resin board with lens, high output type	50	6	75	-30 to +85	3.0*1	6.0*1	20	1.25	1.5	20	±9	940
GL100MD1MP1	Surface mounting leadless type, epoxy resin board with lens, wide beam angle	50	6	75	-30 to +85	—	6.0 (MAX.)	20	—	1.5	20	±80	940

*1 Radiant intensity mW/sr

*2 Handled by the System Device Division III.



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Distance Measuring Sensor Lineup

Output	Range of distance measuring	Features	Model No.
1-bit digital output according to distance measuring	4 to 30 cm	1-bit digital output (detected distance: 15/13 cm)	GP2D150AJ00F/GP2Y0D413K0F
	10 to 80 cm	1-bit digital output (detected distance: 24 cm)	GP2Y0D21YK0F
	20 to 150 cm	1-bit digital output (detected distance: 80 cm)	GP2Y0D02YK0F
		Battery drive compatible, compact, 1-bit digital output (detected distance: 5/10 cm)	GP2Y0D805Z0F/GP2Y0D810Z0F
		Wide operating temperature type (−40 to +85°C) (detected distance: 10 cm)	GP2Y0D810Z1F
		Compact, thin 1-bit digital output (detected distance: 10/40 cm)	GP2Y0D310K/GP2Y0D340K
Analog voltage output according to distance measuring		Battery drive compatible, compact, 1-bit digital output (detected distance: 1.5 cm) Capable of operation at high temperature (−30 to +105°C)	GP2Y5D91S00F
	2 to 15 cm	Analog output	GP2Y0A51SK0F
	4 to 30 cm	Analog output	GP2D120XJ00F/GP2Y0A41SK0F
	10 to 80 cm	Analog output	GP2Y0A21YK0F
	10 to 150 cm	Compact (22 × 8 × 7.2 [T] mm), Analog output	GP2Y0A60SZ0F/GP2Y0A60SZLF
	20 to 150 cm	Analog output	GP2Y0A02YK0F
	100 to 550 cm	Analog output	GP2Y0A710K0F

Wide Angle Sensor Lineup

Output	Range of distance measuring	Detection angle of view	Model No.
Voltage output according to distance measuring	4 to 30 cm	25° (When using 5 beams)	GP2Y3A001K0F
	20 to 150 cm	25° (When using 5 beams)	GP2Y3A002K0F
	40 to 300 cm	25° (When using 5 beams)	GP2Y3A003K0F

High-Precision Displacement Sensor

Output	Range of distance measuring	Features	Model No.
Voltage output according to distance measuring	4.5 to 6.0 mm	Resolution: 50 μm	GP2Y0AH01K0F

Paper Size Sensor (Using Optical Distance Measuring Method) Lineup

Output	Features		Model No.
1-bit output	1-beam (detection height: 60 mm)	Thin type (T: 11.5 mm)	GP2Y2D160K0F
Analog output relative to measuring distance	1-beam (detection height: 80 mm)	Thin type (T: 11.5 mm)	GP2Y2A180K0F
	2-beam (detection height: 80 mm)	Thin type (T: 11.5 mm)	GP2Y2A280K0F



■ Dust Sensor Unit Lineup

Output	Features	Model No.
Analog output	Pulse analog output, single-shot detection of house dust, general purpose	GP2Y1010AU0F

■ Color Toner Concentration (Deposition Amount) Sensor Lineup

Output	Features	Model No.
Analog output	Employs diffuse ref ection system + mirror ref ection system	GP2TC2J0000F
	Employs diffuse ref ection system + mirror ref ection system	GP2Y40010K0F
	Mirror ref ection system	GP2Y40021K0F

■ Smoke Sensor Module (For Fire Alarms) Lineup

Features	Model No.
Built-in microcomputer	GP2Y6001AK0F



Distance Measuring Sensors (1)

◆Digital output

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electro-optical characteristics*1					
		Vcc (V)	Topr (°C)	Detected distance (cm)	Distance measuring range (cm)	VOH (V) MIN.	VOL (V) MAX.	Dissipation current	
GP2Y0D805Z0F	Light detector, infrared LED and signal processing circuit, short distance measuring type, battery drive compatible (operating power supply: 2.7 to 6.2 V)	−0.3 to +7	−10 to +60	5	−	Vcc −0.6	0.6	MAX. 6.5	MAX. 8
GP2Y0D810Z0F	Light detector, infrared LED and signal processing circuit, short distance measuring type, battery drive compatible (operating power supply: 2.7 to 6.2 V)	−0.3 to +7	−10 to +60	10	−	Vcc −0.6	0.6	MAX. 6.5	MAX. 8
GP2Y0D810Z1F	Light detector, infrared LED and signal processing circuit, short distance measuring type, battery drive compatible (operating power supply: 2.7 to 6.2 V)	−0.3 to +7	−40 to +85	10	−	Vcc −0.6	0.6	TYP. 5	MAX. 8
GP2Y5D91S00F	Light detector, infrared LED and signal processing circuit, short distance measuring type, battery drive compatible (operating power supply: 2.7 to 6.2 V), capable of operation at high temperature	−0.3 to +7	−30 to +105	1.5	−	Vcc −0.6	0.6	TYP. 7	−
GP2Y0D310K	Digital voltage output according to the measured distance of GP2Y0D340K	−0.3 to +7	−10 to +60	10	−	Vcc −0.3	0.6	MAX. 35	−
GP2Y0D340K	Compact, thin type (15 x 9.6 x 8.7 mm: sensor part), Light detector, infrared LED and signal processing circuit, digital voltage output according to the measured distance	−0.3 to +7	−10 to +60	40	−	Vcc −0.3	0.6	MAX. 35	−
GP2Y0D21YK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, digital voltage output	−0.3 to +7	−10 to +60	24	10 to 80	Vcc −0.3	0.6	MAX. 40	−
GP2D150AJ00F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, digital voltage output	−0.3 to +7	−10 to +60	15	4 to 30	Vcc −0.3	0.6	MAX. 50	−
GP2Y0D413K0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, digital voltage output	−0.3 to +7	−10 to +60	13	4 to 30	Vcc −0.3	0.6	−	−
GP2Y0D02YK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, long distance measuring type (No external control signal required), digital voltage output according to the measured distance	−0.3 to +7	−10 to +60	80	20 to 150	Vcc −0.3	0.6	MAX. 50	−

*1 Vcc = 5 V

* PSD: Position Sensitive Detector

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Distance Measuring Sensors (2)

◆Analog output

(Ta = 25°C)

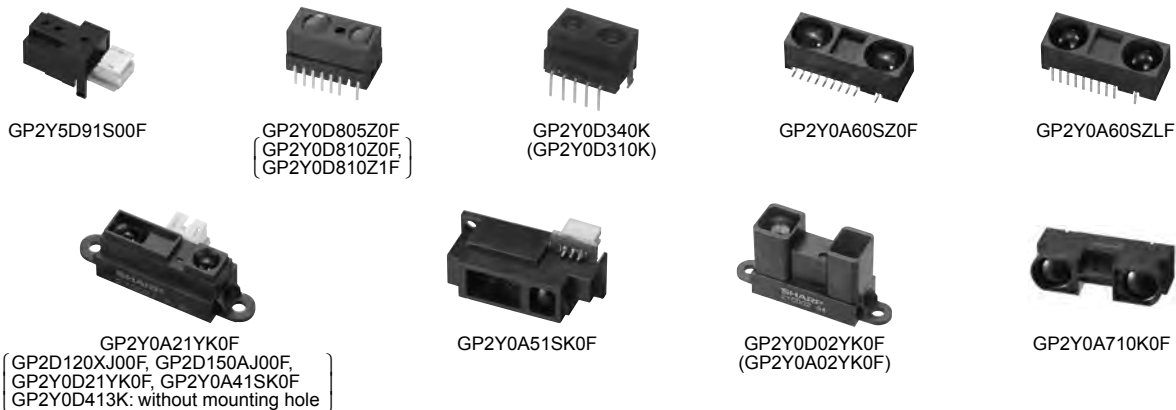
Model No.	Features	Absolute maximum ratings		Electro-optical characteristics*1			
		Vcc (V)	Topr (°C)	Distance measuring range (cm)	VoH (V) MIN.	VoL (V) MAX.	Dissipation current Operating (mA)
GP2Y0A21YK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, linear voltage output	-0.3 to +7	-10 to +60	10 to 80	Vo (TYP.) = 0.4 V (at L = 80 cm), ΔVo (TYP.) = 1.9 V (at L: 80 cm → 10 cm)		MAX. 40
GP2D120XJ00F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, linear voltage output	-0.3 to +7	-10 to +60	4 to 30	Vo (TYP.) = 0.4 V (at L = 30 cm), ΔVo (TYP.) = 2.25 V (at L = 30 cm → 4 cm)		MAX. 50
GP2Y0A41SK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, short measuring cycle (16.5 ms)	-0.3 to +7	-10 to +60	4 to 30	Vo (TYP.) = 0.4 V (at L = 30 cm), ΔVo (TYP.) = 2.25 V (at L = 30 cm → 4 cm)		MAX. 22
☆GP2Y0A51SK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, short measuring cycle (16.5 ms)	-0.3 to +7	-10 to +60	2 to 15	Vo (TYP.) = 0.4 V (at L = 15 cm), ΔVo (TYP.) = 2.25 V (at L = 15 cm → 2 cm)		TYP. 12
GP2Y0A60SZ0F/ GP2Y0A60SZLF	*2 Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, compact type (22 x 8 x 7.2 mm), long distance measuring type (No external control signal required)	-0.3 to +5.5	-10 to +60	10 to 150	Vo (TYP.) = 0.65 V (at L = 150 cm), ΔVo (TYP.) = 3.0 V (at L = 150 cm → 20 cm)	*3	MAX. 50
GP2Y0A02YK0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, long distance measuring type (No external control signal required)	-0.3 to +7	-10 to +60	20 to 150	Vo (TYP.) = 0.4 V (at L = 150 cm), ΔVo (TYP.) = 2.05 V (at L = 150 cm → 20 cm)		MAX. 50
GP2Y0A710K0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, long distance measuring type (No external control signal required)	-0.3 to +7	-10 to +60	100 to 550	Vo (TYP.) = 2.5 V (at L = 100 cm), ΔVo (TYP.) = 0.7 V (at L = 100 cm → 200 cm)		TYP. 30

*1 Vcc = 5 V

*2 GP2Y0A60SZ0F: Surface mount type
GP2Y0A60SZLF: Board insertion type

*3 When Vcc = 3 V: Vo (TYP.) = 0.35 V (at L = 150 cm); ΔVo (TYP.) = 1.6 V (at L = 150 cm → 20 cm)

* PSD: Position Sensitive Detector



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Wide Angle Sensors

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electro-optical characteristics				
		Vcc (V)	Topr (°C)	Distance measuring range (cm)	Output terminal voltage (V)	Output voltage difference (V)	Input voltage (V)	
GP2Y3A001K0F	Distance measuring sensor united with PSD*, infrared LED and signal processing circuit, distance measuring sensor application product, wide range (field of view) detection using 5 infrared beams	-0.3 to +7	-10 to +60	4 to 30	TYP. 2.85*1	TYP. 1.6*4	MIN. 4.5	MAX. 0.5
GP2Y3A002K0F		-0.3 to +7	-10 to +60	20 to 150	TYP. 2.3*2	TYP. 1.6*5	MIN. 4.5	MAX. 0.5
GP2Y3A003K0F		-0.3 to +7	-10 to +60	40 to 300	TYP. 2.3*3	TYP. 1.2*6	MIN. 4.5	MAX. 0.5

* PSD: Position Sensitive Detector

Reflector used: White paper (Gray chart R-27/white surface, made by Kodak Corp., reflectance 90%)

L = Reflector - Sensor distance

*1 L = 4 cm

*4 Change in output voltage from L = 4 cm to 10 cm

*2 L = 20 cm

*5 Change in output voltage from L = 20 cm to 80 cm

*3 L = 40 cm

*6 Change in output voltage from L = 40 cm to 100 cm



Paper Size Sensors

(Ta = 25°C)

Model No.	Features	Operating temperature	Supply voltage	Paper detection height	LED beam pitch	Approved value of paper position sliding	Paper detection density	Dissipation current
		Topr (°C)	Vcc (V)	H (mm)	Lp (mm)	Δx (mm)	OD	Icc (mA)
GP2Y2D160K0F	Thin type (T: 11.5 mm), using optical distance measuring method (1-beam), digital output (1-bit)	-10 to +65	5 $\pm$ 0.5	TYP. 60	-	MIN. $\pm$ 7.5	0.7 or less*1	MAX. 40
GP2Y2A180K0F	Thin type (T: 11.5 mm), analog output using optical distance measuring method (1-beam)	-10 to +65	5 $\pm$ 0.5	TYP. 80	-	-	-	MAX. 25
GP2Y2A280K0F	Thin type (T: 11.5 mm), analog output using optical distance measuring method (2-beam)	-10 to +65	5 $\pm$ 0.5	TYP. 80	TYP. 21	-	-	MAX. 50

* This table shows the characteristics when configured in the paper size sensor system.

*1 Reflectivity: 18% or more, OD = log (1/T), T: Reflectivity



High-Precision Displacement Sensor

(Ta = 25°C)

Model No.	Features	Topr (°C)	Operating supply voltage (V)	Dissipation current (mA)	Distance measuring range (mm)	Distance characteristic of output
GP2Y0AH01K0F	Resolution: 50 μ m	-10 to +60	4.5 to 5.5	TYP. 20	4.5 to 6.0	TYP. 1.70 V Variation in output over range (4.5 to 6.0 mm)



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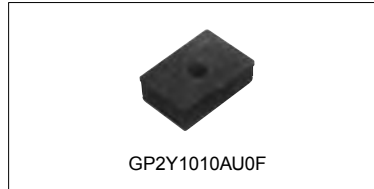
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■ Dust Sensor Unit

(Ta = 25°C)

Model No.	Features	Topr (°C)	Electro-optical characteristics				
			Operating supply voltage (V)	Dissipation current (mA)	Detection sensitivity V/(0.1 mg/m ³)	Output voltage at no dust Voc (V)	Output voltage range Voh (V)
GP2Y1010AU0F	Built-in infrared emitting diode, photodiode and signal processing circuit, compact, single-shot detection of house dust	−10 to +65	4.5 to 5.5	TYP. 11	TYP. 0.5	TYP. 0.9	MIN. 3.4



■ Smoke Sensor Module (For Fire Alarms)

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings		Electro-optical characteristics	
		Topr (°C)	Supply voltage (V)	Average dissipation current (μA)	Output voltage when no smoke (V)
GP2Y6001AK0F	- Thin, compact module integrating sensors and microcomputer - Low dissipation current - Can be made to order with custom functions.	−10 to +50	−0.3 to +3.8	TYP. 16	TYP. 1.25

* Please consult with Sharp if you select this product.

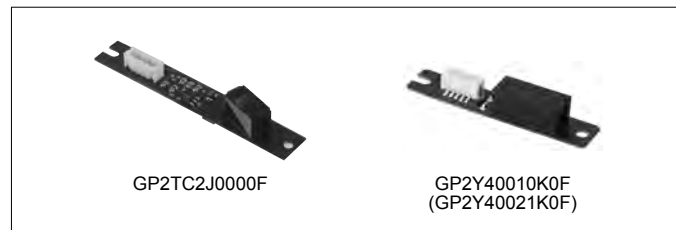
■ Color Toner Concentration (Deposition Amount) Sensors

(Ta = 25°C)

Model No.	Features	Topr (°C)	Electro-optical characteristics		
			Dissipation current*1 (mA)	Output voltage*2 V01 (V)	Output voltage*2 V02 (V)
GP2TC2J0000F	Employs diffuse ref ection system + mirror ref ection system, high-precision detection of toner concentration on photo-sensitive drum, 2-line analog output (2-PD)	0 to +60	TYP. 4	TYP. 1.17	TYP. 2.81
GP2Y40010K0F	Employs diffuse ref ection system + mirror ref ection system, high-precision detection of toner concentration on transfer belt, 2-line analog output (2-PD)	0 to +60	TYP. 4	TYP. 1.27	MAX. 3.5 TYP. 2.87
GP2Y40021K0F	Mirror ref ection system, high-precision detection of toner concentration on transfer belt, 1-line analog output (1-PD)	0 to +60	TYP. 4	—	TYP. 2.81

*1 Dissipation current with LED current of IFM = 0 mA

*2 With reflection object A (Reflectance: 15.6%)



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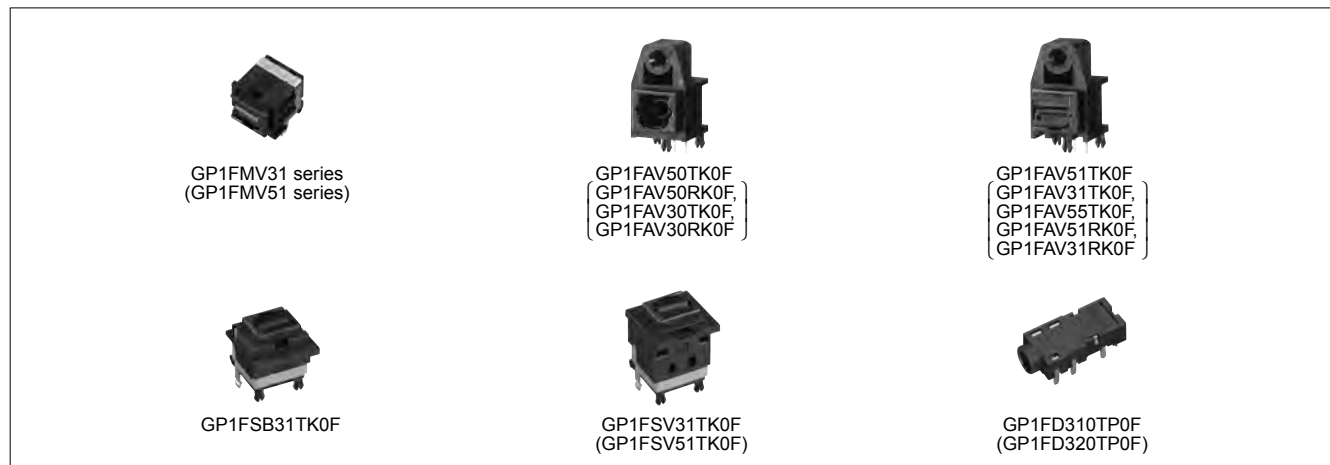


■ Fiber Optics Lineup for Audio Equipment

Connector type	Type	Outline	Features	High speed signal transmission	Model No.	
					Supply voltage 3 to 5 V	Supply voltage 5 V
Square connector (EIAJ RC-5720B)	Fiber optic transmitter	Without mounting hole	With shutter	Horizontal mounting type	MAX. 13.2 Mb/s	GP1FMV51TK0F
					MAX. 15.5 Mb/s	GP1FMV31TK0F
		With mounting hole	With shutter	Horizontal mounting type	MAX. 13.2 Mb/s	GP1FAV51TK0F*1
					MAX. 15.5 Mb/s	GP1FAV31TK0F
					MAX. 50 Mb/s	GP1FAV55TK0F
					MAX. 13.2 Mb/s	GP1FSV51TK0F
			With protection cap	Horizontal mounting type	GP1FSV31TK0F (mounting height: 15 mm) GP1FSB31TK0F (mounting height: 8.5 mm)	
					MAX. 15.5 Mb/s	
					MAX. 13.2 Mb/s	GP1FAV50TK0F*1
					MAX. 15.5 Mb/s	GP1FAV30TK0F
	Fiber optic receiver	Without mounting hole	With shutter	Horizontal mounting type	MAX. 13.2 Mb/s	GP1FMV51RK0F
					MAX. 15.5 Mb/s	GP1FMV31RK0F
		With mounting hole	With shutter	Horizontal mounting type	MAX. 13.2 Mb/s	GP1FAV51RK0F
					MAX. 15.5 Mb/s	GP1FAV31RK0F
			With protection cap	Horizontal mounting type	MAX. 13.2 Mb/s	GP1FAV50RK0F
					MAX. 15.5 Mb/s	GP1FAV30RK0F

*1 TTL drive compatible

Connector type	Type	Outline	Features	High speed signal transmission	Model No.
					Supply voltage 3 V
Optical mini-jack ø3.5 mm (JIS C 6650)	Fiber optic transmitter	Thin type (t: 4.2 mm)	Capable of detection/transmission of optical/electrical signals	MAX. 8 Mb/s	GP1FD310TP0F
				MAX. 25 Mb/s	GP1FD320TP0F





■ Fiber Optic Transmitters (Square Connector)

(Ta = 25°C)

Model No.	Appearance		Features	Absolute maximum ratings		Electro-optical characteristics					
	Mounting hole	Shutter		Vcc (V)	Topr (°C)	Supply voltage (V)	Propagation delay time		Dissipation current Icc (mA) MAX.	Pulse width distortion Δtw (ns)	Transmission speed T (Mb/s) MAX.
							tPLH (ns) MAX.	tPHL (ns) MAX.			
GP1FMV31TK0F	No	Yes	Compact	−0.5 to +7	−20 to +70	2.7 to 5.25	180	180	12	±15	15.5
GP1FMV51TK0F	No	Yes	Compact	−0.5 to +7	−20 to +70	4.75 to 5.25	180	180	13	±15	13.2
GP1FAV30TK0F	Yes	No	Low voltage drive, with protection cap	−0.5 to +7	−20 to +70	2.7 to 5.25	180	180	12	±15	15.5
GP1FAV50TK0F	Yes	No	TTL drive compatible, with protection cap	−0.5 to +7	−20 to +70	4.75 to 5.25 Input voltage: MIN. 2.0 V	180	180	13	±15	13.2
GP1FAV51TK0F	Yes	Yes	TTL drive compatible	−0.5 to +7	−20 to +70	4.75 to 5.25	180	180	13	±15	13.2
GP1FSV51TK0F	No	Yes	Vertical mounting (mounting height: 15 mm), low voltage drive	−0.5 to +7	−20 to +70	4.75 to 5.25	180	180	13	±15	13.2
GP1FAV31TK0F	Yes	Yes	Low voltage drive	−0.5 to +7	−20 to +70	2.7 to 5.25	180	180	12	±15	15.5
GP1FSV31TK0F	No	Yes	Vertical mounting (mounting height: 15 mm), low voltage drive	−0.5 to +7	−20 to +70	2.7 to 5.25	180	180	13	±15	15.5
GP1FAV55TK0F	Yes	Yes	High response speed	−0.5 to +7	−20 to +70	4.75 to 5.25	180	180	13	±15	50
GP1FSB31TK0F	No	Yes	Vertical mounting (mounting height: 8.5 mm)	−0.5 to +7	−20 to +70	2.7 to 5.25	180	180	13	±15	15.5

■ Fiber Optic Transmitters (ø3.5 mm Optical Mini-jack)

(Ta = 25°C)

Model No.	Features	Absolute maximum ratings			Electro-optical characteristics					
		Vcc (V)	Vin (V)	Topr (°C)	Supply voltage (V)	Propagation delay time		Dissipation current Icc (mA) MAX.	Pulse width distortion Δtw (ns)	Transmission speed T (Mb/s) MAX.
						tpLH (ns) MAX.	tpHL (ns) MAX.			
GP1FD310TP0F	Compact, thin type (t: 4.2 mm), optical mini-jack (low voltage type)	-0.5 to +7	-0.5 to Vcc + 0.5	-20 to +70	2.7 to 3.6	180	180	12	±30	8
GP1FD320TP0F	Compact, thin type (t: 4.2 mm), high speed, optical mini-jack (low voltage type)	-0.5 to +7	-0.5 to Vcc + 0.5	-20 to +70	2.3 to 5.5	180	180	12	±11	25

■ Fiber Optic Receivers (Square Connector)

(Ta = 25°C)

Model No.	Appearance		Features	Absolute maximum ratings			Electro-optical characteristics					
	Mounting hole	Shutter		Vcc (V)	IOL (mA)	Topr (°C)	Supply voltage (V)	Propagation delay time		Dissipation current Icc (mA) MAX.	Pulse width distortion Δtw (ns)	Transmission speed T (Mb/s) MAX.
								tPLH (ns) MAX.	tPHL (ns) MAX.			
GP1FMV31RK0F	No	Yes	Compact, low voltage drive	−0.5 to +7	10	−20 to +70	2.7 to 3.6	180	180	15	±20	15.5
GP1FMV51RK0F	No	Yes	Compact	−0.5 to +7	10	−20 to +70	4.75 to 5.25	180	180	25	±20	13.2
GP1FAV30RK0F	Yes	No	Low voltage drive, with protection cap	−0.5 to +7	10	−20 to +70	2.7 to 3.6	180	180	15	±20	15.5
GP1FAV50RK0F	Yes	No	With protection cap	−0.5 to +7	10	−20 to +70	4.75 to 5.25	180	180	25	±20	13.2
GP1FAV51RK0F	Yes	Yes		−0.5 to +7	10	−20 to +70	4.75 to 5.25	180	180	25	±20	13.2
GP1FAV31RK0F	Yes	Yes	Low voltage drive	−0.5 to +7	10	−20 to +70	2.7 to 3.6	180	180	15	±20	15.5

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High-Luminosity (AlGaInP) LED Lamps

(If = 20 mA, Ta = 25°C)

Appearance	Radiation shape (mm)	Resin type				High-luminosity									
						JE (Yellow-green)		JV, ZV (Amber)		JS, ZS (Sunset orange)		ZJ, JJ (Orange)		ZR, JR (Red)	
		Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion	Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.
Cylinder	ø3			●		—	—	GL3ZV402B0SE	400	GL3ZS402B0SE	400	GL3ZJ402B0SE	400	GL3ZR402B0SE	250
				●		GL3JE402B0SE	200	—	—	—	—	—	GL3JR402B0S3	200	
				●		—	—	GL3ZV802B0SE	200	GL3ZS802B0SE	210	GL3ZJ802B0SE	230	GL3ZR802B0SE	150
		●				—	—	GL3JV404B0SE	280	GL3JS404B0SE	280	GL3JJ404B0SE	200	—	—
		●				—	—	GL3JV804B0SE	110	GL3JS804B0SE	120	GL3JJ804B0SE	100	—	—
	ø5			●		—	—	GL5ZV152B0SE	2 700	GL5ZS152B0SE	3 000	GL5ZJ152B0SE	3 000	GL5ZR152B0SE	2 000
				●		—	—	GL5ZV302B0SE	900	GL5ZS302B0SE	1 000	GL5ZJ302B0SE	900	GL5ZR302B0SE	600
				●		—	—	GL5JV302B0SE	640	GL5JS302B0SE	680	GL5JJ302B0SE	570	—	—
				●		—	—	GL0ZV042B0S	16 900	GL0ZS042B0S	22 600	GL0ZJ042B0S	18 500	—	—
	ø10			●		—	—	GL6ZV27	750	GL6ZS27	850	GL6ZJ27	750	GL6ZR27	360
Oval	Long: 5.8 Short: 4.6			●		—	—	GL5JV7D2D0SE	210	GL5JS7D2D0SE	230	GL5JJ7D2D0SE	190	—	—

Taped model is also available.

High-Luminosity LED Lamps

(If = 20 mA, Ta = 25°C)

Appearance	Radiation shape (mm)	Resin type				High-luminosity					
		Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion	BC (Blue)		GC (Green)		UR, U (Red)	
						Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.	Model No.	Luminous intensity (mcd) TYP.
Cylinder	ø3	●				-	-	-	-	GL3UR401E0S	250
				●		-	-	-	-	GL3UR402E0S	300
			●			-	-	-	-	GL3UR804E0S	150
				●		GL3BC302B0S2	900	-	-	GL3UR404E0S	250
				●		GL3B2402B0SC	650	GL3G2402B0SC	2 800	-	-
	ø5			●		-	-	-	-	GL5UR44	850
			●			-	-	-	-	GL5UR2K	2 000
Oval	Long: 5.8 Short: 4.6			●		-	-	-	-	GL5UR2K1	2 000
			●			-	-	-	-	GL6UR26T*1	400
Rectangle	2.5 × 5.0	●				-	-	-	-	GL8UR21	16

*1 With tie-bar

Taped model is also available.

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Cylinder



GL3ZS802B0S series

GL3JV404B0SE series
GL3BC302B0S2
GL3UR404E0SGL5ZV152B0SE series
GL5ZV302B0SE series
GL5JV302B0SE seriesGL6ZV27 series
GL5JV7D2D0SE seriesGL3ZV402B0SE series
GL3JE402B0SE series
GL3UR402E0S
GL3BV2402B0SC series

GL0ZV042B0S series

GL5UR44
GL5UR2K

GL5UR2K1



GL3UR401E0S

GL3JV804B0SE series
GL3UR804E0S

Oval



GL6UR26T

Rectangle



GL8UR21

■ Dichromatic LED Lamps

(I_F = 20 mA, T_a = 25°C)

Appearance	Radiation shape (mm)	Resin type				Yellow-green + Red	Luminous intensity (mcd) TYP.
		Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion		
Cylinder	ø3				●	GL3ED8	20/15
	ø5				●	GL5ED5	40/25
				●		GL5ED44	80/50
Rectangle	2.0 × 5.0				●	GL9ED2	8/3
	5.0 × 5.0				●	GL9ED4	7/4

(The values in luminous intensity are in radiation color order.)



GL3ED8



GL5ED5



GL5ED44



GL9ED2



GL9ED4

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LED Lamps

(I_F = 20 mA, T_a = 25°C)

Appearance	Radiation shape (mm)	Resin type				JG Green		EG Yellow-green		HY Yellow		HS Sunset orange		HD Red	
		Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion	(564 nm)	Luminous intensity (mcd) TYP.	(565 nm)	Luminous intensity (mcd) TYP.	(585 nm)	Luminous intensity (mcd) TYP.	(610 nm)	Luminous intensity (mcd) TYP.	(635 nm)	Luminous intensity (mcd) TYP.
Cylinder	ø3	●				GL3JG401E0S	80	GL3EG401E0S	80	GL3HY401E0S	60	GL3HS401E0S	60	GL3HD401E0S	60
			●			GL3JG402E0S	85	GL3EG402E0S	85	GL3HY402E0S	70	GL3HS402E0S	70	GL3HD402E0S	70
		●				GL3JG804E0S	40	GL3EG804E0S	40	GL3HY804E0S	30	GL3HS804E0S	30	GL3HD804E0S	30
		●				GL3JG404E0S	80	GL3EG404E0S	80	GL3HY404E0S	60	GL3HS404E0S	60	GL3HD404E0S	60
	ø4	●				GL4JG8	85	GL4EG8	100	GL4HY8	110	GL4HS8	80	GL4HD8	110
		●				GL5JG8	140	GL5EG8	150	GL5HY8	120	GL5HS8	80	GL5HD8	80
	ø5	●				GL5JG41	160	GL5EG41	160	GL5HY41	100	GL5HS41	100	GL5HD41	150
		●				GL5JG44	160	GL5EG44	160	GL5HY44	100	GL5HS44	100	GL5HD44	100
		●				—	—	GL5EG40	250	GL5HY40	250	GL5HS40	200	GL5HD40	250
		●				GL5JG43	360	GL5EG43	300	GL5HY43	250	GL5HS43	250	GL5HD43	300
		●				—	—	GL6EG26T ^{*1}	140	—	—	—	—	—	—
Oval	Long: 5.8 Short: 4.6	●				—	—	GL6EG26T ^{*1}	140	—	—	—	—	—	—
Rect-angle	2.0 × 4.5	●				—	—	GL8EG23	6	GL8HY23	8	—	—	GL8HD23	6
	2.0 × 5.0	●				GL8JG21	7	GL8EG21	8	GL8HY21	8	GL8HS21	8	GL8HD21	8
Square	5.0 × 5.0	●				GL8JG22	8	GL8EG22	6	GL8HY22	5	GL8HS22	5	GL8HD22	8

*1 With tie-bar

Taped model is also available.

Cylinder



Oval



Rectangle



Square



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■ High-Luminosity (AlGaInP) Surface Mount LEDs (Taped Models Only)

(I_F = 20 mA, T_a = 25°C*³)

Outline dimensions (mm)	Resin type				JE		ZVJV		ZSJS		ZJJJ		ZRJR	
	Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion	Yellow-green	Luminous intensity (mcd) TYP.	Amber	Luminous intensity (mcd) TYP.	Sunset orange	Luminous intensity (mcd) TYP.	Orange	Luminous intensity (mcd) TYP.	Red	Luminous intensity (mcd) TYP.
1.6 × 0.8 (t = 0.35)			●		GM1JE35200AE* ¹	13	GM1JV35200AE* ¹	18.8	GM1JS35200AE* ¹	19	GM1JJ35200AE* ¹	19	GM1JR35200AE* ¹	13
3.2 × 2.8 (t = 1.9)			●		—	—	GM5ZV96270A	600	—	—	—	—	GM5ZR96270A	600
6.0 × 5.0 (t = 2.5)			●		—	—	GM5ZV01200A* ²	500	GM5ZS01200A* ²	700	GM5ZJ01200A* ²	500	GM5ZR01200A* ²	400
6.0 × 5.0 (t = 2.3) (board insertion type)			●		—	—	GM5ZV03200Z* ²	500	GM5ZS03200Z* ²	700	GM5ZJ03200Z* ²	500	GM5ZR03200Z* ²	400

*¹ GM1JV35200AE series: I_F = 5 mA*² GM5ZR01200A series, GM5ZR03200Z series: I_F = 60 mA*³ GM5ZV96270A series, GM5ZV01200A series, GM5ZV03200Z series: T_c = 25°C■ High-Luminosity (InGaN) Surface Mount LEDs
(Taped Models Only)(I_F = 10 mA, T_a = 25°C*⁴)

Outline dimensions (mm)	Resin type					BC		GC	
	Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion		Blue	Luminous intensity (mcd) TYP.	Green	Luminous intensity (mcd) TYP.
1.6 × 0.8 (t = 0.35)				●		GM1BC35372AC* ¹	35	GM1GC35370AC* ¹	80
3.2 × 2.8 (t = 1.9)			●			GM5BC96270A* ²	500	GM5GC96270A* ²	1 300
6.0 × 5.0 (t = 2.5)			●			GM5BC01250AC* ³	400	GM5GC01250AC* ³	1 200
6.0 × 5.0 (t = 2.3) (board insertion type)			●			GM5BC03210Z* ³	400	GM5GC03210Z* ³	1 200

*¹ GM1BC35372AC series: I_F = 5 mA*² GM5BC96270A series: I_F = 20 mA*³ GM5BC01250AC series, GM5BC03210Z series: I_F = 50 mA*⁴ GM5BC96270A series, GM5BC01250AC series, GM5BC03210Z series: T_c = 25°C

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■ Surface Mount LEDs (Taped Models Only)

(If = 20 mA, Ta = 25°C)

Outline dimensions (mm)	Resin type				EG		HY		HS		HD	
	Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion	Yellow-green	Luminous intensity (mcd) TYP.	Yellow	Luminous intensity (mcd) TYP.	Sunset orange	Luminous intensity (mcd) TYP.	Red	Luminous intensity (mcd) TYP.
1.6 × 0.8 (t = 0.55)			●		GM1EG55200A	19	GM1HY55200A	11.5	GM1HS55200A	11.4	GM1HD55200A	12.5



GM1EG55200A series



GM1JV35200AE series
GM1BC35372AC
GM1GC35370AC



GM5ZV96270A series
GM5BC96270A series



GM5ZR01200A series
GM5BC01250AC series



GM5ZV03200Z series
GM5BC03210Z series



Taped model

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High-Luminosity White Surface Mount LEDs (Taped Models Only)

(Ta = 25°C*5)

Outline dimensions (mm)	Color coordinates (x, y) TYP.	BW	White		BN	High rendering color	
			Luminous intensity (mcd) TYP.	Color temperature (K) TYP.		Luminous intensity (mcd) TYP.	Color temperature (K) TYP.
1.6 × 0.8 (t = 0.2)	(0.27, 0.23)	GM1BW20300A*1	50	—	—	—	—
2.8 × 1.2 (t = 0.8) Side view type	(0.30, 0.29)	GM4BW853A0A*1	1 900	—	—	—	—
		GM4BW853B0A*1	2 200	—	—	—	—
3.85 × 1.0 (t = 0.6) Side view type	(0.30, 0.29)	GM4BW653A0A*1	1 900	—	—	—	—
		GM4BW653B0A*1	2 200	—	—	—	—
	(0.29, 0.28)	—	—	—	GM4BN653C0A*1,4	1 700	—
3.85 × 1.0 (t = 0.5) Side view type	(0.30, 0.29)	GM4BW53340A*1	1 800	—	—	—	—
3.2 × 2.8 (t = 1.9)	(0.31, 0.31)	☆GM5BW96381A*1	2 250	—	—	—	—
	(0.338, 0.365)	☆GM5BW97330A*2	6 400	5 300	—	—	—
	(0.312, 0.311)	☆GM5BW97332A*2	5 800	6 700	—	—	—
	(0.283, 0.262)	☆GM5BW97333A*2	5 100	11 500	—	—	—
	(0.3398, 0.3472)	—	—	—	☆GM5BN97330A*2,4	6 000	5 200
3.2 × 2.8 (t = 1.4)	(0.32, 0.33)	☆GM5BW94370A*3	5 200	—	—	—	—

*1 GM1BW20300A, GM4BW853A0A series, GM4BW653A0A series, GM4BN653C0A, GM4BW53340A, GM5BW96381A: If = 20 mA

*2 GM5BW97330A series, GM5BN97330A: If = 20 mA/chip

*3 GM5BW94370A: If = 25 mA/chip

*4 GM4BN653C0A and GM5BN97330A are high-NTSC-ratio products.

*5 GM5BW96381A, GM5BW97330A series, GM5BW94370A, GM5BN97330A: Tc = 25°C



GM1BW20300A



GM5BW96381A

GM5BW97330A series
GM5BN97330A

GM4BW853A0A series



GM4BW53340A

GM4BW653A0A series
GM4BN653C0A

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High-Luminosity Surface Mount LEDs (RGB 3-color) (Taped Models Only)

(Ta = 25°C*5)

Outline dimensions (mm)	Resin type				WA Red + Green + Blue	Luminous intensity (mcd) TYP.
	Colored diffusion	Colored transparency	Colorless transparency	Milky diffusion		
1.6 × 1.6 (t = 0.55)				●	GM1WA55311A*2	20/70/23
3.2 × 2.8 (t = 1.4)				●	GM5WA94310A*3	1 800 [Mixed color]
5.0 × 2.5 (t = 2.5)				●	GM4WA25300A*4	(2 200) [Mixed color]
6.0 × 5.0 (t = 2.5) 6-terminal leadless				●	☆GM5WA06310A*1	(3 500) [Mixed color]

*1 GM5WA06310A: If = 35 mA (Red), If = 40 mA (Green), If = 10 mA (Blue)

*2 GM1WA55311A: If = 5 mA (Red, Green, Blue)

*3 GM5WA94310A: If = 20 mA (Red), If = 20 mA (Green), If = 7 mA (Blue)

*4 GM4WA25300A: If = 21 mA (Red), If = 25 mA (Green), If = 7 mA (Blue)

*5 GM1WA55311A, GM5WA94310A, GM4WA25300A: Tc = 25°C



GM1WA55311A



GM5WA06310A



GM5WA94310A



GM4WA25300A

ZENIGATA LEDs for Lighting

<3.6W>

(If = 360 mA, Tc = 25°C)

Outline dimensions (mm)	Model No.	Color coordinates (x, y) TYP.	Color temperature (K) TYP.	Total luminous flux (lm) TYP.	Average color rendering index Ra TYP.
18.0 × 18.0 (t = 2.0)	☆GW5BQC15L02	(0.458, 0.410)	(2 725)	(160)	(85)
	GW5BDC15L02	(0.45, 0.41)	2 800	200	70
	☆GW5BTC15L02	(0.434, 0.403)	(3 045)	(190)	(85)
	☆GW5BRC15L02	(0.382, 0.380)	(3 985)	(180)	(94)
	GW5BWC15L02	(0.35, 0.36)	5 000	280	60
	GW5BNC15L02	(0.35, 0.35)	5 000	190	90
	GW5BNC15L12	(0.31, 0.32)	6 500	190	90

<6.7W>

(If = 640 mA, Tc = 25°C)

Outline dimensions (mm)	Model No.	Color coordinates (x, y) TYP.	Color temperature (K) TYP.	Total luminous flux (lm) TYP.	Average color rendering index Ra TYP.
18.0 × 18.0 (t = 2.0)	☆GW5BQF15L0B	(0.458, 0.410)	(2 725)	(300)	(85)
	GW5BDF15L00	(0.45, 0.41)	2 800	400	70
	☆GW5BTF15L0B	(0.434, 0.403)	(3 045)	(360)	(85)
	☆GW5BRF15L0B	(0.382, 0.380)	(3 985)	(340)	(94)
	GW5BWF15L00	(0.35, 0.36)	5 000	540	60
	GW5BNF15L00	(0.35, 0.35)	5 000	350	90
	GW5BNF15L10	(0.31, 0.32)	6 500	350	90

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☆New product
★Under development



■ Surface Mount LEDs for Lighting (Taped Models Only)

(I_F = 20 mA, T_c = 25°C)

Outline dimensions (mm)	Model No.	Color coordinates (x, y) TYP.	Color temperature (K) TYP.	Luminous intensity (mcd) TYP.	Average color rendering index Ra TYP.
3.2 × 2.8 (t = 1.9)	GM5BW96382A	(0.31, 0.31)	6 800	2 300	—
	GM5BW96385A	(0.34, 0.36)	5 200	2 300	—
	GM5BW96387A	(0.29, 0.28)	11 500	2 000	—
	☆GM5SAE27P0A	(0.4578, 0.4101)	(2 700)	(2 000)	(85)
	☆GM5SAE30P0A	(0.4338, 0.4030)	(3 000)	(1 900)	(85)
	☆GM5SAE35P0A	(0.4073, 0.3917)	(3 500)	(2 100)	(83)
	☆GM5SAE40P0A	(0.3818, 0.3797)	(4 000)	(2 100)	(83)
	☆GM5SAE45P0A	(0.3611, 0.3658)	(4 500)	(2 200)	(83)
	☆GM5SAE50P0A	(0.3447, 0.3553)	(5 000)	(2 200)	(83)
	☆GM5SAE57P0A	(0.3287, 0.3417)	(5 700)	(2 200)	(80)
	☆GM5SAE65P0A	(0.3123, 0.3282)	(6 500)	(2 200)	(80)
	GM5BN96385A	(0.34, 0.35)	(5 200)	1 500	(90)

■ Surface Mount LEDs for Lighting (RGB 3-color)

(I_F = 20 mA/chip, T_c = 25°C)

Outline dimensions (mm)	Model No.	Radiation color	Luminous intensity (mcd) TYP.
3.2 × 2.8 (t = 1.4)	★GM5WA94315A	Red	(680)
		Green	(1 500)
		Blue	(450)



GW5BWC15L02 series
GW5BWF15L00 series



GM5BW96382A series
GM5SAE27P0A series
GM5BN96385A



GM5WA94315A

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☆New product
★Under development



■ Laser Diodes

◆ Model Configurations

• For applications other than optical discs

Wavelength (nm)	Absolute maximum ratings (mW)*1	Package	
		 ø5.6 mm Metal type	 ø3.3 mm Metal type
660 band	10	—	GH06510F4A
785 band	10	GH07810C2K	—
	25	GH07825C2K	—

*1 The absolute maximum ratings are the limits that are not to be exceeded under any condition whatsoever, whether in testing or in actual use.

• For optical disc use*3

Wavelength (nm)	Absolute maximum ratings (mW)*1	Package		
		 ø5.6 mm Metal type	 ø3.3 mm Metal type	 1.8 mm t Resin type
405 band	20	GH04020A2G	GH04020A4G	—
	210*2	GH04P21A2G	—	—
	250*2	☆GH04P25A2G	☆GH04P25A4G	—
660 band	240*2	GH06P24A2C	—	GH16P24A8C
	350*2	—	—	GH16P35A8C
	400*2	—	—	☆GH16P40A8C
785 band	240*2	GH07P24C1C	GH07P24C4C	—
	280*2	★GH07P28F1C	★GH07P28F4C	—

*1 The absolute maximum ratings are the limits that are not to be exceeded under any condition whatsoever, whether in testing or in actual use.

*2 Optical power output MAX. (mW)

*3 New models for optical disc use are introduced frequently, and it is possible the model you wish to order may no longer be in production. Sample sales may not be available, either. We ask for your understanding in this matter.

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Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

☆New product
★Under development



◆ Specifications

• Laser diodes lineup for applications other than optical discs

(T_c = 25°C)

Model No.	Wave-length (nm)	Absolute maximum ratings*1	Features	Applications	Terminal connections
		CW (Continuous wave)			
GH06510F4A	660 band	10	ø3.3 mm CAN package, operating temperature: 70°C MAX., with built-in monitor PD	Bar code reader, laser displacement gauge, etc.	A
GH07810C2K	785 band	10	ø5.6 mm CAN package, operating temperature: 60°C MAX., with built-in monitor PD	Printer, copier, complex machine	D
GH07825C2K		25	ø5.6 mm CAN package, operating temperature: 60°C MAX., with built-in monitor PD	Printer, copier, complex machine	

• Laser diodes lineup for optical disc use*2

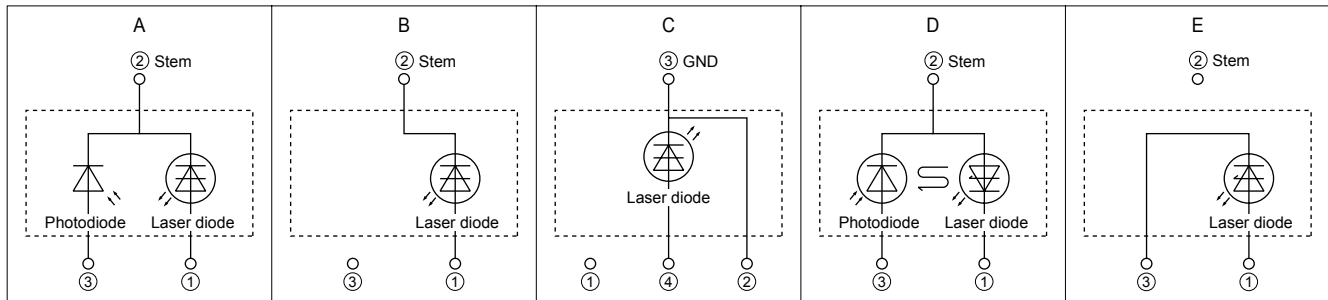
(T_c = 25°C)

Model No.	Wave-length (nm)	Absolute maximum ratings*1		Features	Applications	Terminal connections
		CW (Continuous wave)	Pulse			
GH04020A2G	405 band	20	—	ø5.6 mm CAN package, operating temperature: 70°C MAX.	Blu-ray disc playback	E
GH04020A4G		20	—	ø3.3 mm CAN package, operating temperature: 70°C MAX.	Blu-ray disc playback	E
GH04P21A2G		105	210	ø5.6 mm CAN package, operating temperature: 70°C MAX. (pulse drive)	Blu-ray disc recording	E
☆GH04P25A2G		125	250	ø5.6 mm CAN package, operating temperature: 80°C MAX. (pulse drive)	Blu-ray disc recording	E
☆GH04P25A4G		125	250	ø3.3 mm CAN package, operating temperature: 80°C MAX. (pulse drive)	Blu-ray disc recording	E
GH06P24A2C	660 band	100	240	ø5.6 mm CAN package, operating temperature: 75°C MAX. (pulse drive)	Double-layer DVD 4× writing	B
GH16P24A8C		100	240	1.8 mm frame package, operating temperature: 80°C MAX. (pulse drive)	Double-layer DVD 4× writing	C
GH16P35A8C		125	350	1.8 mm frame package, operating temperature: 80°C MAX. (pulse drive)	Double-layer DVD 8× to 16× recording	
☆GH16P40A8C		135	400	1.8 mm frame package, operating temperature: 80°C MAX. (pulse drive)	Double-layer DVD 8× to 16× recording	
GH07P24C1C	785 band	120	240	ø5.6 mm CAN package, operating temperature: 75°C MAX. (pulse drive)	CD-R/RW (MAX. 48× to 52× writing)	B
★GH07P28F1C		150	280	ø5.6 mm CAN package, operating temperature: 80°C MAX. (pulse drive)	CD-R/RW (MAX. 48× to 52× writing)	
GH07P24C4C		120	240	ø3.3 mm CAN package, operating temperature: 75°C MAX. (pulse drive)	CD-R/RW (H/H, slim dual-purpose) (MAX. 48× to 52× writing)	
★GH07P28F4C		150	280	ø3.3 mm CAN package, operating temperature: 80°C MAX. (pulse drive)	CD-R/RW (H/H, slim dual-purpose) (MAX. 48× to 52× writing)	

*1 The absolute maximum ratings are the limits that are not to be exceeded under any condition whatsoever, whether in testing or in actual use. For recommended optical power output, consult the specification sheet or data sheet for each model.

*2 New models for optical disc use are introduced frequently, and it is possible the model you wish to order may no longer be in production. Sample sales may not be available, either. We ask for your understanding in this matter.

• Terminal Connections



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■ Europe: LNBs for Satellite Broadcast

◆ Features

- (1) Wide band type receiving all broadcasting channels (analog & digital) in Europe. [Universal LNB]
- (2) Originally developed feed-horn waveguide makes the wide-band, low-noise characteristics possible.
- (3) One of the industry's most compact and lightweight package
- (4) Low dissipation current design for energy saving [80 mA (TYP.): BS1K0EL100A]

◆ Specifications

Destination	Europe, Astra/Eutelsat Satellite etc.			
Receiving polarization	Horizontal/Vertical polarization			
Model No. <Type>	BS1R8EL500A <4 output>	BS1R8EL400A <4 output>	BS1R8EL200A <2 output>	BS1K0EL100A <1 output>
Input frequency (GHz)	10.7 to 11.7 [Low band], 11.7 to 12.75 [High band]			
Output frequency (MHz)	950 to 1 950 [Low band], 1 100 to 2 150 [High band]			
Local oscillation frequency (GHz)	9.75 [Low band], 10.6 [High band]			
NF (dB)	0.7 (TYP.)			0.4 (TYP.)
Conversion gain (dB)	56 (TYP.)			58 (TYP.)
Phase noise	-55 dBc/Hz at 1 kHz (TYP.)			
Cross-polar discrimination (dB)	25 (TYP.)			
Supply voltage (V DC) (Polarization switching)	Vertical polarization	11.5 to 14.0 (0/22 kHz)		
	Horizontal polarization	16.0 to 19.0 (0/22 kHz)		
Dissipation current (mA)	210 (TYP.)/250 (MAX.)	310 (TYP.)/350 (MAX.)	190 (TYP.)/250 (MAX.)	80 (TYP.)/120 (MAX.)
Waveguide	Feed-horn (F/D = 0.6)			
Output impedance (Ω)	75			
Output connector (F-type)	4-output (H/H, H/L, V/H, V/L)	4-output (H/V, High and low switching)	2-output (H/V, High and low switching)	1-output (H/V, High and low switching)
Outline dimensions (W) × (D) × (H) (mm)	133.0 × 103.6 × 60.0	133.0 × 103.6 × 60.0	123.5 × 97.0 × 60.0	103.0 × 60.0 × 60.0
Weight (g)	Approx. 255	Approx. 256	Approx. 215	Approx. 90



BS1R8EL500A



BS1R8EL400A



BS1R8EL200A



BS1K0EL100A

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Japan/Asia/Australia: LNBs for CS Digital Satellite Broadcast

◆ Specifications

Destination	Japan, Asia, Australia, CS Satellite	
Receiving polarization	Horizontal/Vertical polarization	
Model No. <Type>	BS1R8AR100A	
Input frequency (GHz)	11.70 to 12.75	
Output frequency (MHz)	1 000 to 2 050	
Local oscillation frequency (GHz)	10.7	
NF (dB)	0.7 (TYP.) / 0.9 (MAX.)	
Conversion gain (dB)	55 to 64	
Phase noise	-75 dBc/Hz at 1 kHz (TYP.)	
Cross-polar discrimination (dB)	25 (TYP.)	
Supply voltage (V DC) (Polarization switching)	Vertical polarization	11.5 to 14.0
	Horizontal polarization	16.0 to 19.0
Dissipation current (mA)	80 (TYP.)/120 (MAX.)	
Waveguide	Feed-horn (F/D = 0.6)	
Output impedance (Ω)	75	
Output connector (F-type)	1-output (H/V switching)	
Outline dimensions (mm)	107.3 (W) × 60 (D) × 60 (H)	
Weight (g)	Approx. 110	



BS1R8AR100A

Japan: LNBs for BS/CS 110° Satellite Broadcast

◆ Features

- (1) Can receive 2 satellite broadcasts of 110° BS/CS digital
[Employs wide-band (1 GHz) circular' linear polarization conversion technology (septum waveguide structure)]
- (2) Outstanding noise figure (NF) characteristics enabling compact design of antenna diameter. [NF: 0.45 dB (TYP.)/BS1F6JU300A]
- (3) Low dissipation current design for improved energy saving. [80 mA (TYP.)]

◆ Standard Specifications

Destination	Japan BS/CS 110° Satellite		
Receiving polarization	Right circular polarization		Right/Left circular polarization
Model No.	BS1F6JU300A	BS1F6JP300A	BS1F6JP100A
Input frequency (GHz)	11.71023 to 12.751		
Output frequency (MHz)	1 032.23 to 2 073		
Local oscillation frequency (GHz)	10.678		
NF (dB)	0.45 (TYP.) / 0.6 (MAX.)	0.7 (TYP.) / 1.1 (MAX.)	
Conversion gain (dB)	48 to 60		
Phase noise	−65 dBc/Hz at 1 kHz (TYP.)		
Cross-polar discrimination (dB)	25 (TYP.)/20 (MIN.)		
Supply voltage (V DC) (Polarization switching)	Right circular polarization	9.5 to 18.0	13.5 to 16.5
	Left circular polarization	—	9.5 to 12.0
Dissipation current (mA)	80 (TYP.)/110 (MAX.)		
Waveguide	Feed-horn (F/D = 0.5)		
Output impedance (Ω)	75		
Output connector (F-type)	1-output		1-output (R/L switching)
Outline dimensions (mm)	96 (W) × 53.07 (D) × 71 (H)		
Weight (g)	Approx. 130 (not including outer cabinet)		



BS1F6JP300A

* Outer cabinet is made upon request.

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■ Digital DBS Front-End Units

◆ Features

- (1) Equipped with a direct conversion IC developed by Sharp. Reliability is improved by reducing power consumption and component counts.
- (2) Wide-band reception design also covering CS broadcast band. [Reception frequency: 950 to 2 150 MHz]
- (3) Wide product line-up of LINK integrated types for contributing to set development time reduction.
[Compatible with DVB-S/DVB-S2/ISDB-S/ABS-S demodulation]
- (4) User support tools can be provided. [Sample/evaluation boards and software are available.]

◆ Standard Specifications <I/Q output type>

Destination	Global (DVB-S)	Global (ISDB-S/DVB-S2/ABS-S)	
Input type	1-input/1-loop through output		1-input
Model No.	BS2S7HZ0502	BS2S7HZ7306A	BS2S7HZ6701
Input frequency (MHz)	950 to 2 150		
Input signal level (dBm)	-65 to -25		
The 1st intermediate frequency (MHz)	Zero-IF (Direct conversion)		
Base band frequency bandwidth (MHz)	10 to 30, 2.0 MHz step (BB LPF)		
RF input local leak (dBm)	-70 and below		
Output type	I/Q		
Channel selection system	PLL (I ² C-bus)*1		
Noise figure (dB)	7 (TYP.)		
Tuning voltage (V DC)	Shared with a 3.3 V power source		
Supply voltage (V DC)	3.3		
LNB power supply	DC 25 V, 400 mA (MAX.)		
Input impedance (Ω)	75		
Outline dimensions (mm)	29.6 (W) × 29.4 (D) × 13.0 (H)		30.6 (W) × 25.0 (D) × 13.0 (H)

* Contact SHARP for custom design product.

*1 I²C-bus is a trademark of Philips Corporation.



BS2S7HZ0502/
BS2S7HZ7306A



BS2S7HZ6701

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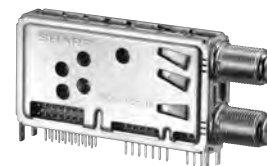
■ Digital DBS Front-End Unit

◆ Standard Specifications <NIM type>

Destination	Global (DVB-S)
Input type	1-input, 1-loop through output
Model No.	BS2F7VZ7395
Input frequency (MHz)	950 to 2 150
Input signal level (dB m)	−65 to −25
The 1st intermediate frequency (MHz)	Zero-IF (Direct conversion)
Base band frequency bandwidth (MHz)	10 to 30, 2.0 MHz step (BB LPF)
RF input local leak (dB m)	−70 and below
Output type	Transport stream (parallel/serial)
Symbol rate (M baud)	45 (MAX.)
Channel selection system	PLL (I ² C-bus)*1
Noise figure (dB)	7 (TYP.)
Tuning voltage (V DC)	Shared with a 3.3 V power source
Supply voltage (V DC)	3.3, 2.5
LNB power supply	25 V DC, 400 mA (MAX.)
Input impedance (Ω)	75
Outline dimensions (mm)	57.5 (W) × 29.6 (D) × 13.2 (H)

※ Contact SHARP for custom design product.

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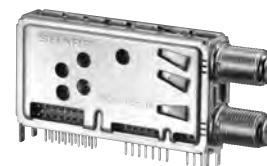
BS2F7VZ7395

◆ Standard Specifications <NIM type>

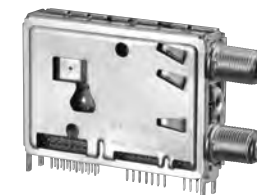
Destination	Europe (DVB-S2)	
Input type	1-input, 1-loop through output	
Model No.	BS2F7VZ7700	BS2F7VZ0169
Input frequency (MHz)	950 to 2 150	
Input signal level (dB m)	−65 to −25	
The 1st intermediate frequency (MHz)	Zero-IF (Direct conversion)	
Base band frequency bandwidth (MHz)	10 to 30, 2.0 MHz step (BB LPF)	10 to 30
RF input local leak (dB m)	−70 and below	
Output type	Transport stream (parallel/serial)	
Symbol rate (M baud)	45 (MAX.)	10 to 30
Channel selection system	PLL (I ² C-bus)*1	
Noise figure (dB)	7 (TYP.)	
Tuning voltage (V DC)	Shared with a 3.3 V power source	
Supply voltage (V DC)	3.3, 1.2	3.3, 1.0
LNB power supply	25 V DC, 400 mA (MAX.)	
Input impedance (Ω)	75	
Outline dimensions (mm)	57.5 (W) × 29.6 (D) × 13.2 (H)	55.1 (W) × 37.9 (D) × 13.2 (H)

※ Contact SHARP for custom design product.

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BS2F7VZ7700



BS2F7VZ0169

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■ Combination Front-End Units for Digital Terrestrial, Analog Terrestrial and Digital Satellite Broadcasting

◆ Features

- (1) Enables simultaneous reception of digital terrestrial and digital satellite broadcasting.
- (2) Contributes to making LCD TVs and other devices thinner.

◆ Standard Specifications

Destination	Japan (ISDB-T/S/NTSC)		
Model No.	VA1R5JF7012		
	Digital terrestrial	Analog terrestrial	Digital DBS
Input frequency (MHz)	VHF, UHF, CATV (pass-through) VHF Low: 93 to 167 VHF High: 173 to 399 UHF: 405 to 767		950 to 2 150
Input signal level*1 (dBm)	-75 to -20	-	-65 to -25
Output type	Transport stream (Serial)	CVBS/SIF	Transport stream (Serial)
IF bandwidth (MHz)	6		-
Base band frequency bandwidth (MHz)	-		10 to 30, 2.0 MHz step (BB LPF)
Noise figure (dB)	6 (TYP.)		6 (TYP.)
Phase noise (dBc/Hz)	-90 (TYP.) at 10 kHz offset		-80 (TYP.) at 10 kHz offset
Image rejection (dB)	-65 (TYP.)		-
Channel selection system	PLL (I ² C-bus)*2		
Supply voltage (V DC)	1.2, 2.5, 3.3, 5.0		
Outline dimensions (mm)	85.5 (W) × 45.2 (D) × 12.7 (H)		

*1 It conforms to the ARIB standard.

*2 I²C-bus is a trademark of Philips Corporation.



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■ Front-End Units for ISDB-T/DVB-T/CTTB/CATV

◆ Features

- (1) Low phase noise characteristics, high elimination of adjacent channel interference.
- (2) Transport stream output front-end units with built-in OFDM demodulation IC.
- (3) Compact, low power consumption.
- (4) Other types are available with various forms of chassis (vertical or horizontal type) and input connectors (F or DIN type), etc.

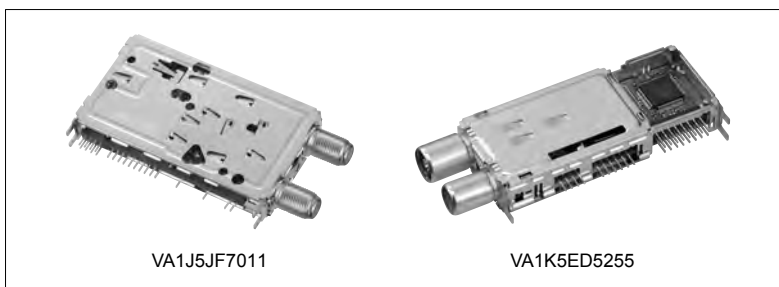
◆ Standard Specifications

Destination	Japan (ISDB-T/S)		Europe (DVB-T)/Asia (DVB-T)	
Model No.	VA1J5JF7011*1		VA1T1ED5065	VA1K5ED5255
	Digital terrestrial	Digital satellite		
Input frequency (MHz)	VHF, UHF, CATV (pass-through) VHF Low: 93 to 167 VHF High: 173 to 399 UHF: 405 to 767	950 to 2 150	VHF: 143.5 to 430 UHF: 430 to 862	VHF: 146 to 430 UHF: 430 to 862
Output type	Transport stream (Serial)		Direct IF	Transport stream (Serial)
IF bandwidth (MHz)	6	—	7, 8, selectable	8
Noise figure (dB)	6 (TYP.)	8 (TYP.)	6 (TYP.)	
Phase noise (dBc/Hz)	−90 (TYP.) at 10 kHz offset	−80 (TYP.) at 10 kHz offset	−90 (TYP.) at 10 kHz offset	
Image rejection (dB)	−65 (TYP.)	—	−55 (TYP.)	—
Channel selection system	PLL (I ² C-bus)*2			
Power consumption (W)	2.0*3		0.75	1.33
Supply voltage (V DC)	1.2, 2.5, 3.3, 5		5 (DC-DC converter)	5, 3.3, 1.8 (DC-DC converter)
Outline dimensions (mm)	70.0 (W) x 40.0 (D) x 12.7 (H)		52.0 (W) x 35.9 (D) x 13.4 (H)	70.0 (W) x 29.6 (D) x 13.2 (H)

*1 Enables simultaneous reception of digital terrestrial and digital satellite broadcasting.

*2 I²C-bus is a trademark of Philips Corporation.

*3 During simultaneous OFDM/8PSK demodulation operation.



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◆ Standard Specifications

Destination	Brazil (SBTVD-T)	China (CTTB)	Europe/China/India (DVB-C)
Model No.	VA1J5BF6009	VA1T1EF2096	VA1K5CD5405
	Digital terrestrial	Digital terrestrial	CATV
Input frequency (MHz)	54 to 864	47 to 862	
Output type	Transport stream (Serial)	Direct IF	Transport stream (Parallel/serial)
IF frequency/IF bandwidth (MHz)	44/6	36/8	
Noise figure (dB)	6 (TYP.)		
Phase noise (dBc/Hz)	−90 (TYP.) at 10 kHz offset	−87 (TYP.) at 10 kHz offset	
Image rejection (dB)	−65 (TYP.)	−55 (TYP.)	
Channel selection system	PLL (I ² C-bus)*1		
Power consumption (W)	2.0	0.75	1.3
Supply voltage (V DC)	1.2, 2.5, 3.3, 5	5	2.5, 3.3, 5
Outline dimensions (mm)	70.0 (W) x 37.0 (D) x 12.5 (H)	68.2 (W) x 35.9 (D) x 14.1 (H)	70.0 (W) x 29.4 (D) x 13.0 (H)

*1 I²C-bus is a trademark of Philips Corporation.



VA1J5BF6009



VA1T1EF2096

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■ Front-End Units for Digital Terrestrial and Analog Terrestrial Broadcasting

◆ Features

Contributing to the development of thinner LCD TVs and similar products by combining compatibility with digital and analog terrestrial broadcasts into a single unit.

◆ Standard Specifications

Destination		North America	Europe	Brazil*2	China/Asia
Model No.		VA1Y2UF2446	VA1E2ED2001	VA1G5BF8015	VA1E2CD2001
Input frequency (MHz)		Low: 54 to 160.9 Mid: 161 to 425.9 High: 426 to 864	VHF: 47 to 430 UHF: 430 to 862	VHF Low: 54 to 160.9 VHF High: 161 to 425.9 UHF: 426 to 864	47 to 870
Analog intermediate frequency (MHz)	Video	45.75	B/G, I, D/K, L: 38.9 L': 33.9	45.75	38.0
	Audio	41.25	D/K, L: 32.4 I: 32.9 B/G: 33.4 L': 40.4	41.25	D/K: 31.5, I: 32.0, B/G: 32.5, M/N: 33.5
Digital intermediate frequency (MHz)		44	36.167	44	36
Digital IF bandwidth (MHz)		6	7/8 (switchable)	6	8
Phase noise (dBc/Hz)		−85 (TYP.) at 20 kHz offset	−85 (TYP.) at 10 kHz offset	−90 (TYP.) at 10 kHz offset	−85 (TYP.) at 10 kHz offset
Supply voltage (V DC)		5.0	5.0	1.2, 2.5, 3.3, 5	5.0
Noise figure (dB)		TYP. 6 (54 to 806 MHz), TYP. 7 (806 to 861 MHz)	TYP. 6		
Channel selection system		PLL (I ² C-bus)*1			
Image rejection (dB)		Low: −65.0, Mid: −65.0, High: −60.0	TYP. −65		
Outline dimensions (W) × (D) × (H) (mm)		52.6 × 38.1 × 10.0	53.9 × 28.9 × 9.5	70.0 × 37.0 × 10.0	53.9 × 28.9 × 9.5

*1 I²C-bus is a trademark of Philips Corporation.

*2 Transport stream output front-end units with built-in OFDM demodulation IC



VA1Y2UF2446



VA1E2ED2001



VA1G5BF8015

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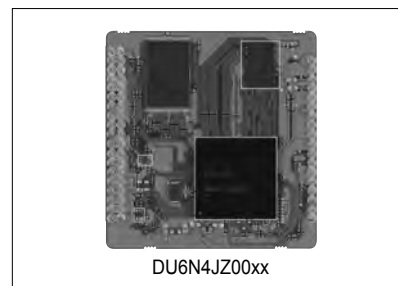
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RF-separation Type Digital Terrestrial Compound Receiver Module

◆ Features

- (1) An OFDM demodulator, MPEG decoder and video encoder circuit are combined into a single package for reception of ISDB-T.
- (2) Comes with built-in standard reception software, with a simple EPG included, based on the ARIB standard.
Compatible with Ministry of Internal Affairs and Communications specifications for a “simple tuner.”
- (3) The tuner (RF) section is separate, making it possible to select between digital/analog and digital tuners.

Recommended tuner { Digital terrestrial: VA1T1JF2031
Analog terrestrial/Digital terrestrial: VA1W2JF2008



DU6N4JZ00xx

◆ Standard Specifications

Model No.	DU6N4JZ00xx
Circuit configuration	[RF (separate body) +] OFDM + MPEG
Receiving channel (ch)	[VHF] 1 to 13, [UHF] 14 to 62, [CATV] C13 to C63*1
Video output	Component (Full HD)*2
Audio output	Analog stereo (L/R)
B-CAS	Built-in control software
EPG	Built-in simple EPG
ES (Engineering service)	○
Firmware upgrades	○
Supply voltage (V)	3.3/1.8/1.0
Power consumption (W)	Approx. 1.1
Outline dimensions (mm)	58 (W) × 60 (D) × 7 (H)

*1 CATV (pass-through)

*2 Composite video/YC (SD) output is also supported.

One-Seg Tuner Module

◆ Features

- (1) High sensitivity: -109 dBm [TYP.] (QPSK, CR1/2 ch13)
- (2) Compact and thin design: 5.9 × 5.9 × 1.05 mm
- (3) Low power consumption: 80 mW
- (4) Output interface: TS serial output



VA3A5JZ922

◆ Standard Specifications

Destination	Japan
Model No.	VA3A5JZ922
Input frequency (MHz)	470 to 770 (UHF: 13 to 62)
Input signal level (dBm)	-109 [TYP.] (QPSK, CR1/2, ch13)
Outline dimensions (mm)	5.9 (W) × 5.9 (D) × 1.05 (H)
Supply voltage (V DC)	1.8 (RF) 2.8 (RF OSC) 1.2 (OFDM Core) 1.7 to 2.8 (I/O)
Power consumption (mW)	80
Operating temperature (degree C)	-20 to 85
Control I/F	I ² C-bus*1

*1 I²C-bus is a trademark of Philips Corporation.

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■ One-Seg Tuner Module for Simultaneous 2-program Reception

◆ Features

- (1) Capable of receiving two one-seg programs simultaneously
- (2) Compatible with diversity reception for stable, high-sensitivity reception (with single-program reception)
- (3) Compact package size (9.0 × 9.0 × 1.25 mm)



VA3A5JZ923

◆ Standard Specifications

Destination	Japan
Model No.	VA3A5JZ923
Output type	Transport stream
Reception frequency range (MHz)	470 to 770 (UHF: 13 to 62 ch)
OFDM demodulation	Built in
Input sensitivity (dBm)	-112 (using diversity reception)
Control interface	I ² C-bus*1
Supply voltage (V)	1.2 (OFDM), 1.8 (RF), 1.8 to 3.1 (I/O)
Power consumption (mW)	82 (with single-tuner reception) 160 (with 2-tuner reception) 155 (with 2-tuner diversity reception)
Outline dimensions (mm)	9.0 (W) × 9.0 (D) × 1.25 (H)

*1 I²C-bus is a trademark of Philips Corporation.

■ Tuner Module for China's CMMB*-system Mobile Broadcasts

◆ Features

- (1) Industry's smallest package size (9.0 × 9.0 × 1.7 mm)
- (2) One of the lowest power consumption rates in the industry (93 mW)

*CMMB: China Mobile Multimedia Broadcasting, one of China's digital mobile broadcasting formats.



VA3C5CZ934

◆ Standard Specifications

Model No.	VA3C5CZ934
Reception frequency (MHz)	UHF: 470 to 798 (8 MHz range)
Reception sensitivity (dBm)	-98 (QPSK, 1/2 LDPC)
Interface	SPI or SDIO (1-bit) (3.3 V, clock 4 MHz MAX.)
Supply voltage (V)	1.8 (RF), 1.2 (OFDM core), 3.3 (I/O)
Power consumption (mW)	93 (TYP. time-sliced image, 1-ch reception)
Outline dimensions (mm)	9.0 (W) × 9.0 (D) × 1.7 (H)

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■ Embedded Wireless LAN Module

◆ Features

- (1) LSI implementation of MAC functionality for reduced load on host CPU and high throughput
Transmission: 10.2 Mbps
Reception: 12.5 Mbps
Test environment: i-MX3i (500 MHz), SDIO, Windows Mobile 5.0
- (2) Low power consumption
Continuous transmission: 530 mW (11g: +10 dBm output)
Continuous reception: 326 mW
Sleep mode: 81 μ W
- (3) Wake on WLAN support
- (4) LSI implementation of encryption function for reduced load on host CPU



DC2J1DZ150

◆ Standard Specifications

Standard	IEEE802.11b/g
Model No.	★DC2J1DZ150
Operating frequency (MHz)	2 400 to 2 484
Data rate (Mbps)	1/2/5.5/11 & 6/9/12/18/24/36/48/54
Number of channels	13
Demodulator system	CCK/DQPSK/DBPSK (11b) OFDM (11g)
Transmission output (dBm)	13/10
Receiving sensitivity (dBm)	TYP.: -87 (11 Mbps CCK) TYP.: -70 (54 Mbps OFDM)
Channel selection system	PLL (I ² C)
Security	WEP TKIP AES
Outline dimensions (mm)	7.9 (W) × 8.5 (D) × 1.3 (H)

Consult separately regarding driver software.

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■ Embedded Wireless LAN-Bluetooth Combo Module

◆ Features

- (1) A two-in-one module compliant with the latest Bluetooth standard (v2.1)
Wireless LAN: 11b/g, Bluetooth: v2.1+EDR* (3 Mbps)
- (2) Compatible with IEEE802.15.2 standard compliant wireless LAN and Bluetooth coexistence functions.
- (3) Thin, compact configuration—the smallest class in the industry.
10.0 x 10.0 x 1.3 mm

*EDR: Enhanced Data Rate



DC2K1DZ145

◆ Standard Specifications

Model No.	★DC2K1DZ145	
Standard	WLAN (IEEE802.11b/g)	Bluetooth v2.1+EDR; HCI
Outline dimensions (mm)	10.0 (W) × 10.0 (D) × 1.3 (H)	
Supply voltage (V DC)	VCCIF_WLAN 1.7 to 1.9 or 2.3 to 2.7 VCCPA 2.7 to 3.6 VCC285 2.7 to 2.9 VCC120 1.1 to 1.3	VCCIF_BT 1.7 to 1.9 or 2.3 to 2.7 Vcc275_BT 2.65 to 2.85
Input frequency (MHz)	2,400 to 2,484	2,402 to 2,480
Data rate (Mbps)	1/2/5.5/11 & 6/9/12/18/24/36/48/54	1/2/3
Number of channels	13	79
Modulation system	CCK/DQPSK/DBPSK (11b) OFDM (11g)	GFSK (1 Mbps) DQPSK (2 Mbps) 8-DPSK (3 Mbps)
Transmission output (dBm)	13/10	Class 2 4 (Max.)
Receiving sensitivity (dBm)	TYP.: -87 (11 Mbps, PER 8%) TYP.: -70 (54 Mbps, PER 10%)	TYP.: -82 (1 Mbps, BER 0.1%) TYP.: -84 (2 Mbps, BER 0.01%) TYP.: -76 (3 Mbps, BER 0.01%)
Security	WEP TKIP AES	by driver software
Interface	SPI/SDIO	PCM (64 kbps), SPI/UART

Consult separately regarding driver software.

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■ Infrared Data Communication Device Lineup

Communication system	Transmission speed	Transmission distance	Features	Operating supply voltage	Model No.
IrDA data (IrDA 1.x)	FIR 4 Mb/s (Receiver only)	250 cm		3.0 to 3.6 V	GP2W4020XPMF
		150 cm		3.0 to 3.6 V	GP2W4010YP0F
	FIR 4 Mb/s (Integrated receiver and transmitter type)	100/21 cm	LP/MP/HP mode switching function	2.7 to 5.5 V	GP2W1001YP0F
		35/21 cm	LP/HP mode switching function, remote control transmission function, thin (height: 1.5 mm)	2.6 to 3.6 V	GP2W3152YP0F
			LP/HP mode switching function, remote control transmission function, top view type (height: 1.75 mm)	2.6 to 3.6 V	GP2W3172XP0F
			LP/HP mode switching and remote control transmission functions	2.6 to 3.6 V	GP2W3120YP0F
			LP/HP mode switching function	2.7 to 3.6 V	GP2W1320YP0F
		70/21 cm	LP/MP/HP mode switching and remote control transmission functions	2.6 to 3.3 V	GP2W3104YP0F
	SIR 115.2 kb/s (Integrated receiver and transmitter type)	100 cm	Compact, low dissipation current	2.4 to 5.5 V	GP2W0004YP0F/ GP2W0004XP0F
	SIR LP 115.2 kb/s (Integrated receiver and transmitter type)	20 cm	Built-in LED constant current circuit, 3-state output	2.0 to 3.6 V	GP2W0110VX/ GP2W0110VY

■ Infrared Data Communication Devices

◆ FIR Compliant Devices (Receiver Only)

Model No.	Communication system	Transmission speed	Description	Maximum reception distance*1 (cm)	Supply voltage (V DC)	Outline dimensions (mm)
GP2W4020XPMF	Uni-directional communication (receiving only)	4 Mb/s	IrSS™-compliant, receiving-only type	250	3 to 3.6	21 × 7 × 7.1
GP2W4010YP0F	Uni-directional communication (receiving only)	9.6 k to 4 Mb/s	IrSS™-compliant, receiving-only type	150	3 to 3.6	10 × 4 × 4.5

*1 Radiant intensity at transmitting side: 100 mW/sr



◆ FIR Compliant Devices (Integrated Receiver and Transmitter Type)

Model No.	Communication system	Transmission speed	Description	Transmission distance (cm)	Supply voltage (V DC)	Outline dimensions (mm)
GP2W3152YP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	With remote control transmission function, LP/HP mode switching function	21/35	2.6 to 3.6	7.9 × 2.8 × 1.5
GP2W3172XP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	With remote control transmission function, top-view, LP/HP mode switching function	21/35	2.6 to 3.6	8.8 × 2.5 × 1.75
GP2W3120YP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	With remote control transmission function, LP/HP mode switching function	21/35	2.6 to 3.6	7.16 × 2.73 × 1.82
GP2W1001YP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	LP/MP/HP mode switching function	21/100	2.7 to 5.5	10.01 × 4.4 × 3.5
GP2W1320YP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	Compact, thin, low dissipation current (Icc: TYP. 0.45 mA)	21/35	2.7 to 3.6	7.16 × 2.73 × 1.82
GP2W3104YP0F	Bi-directional (half-duplex) communication	9.6 k to 4 Mb/s	With remote control transmission function, LP/MP/HP mode switching function	21/70	2.6 to 3.3	7.9 × 2.85 × 2.5



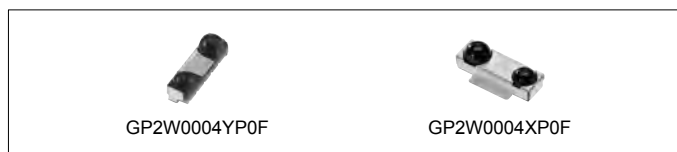
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◆SIR Compliant Devices (Integrated Receiver and Transmitter Type)

Model No.	Communication system	Transmission speed	Description	Transmission distance (cm)	Supply voltage (V DC)	Outline dimensions (mm)
GP2W0004YP0F	Bi-directional (half-duplex) communication	9.6 k to 115.2 kb/s	Low dissipation current (I _{cc} : 130 μA MAX.)	100	2.4 to 5.5	9.21 × 3.76 × 2.71
GP2W0004XP0F	Bi-directional (half-duplex) communication	9.6 k to 115.2 kb/s	Low dissipation current (I _{cc} : 130 μA MAX.), top-view	100	2.4 to 5.5	9.2 × 3.35 × 2.95



◆SIR LP Compliant Devices (Integrated Receiver and Transmitter Type)

Model No.	Communication system	Transmission speed	Description	Transmission distance (cm)	Supply voltage (V DC)	Outline dimensions (mm)
GP2W0110VX/VY	Bi-directional (half-duplex) communication	2.4 k to 115.2 kb/s	Top-view and side view compatible (Model name is prescribed based on the packaging status.)	20	2.0 to 3.6	6.8 × 2.35 × 2.1



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IR Detecting Unit for Remote Control Lineup (Classified by Form/Operating Voltage)

Type	Package		Features	Model No.	
	Form	Detection position*5 (from PCB)		Operating voltage: 5 V	Operating voltage: 3 to 5 V
IR detecting unit for remote control	Compact, thin type SMD (4.5 × 5.0 × 1.3 t mm)				GP1USC3xXP series
	Compact type SMD (6.8 × 2.1 × 2.35 t mm)				GP1UF31 series
	Lead L bend with holder	16.0 mm*1	Compact size	GP1UM28XK0VF series	GP1UE28xXKC4 series
		12.0 mm*2	Compact size, Strengthened resistance to electromagnetic induction noise (Mesh type)	GP1UM28RK0VF series	GP1UE28xRKC4 series
			Compact size	GP1UM27XK0VF series	GP1UE27xXKC4 series
		6.8 mm*3	Compact size, Strengthened resistance to electromagnetic induction noise (Mesh type)	GP1UM27RK0VF series	GP1UE27xRKC4 series
			Compact size	GP1UM26XK0VF series	GP1UE26xXKC4 series
			Compact size, Strengthened resistance to electromagnetic induction noise (Mesh type)	GP1UM26RK0VF series	GP1UE26xRKC4 series
	Lead straight with holder	19.0 mm	Compact size, Strengthened resistance to electromagnetic induction noise (Mesh type)	GP1UM29QK0VF series	GP1UE29xQKC4 series
		9.6 mm	Compact size	GP1UM28YK0VF series	GP1UE28xYKC4 series
			Compact size, Strengthened resistance to electromagnetic induction noise (Mesh type)	GP1UM28QK0VF series	GP1UE28xQKC4 series
	Holderless	Lead straight 6.0 mm		GP1UX51QS series	GP1UXC4xQS series
		Lead L bend*4 5.3 mm		GP1UX51RK series	GP1UXC4xRK series

*1 Mesh type (strengthened resistance to electromagnetic induction noise): 16.4 mm

*2 Mesh type: 12.4 mm

*3 Mesh type: 7.2 mm

*4 Mesh type: 5.3 mm

*5 Lead straight: Distance from lens center to mounting board upper surface

No mesh lead L bend: Distance from tip of lens to mounting board upper surface

Mesh-type lead L bend: Distance from tip of mesh to mounting board upper surface



GP1UM26XK0VF
(GP1UE26xXKC4)



GP1UM27XK0VF
(GP1UE27xXKC4)



GP1UM28XK0VF
(GP1UE28xXKC4)



GP1UM28YK0VF
(GP1UE28xYKC4)



GP1UM26RK0VF
(GP1UE26xRKC4)



GP1UM27RK0VF
(GP1UE27xRKC4)



GP1UM28RK0VF
(GP1UE28xRKC4)



GP1UM28QK0VF
(GP1UE28xQKC4)



GP1UM29QK0VF
(GP1UE29xQKC4)



GP1UX51QS
(GP1UXC4xQS)



GP1UF31xXP0F
(GP1UF31xYP0F)



GP1USC3xXP

■ IR Detecting Units for Remote Control

(Ta = 25°C)

Type	Series No.	Absolute maximum ratings		Operating voltage (V)	Electrical characteristics				Size (mm)	Terminal layout
		Vcc (V)	ToPr (°C)		Icc (mA) *1 MAX.	VOH (V) MIN.	VOL (V) MAX.	fo (kHz) TYP.		
Surface-mount type, Ref ow soldering compatible	GP1UF31xXP0F/ *6 GP1UF31xYP0F	0 to 6.0	−30 to +85	2.7 to 5.5	0.4	Vcc−0.5	0.45	*5	6.8 × 2.1 × 2.35	—
	☆GP1USC3xXP	0 to 6.0	−30 to +85	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5 × 4.5 × 1.3	—
With holder, CMOS type, 3 to 5 V drive	GP1UE26xXKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 6.8	Center Vcc
	GP1UE27xXKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 12.0	
	GP1UE28xXKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 16.0	
	GP1UE28xYKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 8.6 × 12.5(9.6)*2	
With holder, CMOS type, 3 to 5 V drive, Strengthened resistance to electromagnetic induction noise	GP1UE26xRKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 7.2	
	GP1UE27xRKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 12.4	
	GP1UE28xRKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.6 × 16.4	
	GP1UE28xQKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 9.0 × 12.5(9.6)*2	
	GP1UE29xQKC4	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.6 × 16.2 × 21.9(19)*2	
With holder, 5 V drive	GP1UM26XK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 6.8	
	GP1UM27XK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 12.0	
	GP1UM28XK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 16.0	
	GP1UM28YK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 8.6 × 12.5(9.6)*2	
With holder, 5 V drive, Strengthened resistance to electromagnetic induction noise	GP1UM26RK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 7.2	
	GP1UM27RK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 12.4	
	GP1UM28RK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.6 × 16.4	
	GP1UM28QK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 9.0 × 12.5(9.6)*2	
	GP1UM29QK0VF	0 to 6.0	−10 to +70	4.5 to 5.5	0.6 (0.65)	Vcc−0.5	0.45	*4	5.6 × 16.2 × 21.9(19)*2	
Holderless, CMOS type, 3 to 5 V drive, Strengthened resistance to electromagnetic induction noise	GP1UXC4xQS	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.5 × 5.3 × 7.5	Center GND
	GP1UXC4xRK	0 to 6.0	−10 to +70	2.7 to 5.5	0.6	Vcc−0.5	0.45	*3	5.5 × 5.3 × 7.5	
Holderless, 5 V drive, Strengthened resistance to electromagnetic induction noise	GP1UX51QS	0 to 6.0	−10 to +70	4.5 to 5.5	0.6	Vcc−0.5	0.45	*4	5.5 × 5.3 × 7.5	
	GP1UX51RK	0 to 6.0	−10 to +70	4.5 to 5.5	0.6	Vcc−0.5	0.45	*4	5.5 × 5.3 × 7.5	

* A voltage regulator circuit is built-in but may be affected by the usage environment. Install with an externally mounted C and R as a power supply filter.

*1 When no signal is input (during input light).

*2 Figures in parentheses indicate the distance to the light detection center.

*3 fo = 32.75/36/36.7/38/40 kHz

*4 fo = 32.75/36/36.7/38/40/56.8 kHz

*5 fo = 36/36.7/38/40 kHz

*6 GP1UF31xXP0F: Top view taped package,
GP1UF31xYP0F: Side view taped package

Notice

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Except where specially indicated, models listed on this page comply with the RoHS Directive*. For details, please contact SHARP.
*RoHS Directive: Prohibits use of lead, cadmium, hexavalent chromium, mercury and specific brominated flame retardants (PBBs and PBDEs), with certain exceptions.

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■ Advanced Flex Printed Circuit Boards

The advanced flex printed circuit board is a multilayered composite wiring board comprised of flexible printed circuits (FPC) laminated into a multilayer configuration. The PWBs and FPCs are connected to each other via copper-plated through holes. It is ideal for compact, lightweight equipment design.

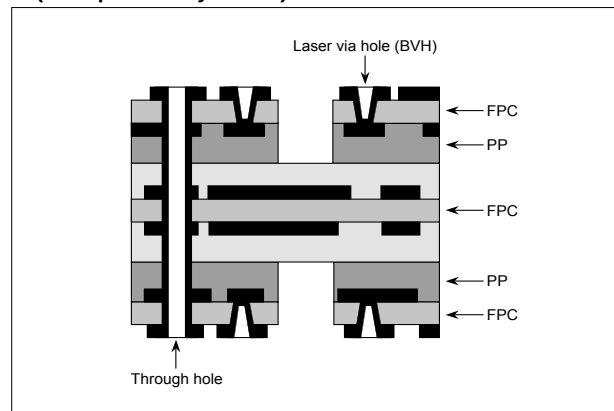
◆ Features

- (1) For selecting optimal specifications to suit specific applications, special specifications such as for mobile phones are also available.
 - Minimum thickness in multi-layer part: 0.26 mm (4-layer), 0.33 mm (6-layer)
 - Minimum pattern width/pitch: 0.06/0.07 mm
 - Flexibility of single/double sided FPC part (dedicated for hinge): More than 200 000 times 180-degree bending of radius 3 mm
- (2) Capable of board-to-board connection without connectors, which enables space-saving and 3-dimensional equipment assembly.
- (3) Through hole plating connection of multi-layer (3 to 8) part to flexible part significantly improves reliability.
- (4) Blind Via Hole (BVH) forming with laser via drilling of small diameter.
- (5) Sheet design provides excellent mountability, equivalent to that of PWB.

◆ Outline Specifications

Type	Folding type/Flying tail type	
Min. base thickness (mm)	0.26 (4-layer), 0.33 (6-layer), 0.40 (8-layer)	
Min. line width/spacing (mm)	0.06/0.07	
Min. through hole diameter (mm)	ø0.25	
Min. via hole land diameter	Through hole (mm)	Outer layer: ø0.5, Inner layer: ø0.5
	Blind via hole (mm)	ø0.09
	Inner via hole (mm)	ø0.30
Solder resist	Multi layer: Liquid photo solder resist, FPC: Film cover ray	
Surface finish	Heat-resistant preflux, Ni-Au plating (Ni-Au plating for flying tail)	
Safety standard	UL (94V-0)	

■ Construction of Advanced Flex Board (example of 6-layer BVH)



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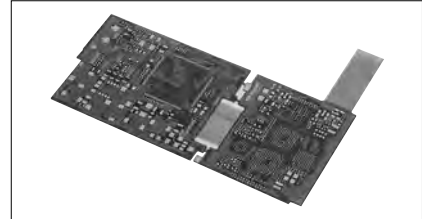
Flexible Build-Up Multilayer PCBs

<Flex-rigid specifications>

Advanced flex specifications are used for the inner layer core material of this build-up multilayer PCB, so the board can handle finer mounting patterns and achieve connectorless between-board connections using an inner layer flexible printed circuit (FPC). This facilitates greater equipment design flexibility and ultra-compact designs.

◆ Features

- (1) Multiple build-up layers are connected internally with an FPC, thereby improving connection reliability between multilayer boards and reducing both connection space and connector weight.
- (2) Enables narrow pitch (0.4 mm) CSP and bare chip mounting, and thus greater equipment compactness through ultra-high density mounting.
- (3) Enables via-on-IVH (inner-via-hole) configurations, and makes it possible to achieve ultra-high density wiring designs.
(Facilitates a diverse range of designs for greater compactness and thinness.)



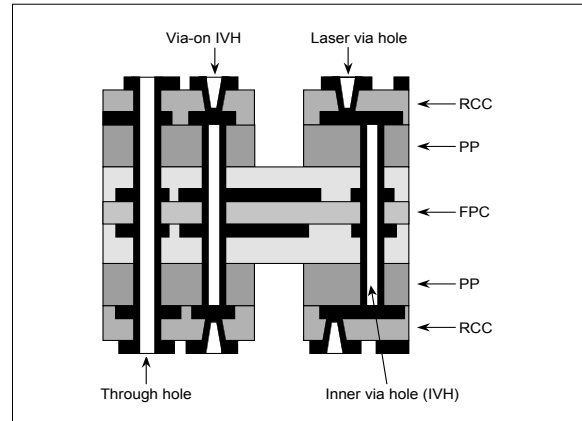
◆ Outline Specifications

Type	F1 (6- to 8-layer)	
No. of build-up layers	1 for each side of core layer	
Core layer configuration	3 to 6 layers (Polyimide, FR-4)	
Min. board thickness*1 (mm)	0.57 (6-layer), 0.77 (8-layer)	
Via hole diameter	Conformal via hole (mm)	ø0.09/ø0.30
Land hole diameter	Stacked via hole	—
Via-on IVH	Available	
Inner via hole diameter (mm)	ø0.2	
Min. line width/spacing*2 (mm)	0.09/0.09	
CSP mountable pitch (mm)	0.4	
Safety standard	UL (94V-0)	

*1 Consult with SHARP if a thinner type is required for special designs.

*2 Values are measured at build-up portion.

■ Construction of Flexible Build-Up Multilayer PCBs (example of 6-layer IVH)



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Flexible Printed Circuit Boards

The flexible printed circuit board is designed for high space efficiency and product design flexibility, which are now aiming at more compact and higher density mounting. It also contributes to the reduction of assembly process and to the enhancement of the reliability.

◆ Features

- (1) High density mounting circuit, SMT and other most suitable flexible PCB are available.
- (2) High precision type for COF with flip chip mounting and wire bonding capabilities and other connector mounting type are also available.

◆ Standard specifications

Layers	Single side	Both-side through-hole
Substrate materials	Polyimido f lm, non-adhesive polyimido	
Design pattern width (mm)	0.02 (MIN.)	0.05 (MIN.)
Design pattern spacing (mm)	0.04 (MIN.)	0.05 (MIN.)
Through-hole / land diameter (mm)	—	ø0.1/ø0.3 (MIN.)
Cover lay	Polyimido f lm, heat resistant ink, liquid soldering resist	
Safety standard	UL (94V-0)	



◆ Line-up

Multi-layer flexible PCB	Both-side flexible PCB
Single-layer flexible PCB	Flex-rigid PCB
Single-side high precision flexible PCB	Both-side high precision flexible PCB

Other line-up

Bonding Ni-Au plating
Highly flexible (bending capacity)
High density SMT

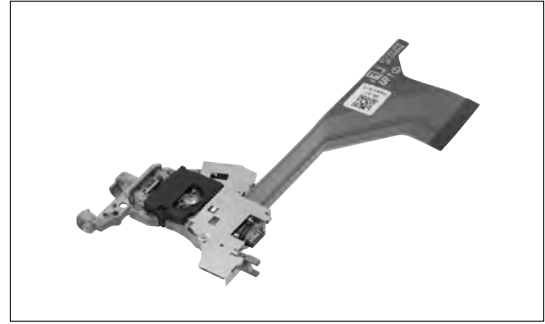
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■ Slim Combo Drive Pickup <DD-57>

◆ Features

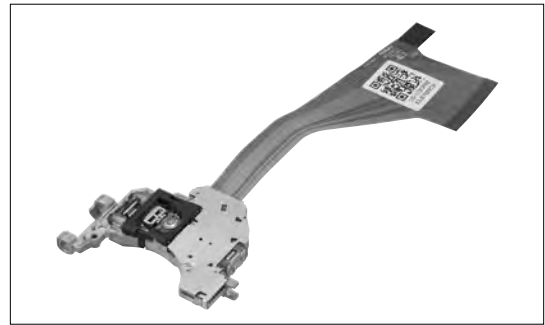
- Thin type pickup compatible with half-inch-height drive (12.7 mm thickness)
- Playback speed: 8× (DVD-ROM), 24× (CD-ROM)
- Recording speed: 24× (CD-R), 24× (CD-RW)
- DVD-RAM readable
- Outline dimensions: W 38.6 × H 7.3 × D 48.7 (mm)
- Weight: Approx. 11 g



■ Slim DVD Super-Multi Drive Pickup <DD-115>

◆ Features

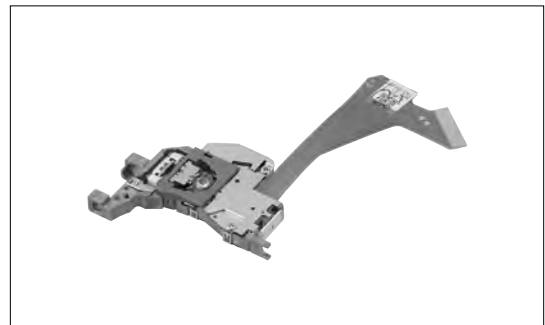
- Thin type pickup compatible with half-inch-height drive (12.7 mm thickness)
- Playback speed: 8× (DVD-ROM), 24× (CD-ROM)
- Recording speed: 8× (DVD±R, +RW, ±R/+RW(DL))
6× (DVD-RW, -RW(DL))
5× (DVD-RAM)
24× (CD-R/RW)
- Outline dimensions: W 35.6 × H 7.3 × D 48.7 (mm)
- Weight: Approx. 13.5 g



■ DVD Pickup for Automotive Use <HPD-61>

◆ Features

- Compact, thin (7.3 mm) pickup
- Playable disk: DVD-ROM, CD-ROM
- Operating temperature: -20 to +80°C
- Outline dimensions: W 30.2 × H 7.3 × D 48.7 (mm)
- Weight: Approx. 13.5 g



Notice

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BS

BS1F6JP100A.....	105
BS1F6JP300A.....	105
BS1F6JU300A.....	105
BS1K0EL100A.....	104
BS1R8AR100A.....	105
BS1R8EL200A.....	104
BS1R8EL400A.....	104
BS1R8EL500A.....	104
BS2F7VZ0169.....	107
BS2F7VZ7395.....	107
BS2F7VZ7700.....	107
BS2S7HZ0502.....	106
BS2S7HZ6701.....	106
BS2S7HZ7306A.....	106

DC

DC2J1DZ150.....	114
DC2K1DZ145.....	115

DD

DD-115.....	124
DD-57.....	124

DU

DU6N4JZ00xx.....	112
------------------	-----

GA

GA1A1S100WP.....	78
GA1A1S202WP.....	78
GA1A1S203WP.....	78
GA1A1S204WP.....	78

GA1A2S100LY.....	78
GA1A2S100SS.....	78
GA220T2L1IZ.....	80

GH0

GH04020A2G.....	102/103
GH04020A4G.....	102/103
GH04P21A2G.....	102/103
GH04P25A2G.....	102/103
GH04P25A4G.....	102/103
GH06510F4A.....	102/103
GH06P24A2C.....	102/103
GH07810C2K.....	102/103
GH07825C2K.....	102/103
GH07P24C1C.....	102/103
GH07P24C4C.....	102/103
GH07P28F1C.....	102/103
GH07P28F4C.....	102/103

GH1

GH16P24A8C.....	102/103
GH16P35A8C.....	102/103
GH16P40A8C.....	102/103

GL0

GL0ZJ042B0S.....	94
GL0ZS042B0S.....	94
GL0ZV042B0S.....	94

GL1

GL100MD1MP1.....	85
GL100MN0MP.....	85
GL100MN1MP.....	85

GL100MN3MP.....	85
-----------------	----

GL3

GL380.....	85
GL381.....	85
GL382.....	85
GL3B2402B0SC.....	94
GL3BC302B0S2.....	94
GL3ED8.....	95
GL3EG401E0S.....	96
GL3EG402E0S.....	96
GL3EG404E0S.....	96
GL3EG804E0S.....	96
GL3G2402B0SC.....	94
GL3HD401E0S.....	96
GL3HD402E0S.....	96
GL3HD404E0S.....	96
GL3HD804E0S.....	96
GL3HS401E0S.....	96

GL3HS402E0S.....	96
GL3HS404E0S.....	96
GL3HS804E0S.....	96
GL3HY401E0S.....	96
GL3HY402E0S.....	96
GL3HY404E0S.....	96

GL3HY804E0S.....	96
GL3JE402B0SE.....	94
GL3JG401E0S.....	96
GL3JG402E0S.....	96

GL3JG404E0S.....	96
GL3JG804E0S.....	96
GL3JJ404B0SE.....	94
GL3JJ804B0SE.....	94

GL3JR402B0S3.....	94
GL3JS404B0SE.....	94
GL3JS804B0SE.....	94
GL3JV404B0SE.....	94
GL3JV804B0SE.....	94
GL3UR401E0S.....	94
GL3UR402E0S.....	94
GL3UR404E0S.....	94
GL3UR804E0S.....	94
GL3ZJ402B0SE.....	94
GL3ZJ802B0SE.....	94
GL3ZR402B0SE.....	94
GL3ZR802B0SE.....	94
GL3ZS402B0SE.....	94
GL3ZS802B0SE.....	94
GL3ZV402B0SE.....	94
GL3ZV802B0SE.....	94

GL4

GL4100E0000F.....	85
GL4800E0000F.....	85
GL480E00000F.....	85
GL4EG8.....	96
GL4HD8.....	96
GL4HS8.....	96
GL4HY8.....	96
GL4JG8.....	96

GL5

GL537.....	85
GL538.....	85
GL560.....	85
GL561.....	85

GL5ED44.....	95
GL5ED5.....	95
GL5EG40.....	96
GL5EG41.....	96
GL5EG43.....	96
GL5EG44.....	96
GL5EG8.....	96
GL5HD40.....	96
GL5HD41.....	96
GL5HD43.....	96
GL5HD44.....	96
GL5HD8.....	96
GL5HS40.....	96
GL5HS41.....	96
GL5HS43.....	96
GL5HS44.....	96
GL5HS8.....	96
GL5HY40.....	96
GL5HY41.....	96
GL5HY43.....	96
GL5HY44.....	96
GL5HY8.....	96
GL5JG41.....	96
GL5JG43.....	96
GL5JG44.....	96
GL5JG8.....	96
GL5JJ302B0SE.....	94
GL5JJ7D2D0SE.....	94
GL5JS302B0SE.....	94
GL5JS7D2D0SE.....	94
GL5JV302B0SE.....	94
GL5JV7D2D0SE.....	94
GL5UR2K.....	94

GL5UR2K1.....	94
GL5UR44.....	94
GL5ZJ152B0SE.....	94
GL5ZJ302B0SE.....	94
GL5ZR152B0SE.....	94
GL5ZR302B0SE.....	94
GL5ZS152B0SE.....	94
GL5ZS302B0SE.....	94
GL5ZV152B0SE.....	94
GL5ZV302B0SE.....	94
GL6	
GL6EG26T.....	96
GL6UR26T.....	94
GL6ZJ27.....	94
GL6ZR27.....	94
GL6ZS27.....	94
GL6ZV27.....	94
GL8	
GL8EG21.....	96
GL8EG22.....	96
GL8EG23.....	96
GL8HD21.....	96
GL8HD22.....	96
GL8HD23.....	96
GL8HS21.....	96
GL8HS22.....	96
GL8HY21.....	96
GL8HY22.....	96
GL8HY23.....	96
GL8JG21.....	96
GL8JG22.....	96

GL8UR21.....	94
GL9	
GL9ED2.....	95
GL9ED4.....	95
GM1	
GM1BC35372AC.....	97
GM1BW20300A.....	99
GM1EG55200A.....	98
GM1GC35370AC.....	97
GM1HD55200A.....	98
GM1HS55200A.....	98
GM1HY55200A.....	98
GM1JE35200AE.....	97
GM1JJ35200AE.....	97
GM1JR35200AE.....	97
GM1JS35200AE.....	97
GM1JV35200AE.....	97
GM1WA55311A.....	100
GM4	
GM4BN653C0A.....	99
GM4BW53340A.....	99
GM4BW653A0A.....	99
GM4BW653B0A.....	99
GM4BW853A0A.....	99
GM4BW853B0A.....	99
GM4WA25300A.....	100
GM5	
GM5BC01250AC.....	97
GM5BC03210Z.....	97

GM5BC96270A.....	97
GM5BN96385A.....	101
GM5BN97330A.....	99
GM5BW94370A.....	99
GM5BW96381A.....	99
GM5BW96382A.....	101
GM5BW96385A.....	101
GM5BW96387A.....	101
GM5BW97330A.....	99
GM5BW97332A.....	99
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GM5GC03210Z.....	97
GM5GC96270A.....	97
GM5SAE27P0A.....	101
GM5SAE30P0A.....	101
GM5SAE35P0A.....	101
GM5SAE40P0A.....	101
GM5SAE45P0A.....	101
GM5SAE50P0A.....	101
GM5SAE57P0A.....	101
GM5SAE65P0A.....	101
GM5WA06310A.....	100
GM5WA94310A.....	100
GM5WA94315A.....	101
GM5ZJ01200A.....	97
GM5ZJ03200Z.....	97
GM5ZR01200A.....	97
GM5ZR03200Z.....	97
GM5ZR96270A.....	97
GM5ZS01200A.....	97
GM5ZS03200Z.....	97
GM5ZV01200A.....	97

GM5ZV03200Z 97

GM5ZV96270A 97

GP1

GP1A054RDKLF 76

GP1A057RBKLF 76

GP1A057SGKLF 76

GP1A058SCK0F 76

GP1A073LCS 74

GP1A101C2KSF 76

GP1A173LCS2F 74

GP1A204HCS0 76

GP1A273LCS1F 74

GP1A50HRJ00F 73

GP1A51HRJ00F 73

GP1A52HRJ00F 73

GP1A52LRJ00F 73

GP1A53HRJ00F 73

GP1A57HRJ00F 73

GP1A58HRJ00F 73

GP1A73AJ000F 74

GP1A75EJ000F 74

GP1A98HCZ0F 72

GP1FAV30RK0F 93

GP1FAV30TK0F 93

GP1FAV31RK0F 93

GP1FAV31TK0F 93

GP1FAV50RK0F 93

GP1FAV50TK0F 93

GP1FAV51RK0F 93

GP1FAV51TK0F 93

GP1FAV55TK0F 93

GP1FD310TP0F 93

GP1FD320TP0F 93

GP1FMV31RK0F 93

GP1FMV31TK0F 93

GP1FMV51RK0F 93

GP1FMV51TK0F 93

GP1FSB31TK0F 93

GP1FSV31TK0F 93

GP1FSV51TK0F 93

GP1L50J0000F 72

GP1L51J0000F 72

GP1L52VJ000F 72

GP1L53VJ000F 72

GP1L57J0000F 72

GP1S092HCP1F 70

GP1S093HCZ0F 70

GP1S094HCZ0F 70

GP1S096HCZ0F 70

GP1S097HCZ0F 70

GP1S173LCS2F 71

GP1S194HCZ0F 70

GP1S195HCPSF 70

GP1S195HCZSF 70

GP1S196HCPSF 70

GP1S196HCZ0F 70

GP1S196HCZSF 70

GP1S273LCS1F 71

GP1S296HCPSF 70

GP1S50J0000F 71

GP1S51VJ000F 71

GP1S52VJ000F 71

GP1S53VJ000F 71

GP1S54J0000F 71

GP1S56TJ000F 71

GP1S58VJ000F 71

GP1S59J0000F 71

GP1S74PJ000F 71

GP1UE26xRKC4 120

GP1UE26xXKC4 120

GP1UE27xRKC4 120

GP1UE27xXKC4 120

GP1UE28xQKC4 120

GP1UE28xRKC4 120

GP1UE28xXKC4 120

GP1UE28xYKC4 120

GP1UE29xQKC4 120

GP1UF31xXP0F 120

GP1UF31xYP0F 120

GP1UM26RK0VF 120

GP1UM26XK0VF 120

GP1UM27RK0VF 120

GP1UM27XK0VF 120

GP1UM28QK0VF 120

GP1UM28RK0VF 120

GP1UM28XK0VF 120

GP1UM28YK0VF 120

GP1UM29QK0VF 120

GP1USC3xXP 120

GP1UX51QS 120

GP1UX51RK 120

GP1UXC4xQS 120

GP1UXC4xRK 120

GP2

GP2A200LCS0F 75

GP2A224P0KA 77

GP2A231LRSF 75

GP2A240LCS0F 75

GP2A250LCS0F 75

GP2A25DJ000F 75

GP2A25J0000F 75

GP2A25NJ000F 75

GP2A28AJ000F 75

GP2AP002A00F 77

GP2AP002S00F 77

GP2D120XJ00F 89

GP2D150AJ00F 88

GP2S29SVJ00F 76

GP2S60 74

GP2S700HCP 74

GP2TC2J0000F 91

GP2W0004XP0F 118

GP2W0004YP0F 118

GP2W0110VX 118

GP2W0110VY 118

GP2W1001YP0F 117

GP2W1320YP0F 117

GP2W3104YP0F 117

GP2W3120YP0F 117

GP2W3152YP0F 117

GP2W3172XP0F 117

GP2W4010YP0F 117

GP2W4020XPMF 117

GP2Y0A02YK0F 89

GP2Y0A21YK0F 89

GP2Y0A41SK0F 89

GP2Y0A51SK0F 89

GP2Y0A60SZ0F 89

GP2Y0A60SZLF 89

GP2Y0A710K0F 89

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GP2Y0D21YK0F	88
GP2Y0D310K	88
GP2Y0D340K	88
GP2Y0D413K0F	88
GP2Y0D805Z0F	88
GP2Y0D810Z0F	88
GP2Y0D810Z1F	88
GP2Y1010AU0F	91
GP2Y2A180K0F	90
GP2Y2A280K0F	90
GP2Y2D160K0F	90
GP2Y3A001K0F	90
GP2Y3A002K0F	90
GP2Y3A003K0F	90
GP2Y40010K0F	91
GP2Y40021K0F	91
GP2Y5D91S00F	88
GP2Y6001AK0F	91

GW5

GW5BDC15L02	100
GW5BDF15L00	100
GW5BNC15L02	100
GW5BNC15L12	100
GW5BNF15L00	100
GW5BNF15L10	100
GW5BQC15L02	100
GW5BQF15L0B	100
GW5BRC15L02	100
GW5BRF15L0B	100
GW5BTC15L02	100

GW5BTF15L0B	100
GW5BWC15L02	100
GW5BWF15L00	100

HPD

HPD-61	124
--------------	-----

IR2

IR2D071	42
IR2D20U	42
IR2E49M	41
IR2E49U	41
IR2E51Y6	41
IR2E55Yx	41
IR2E56U6	41
IR2E58U	41
IR2E62U	41
IR2E65U	42
IR2E66M	42

IR3

IR3M58M	25/38/40
IR3M58U	25/38/40
IR3M59U	19/40
IR3M63U	19/20/40
IR3T46U6	43
IR3T48Y6	43
IR3Y48B1	18/22
IR3Y50U6	18
IR3Y60U6	18

IRM

IRM046U7	43
----------------	----

IRM053U7	43
IRM063U7	43
IRM065U7	43
IRM067U6	43
IRM068U7	43

IS

IS471FE	79
IS485E	79
IS486E	79
IS489E	79

LH1

LH16CR	24
LH16DD	24
LH16DH	24

LH2

LH28F128BFH-PBTL	30
LH28F128BFH-PTTL	30
LH28F128BFH-PWTL	30
LH28F128BFHED-PWTLT2	31
LH28F128BFHT-PBTL75A	31
LH28F128BFHT-PTTL75A	31
LH28F128BFHT-PTTLT1A	31
LH28F128SPH-PTL	30
LH28F128SPHT-PTL12B	31
LH28F256BFH-PTTL	30
LH28F256BFHTD-PTTLZ3	31
LH28F320BFH-PTTL	30
LH28F320BFHE-PTTLE0	31
LH28F640BFH-PBTL	30
LH28F640BFH-PTTL	30

LH28F640BFHE-PBTLHGA	31
LH28F640BFHE-PBTLHK	31
LH28F640BFHE-PTTLH1A	31
LH28F640BFHE-PTTLHFA	31
LH28F640SPH-PL	30
LH28F640SPHT-PL12B	31

LK

LK315T3LA5X	10
LK400D3LA14	10
LK460D3LA2X	10
LK520D3LA5X	10
LK600D3LA38	10
LK816D3LA19	10
LK816D3LA29	10

LQ0

LQ025Q3DW02	9
LQ028Q3UX01	13
LQ030T5DG01	11
LQ035Q3DG01	9
LQ035Q3DG03	9
LQ035Q3DW02	9
LQ035Q5DG02	11
LQ038Q3DC01	9
LQ043T3DG01	9
LQ043T3DG02	9
LQ043T5DG02	11
LQ050T5DG01	11
LQ057Q3DC12	9
LQ057Q3DG01	9
LQ057Q3DG02	9
LQ057V3DG01	9

(Note) The following models listed on this page are not sold in the United States.
LK816D3LA19, LK816D3LA29, LK520D3LA5X, LK460D3LA2X, LK400D3LA14, LK315T3LA5X

LQ057V3DG02..... 9	LQ104V1DG61..... 8		PC354NJ0000F..... 56
LQ057V3LG11..... 9	LQ104V1DG62..... 8	LR3	PC355NJ0000F..... 56
LQ058T5DG02..... 11	LQ104V1LG61..... 8	LR35501..... 26	PC357NJ0000F..... 56
LQ058Y5DG01..... 11	LQ121K1LG11..... 8	LR35503..... 26	PC364NJ0000F..... 56
LQ064V3DG01..... 9	LQ121S1DG42..... 8	LR35504..... 26	PC365NJ0000F..... 56
LQ065T5DG02..... 11	LQ121S1DG61..... 8	LR366851..... 18	PC367NJ0000F..... 56
LQ065T5GG64..... 11	LQ121S1LG42..... 8	LR36B03..... 18/22/23	PC3H2J00000F..... 57
LQ065T9DZ03A..... 11	LQ121S1LG61..... 8	LR386032..... 19/22	PC3H3J00000F..... 57
LQ065Y5DG03..... 11	LQ121S1LG62..... 8	LR38627..... 19/22	PC3H41xNIP0F..... 57
LQ070T5DG04..... 12	LQ121S1LW01..... 8	LR38653..... 18/20	PC3H4J00000F..... 57
LQ070T5DG05..... 12	LQ150X1LG55..... 8	LR38654..... 18/20	PC3H510NIP0F..... 57
LQ070Y5DE03..... 12	LQ150X1LG81..... 8	LR38690..... 19/23	PC3H5J00000F..... 57
LQ070Y5DG06..... 12	LQ150X1LG82..... 8	LR38692..... 18	PC3H71xNIP0F..... 57
LQ070Y5DG20..... 12	LQ150X1LGB1..... 8	LR38693..... 18/21	PC3H7J00000F..... 57
LQ080Y5DE30..... 13	LQ150X1LW71N..... 8	LR38694..... 19/21	PC3HU72YIP0B..... 57
LQ080Y5DG03..... 12	LQ150X1LW72..... 8	LR388692..... 24	PC3SD11NTZBF..... 63
LQ080Y5DGGQ3..... 12	LQ150X1LW73..... 8	LR38869A..... 24	PC3SD11NTZCF..... 63
LQ080Y5DR04..... 12	LQ190E1LW02..... 8	LR388D1..... 24	PC3SD11YTZDF..... 63
LQ080Y5DW01..... 12	LQ190E1LW43..... 8	LR388D8..... 24	PC3SD12NTZAF..... 63
LQ080Y5DW30..... 12	LQ190E1LX51..... 8	LR388F5A..... 24	PC3SD21NTZAF..... 64
LQ084S3DG01..... 9			PC3SD21NTZBF..... 64
LQ084S3LG01..... 9	LQ2	PC1	PC3SD21NTZCF..... 64
LQ084V1DG41..... 9	LQ201U1LW11Z..... 8	PC1231xNSZ0X..... 58	PC3SD21NTZDF..... 64
LQ084V3DG01..... 9	LQ201U1LW21..... 8	PC123XNNSZ0F..... 58	PC3SD21YTZEF..... 64
LQ084V3DG02..... 9	LQ231U1LW31..... 8	PC1S3021NTZF..... 64	PC3SD23YTZCF..... 64
	LQ281L1LW14..... 8	PC1S3052NTZF..... 64	PC3SF11YVZAF..... 63
LQ1	LQ283G1TW11..... 8	PC1S3063NTZF..... 64	PC3SF11YVZBF..... 63
LQ104S1DG2A..... 8			PC3SF13YVZBF..... 63
LQ104S1DG61..... 8	LR0	PC2	PC3SF21YVZAF..... 64
LQ104S1LG2A..... 8	LR0G934..... 26	PC2SD11NTZAF..... 63	PC3SF21YVZBF..... 64
LQ104S1LG61..... 8	LR0G938..... 26		PC3SF23YVZSF..... 64
LQ104V1DG21..... 8	LR0GC02..... 43	PC3	PC3SH11YFZAF..... 63
LQ104V1DG5A..... 8		PC352NJ0000F..... 56	PC3SH13YFZAF..... 63

(Note) The following models listed on this page are not sold in the United States.

LQ283G1TW11, LQ281L1LW14, LQ231U1LW31, LQ201U1LW11Z, LQ201U1LW21, LQ190E1LW02, LQ190E1LW43, LQ190E1LX51, LQ150X1LW71N, LQ150X1LW72, LQ121S1LW01

PC3SH21YFZBF	64
PC3ST11NSZAF	63
PC3ST21NSZBF	64

PC4

PC400J00000F	60
PC401J00000F	60
PC410S0NIP0F	60
PC451J00000F	56
PC456L0NIP0F	60
PC457L0NIP0F	60
PC457S0NIP0F	60
PC4D10SNIP0F	60
PC4H510NIP0F	57
PC4SD11NTZBF	63
PC4SD11NTZCF	63
PC4SD21NTZCF	64
PC4SD21NTZDF	64
PC4SF11YVZAF	63
PC4SF11YVZBF	63
PC4SF21YVZBF	64
PC4SF21YVZCF	64

PC7

PC713V0NSZXF	59
PC714V0NSZXF	59
PC715V0NSZXF	59
PC724V0NSZXF	59
PC725V0NSZXF	59

PC8

PC81100NSZ0X	58
PC81510NSZ0X	58

PC815XNNSZ0F	58
PC8171xNSZ0X	58
PC817XNNSZ0F	58
PC851XNNSZ0F	58
PC852XNNSZ0F	58
PC853XNNSZ0F	58

PC9

PC900V0NSZXF	61
PC901V0NSZXF	61
PC925LENSZ0F	61
PC942J00000F	61

PD

PD100MCOMP	83
PD100MF0MP	83
PD101SC0SS1F	83
PD102TS0MP0F	83
PD410PI2E00F	83
PD411PI2E00F	83
PD412PI2E00F	83
PD413PI2E00F	83

PQ0

PQ015YZ5MZPH	36
PQ035ZN01ZPH	36
PQ035ZN1HZPH	36
PQ05VY053ZPH	37
PQ05VY3H3ZPH	37
PQ070VK01FZH	32
PQ070VK02FZH	32
PQ070XF01SZH	32
PQ070XF02SZH	32

PQ070XH01ZPH	37
PQ070XH02ZPH	37
PQ070XHA2ZPH	37
PQ070XN01ZPH	36
PQ070XNA1ZPH	36
PQ070XNA2ZPH	36
PQ070XNAHZPH	36
PQ070XNB1ZPH	36
PQ070XZ01ZPH	36
PQ070XZ02ZPH	36
PQ070XZ1HZPH	36
PQ070XZ5MZPH	36
PQ07VR5MAZPH series	35

PQ1

PQ150RWA2SZH	32
PQ150VB01FZH	32
PQ150VB02FZH	32
PQ15RW08J00H	32
PQ15RW11J00H	32
PQ15RW21J00H	32
PQ1AS10C1KA	42
PQ1AS10C1KB	42
PQ1CG2032FZH	39
PQ1CG2032RZH	39
PQ1CG21H2FZH	39
PQ1CG21H2RZH	39
PQ1CG3032FZH	39
PQ1CG3032RZH	39
PQ1CG38M2FZH	39
PQ1CG38M2RZH	39
PQ1CG41H2FZH	39
PQ1CG41H2RZH	39

PQ1CN38M2ZPH	38
PQ1CN41H2ZPH	38
PQ1CX12H2ZPQ	38
PQ1CX22H2ZPQ	38
PQ1CX41H2ZPQ	38
PQ1CX53H2MPQ	38
PQ1CX61H1ZPQ	38
PQ1CY1032ZPH	38
PQ1CYxx3HZPH series	38
PQ1CYxx3LZPH series	38
PQ1CZ21H2ZPH	38
PQ1DX095MZPQ	37
PQ1DX125MZPQ	37
PQ1Kxx3M2ZPH series	33
PQ1LAX95MSPQ	34
PQ1LAXx5MSPQ	34
PQ1Lxx3M2SPQ	34
PQ1MX55M2SPQ	34
PQ1Mxx5M2SPQ	34
PQ1Nxx3MxSPQ	34
PQ1RxxJ0000H series	33
PQ1Uxx1M2ZPH series	33
PQ1Xxx1M2ZPH series	33

PQ2

PQ200WN3MZPH	36
PQ200WNA1ZPH	36
PQ20RX05J00H	32
PQ20RX11J00H	32
PQ20VZ11J00H	36
PQ20VZ51J00H	36
PQ20WZ11J00H	36
PQ20WZ51J00H	36

PQ2CF1J000H	39
PQ2Lxxx2MSPQ	34

PQ3

PQ30RV11J00H	32
PQ30RV21J00H	32
PQ30RV31J00H	32
PQ3DZ13J000H	35
PQ3DZ53J000H	35
PQ3RD083J00H	32
PQ3RD13J000H	32
PQ3RD23J000H	32
PQ3RF23J000H	32
PQ3RF33J000H	32

PQ6

PQ6CB11X1CP	40
PQ6CU12X2APQ	38
PQ6RD083J00H	32

PQ7

PQ7L2020BP	40
PQ7L3010QPF	40
PQ7RV4J000H	32

PQx

PQxxDZ11J00H series	35
PQxxDZ51J00H series	35
PQxxRA11J00H series	32
PQxxRD08J00H series	32
PQxxRD11J00H series	32
PQxxRD21J00H series	32
PQxxRF11J00H series	32

PQxxRF21J00H series	32
PQxxRH11J00H series	32
PQxxxDNA1ZPH series	35
PQxxxDZ01ZPH series	35
PQxxxEF01SZH series	32
PQxxxEF02SZH series	32
PQxxxEH01ZPH	37
PQxxxEH02ZPH	37
PQxxxEN01ZPH series	35
PQxxxENA1ZPH series	35
PQxxxENAHZPH series	35
PQxxxENB1ZPH series	35
PQxxxEZ01ZPH series	35
PQxxxEZ02ZPH series	35
PQxxxEZ1HZPH series	35
PQxxxEZ5MZPH series	35
PQxxxFZ5MZPH series	35
PQxxxGN01ZPH series	35
PQxxxGN1HZPH series	35
PQxxxRDA1SZH series	32
PQxxxRDA2SZH series	32
PQxxxY053ZPH	37
PQxxxY3H3ZPH	37

PR

PR22MA11NTZF	66
PR23MF11NSZF	66
PR26MF11NSZF	66
PR26MF12NSZF	66
PR26MF21NSZF	66
PR29MF11NSZF	66
PR29MF12NSZF	66
PR29MF21NSZF	66

PR31MA11NTZF	66
PR32MA11NTZF	66
PR33MF51NSZF	66
PR36MF12NSZF	66
PR36MF21NSZF	66
PR36MF22NSZF	66
PR36MF51NSZF	66
PR39MF12NSZF	66
PR39MF21NSZF	66
PR39MF22NSZF	66
PR39MF51NSZF	66
PR3BMF21NSZF	66
PR3BMF51NSKF	66

PT

PT100MCOMP	82
PT100MF0MP	82
PT100MF1MP	82
PT380	82
PT380F	82
PT381	82
PT381F	82
PT4800E0000F	82
PT4800FE000F	82
PT480E00000F	82
PT480FE0000F	82
PT4810E0000F	82
PT4810FE00F	82
PT481E00000F	82
PT481FE0000F	82
PT483F1E000F	82
PT4850FE000F	82
PT491FE0000F	82

RJ

RJ2311DB0PB	17/20/22/23
RJ2312DB0PB	17/20/22/23
RJ2321DB0PB	17/20/22/23
RJ2322DB0PB	17/20/22/23
RJ2351CA0PB	17/20/21/22/23
RJ2352CA0PB	17/20/21/22/23
RJ2361CA0PB	17/20/21/22/23
RJ2362CA0PB	17/20/21/22/23
RJ2393BB0KT	17
RJ23V3EB0KT	17
RJ23W3EA0KT	17
RJ23W3HA0LT	17
RJ23Y3BA0LT	17
RJ23Y3EA0LT	17
RJ23Y3HA0LT	17
RJ2411BA0PB	17/20
RJ2411BB0PB	17/20/22/23
RJ2411CA0PB	17/20
RJ2411DA0PB	17/20/22/23
RJ2411EA0PB	17/20
RJ2411EB0PB	17/20/22/23
RJ2411FA0PB	17/20/22/23
RJ2421BB0PB	17/20/22/23
RJ2421DA0PB	17/20/22/23
RJ2421EB0PB	17/20/22/23
RJ2421FA0PB	17/20/22/23
RJ2451BA0PB	17/20/21/22/23
RJ2451CA0PB	17/20/21/22/23
RJ2461BA0PB	17/20/21/22/23
RJ2461CA0PB	17/20/21/22/23

RJ63SC400	15	S202S15F	68
RJ63SC500	15	S202T01F	67
RJ64PC200	15	S202T02F	67
RJ64PC700	15	S208T01F	67
RJ64PC800	15	S208T02F	67
RJ64SC100	15	S212S01F	67
RJ65NC100	15	S216S01F	67
RJ68BA100	15	S216S02F	68
RJ6ABA103	15	S2S3000F	63
RJ6ABA600	15	S2S4000F	64
		S2S5A00F	63

S1

S101S05F	67
S101S06F	67
S101S16F	67
S102S01F	67
S102S02F	67
S102S11F	67
S102S12F	67
S102T01F	67
S102T02F	67
S108T01F	67
S108T02F	67
S112S01F	67
S116S01F	67
S116S02F	67

S2

S201S06F	68
S202S01F	67
S202S02F	68
S202S11F	68
S202S12F	68

VA

VA1E2CD2001	111
VA1E2ED2001	111
VA1G5BF8015	111
VA1J5BF6009	110
VA1J5JF7011	109
VA1K5CD5405	110
VA1K5ED5255	109
VA1R5JF7012	108
VA1T1ED5065	109
VA1T1EF2096	110
VA1Y2UF2446	111
VA3A5JZ922	112
VA3A5JZ923	113
VA3C5CZ934	113

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Nara Plant	EC99J2021	September 24, 1996
Advanced Development and Planning Center	EC99J2038	December 3, 1996
Mobile Liquid Crystal Display Group	EC99J2051	January 28, 1997
Kameyama Plant	EC04J0284	October 12, 2004
Communication Systems Group Hiroshima Plant	JQA-EM5312	April 14, 2006
Appliance Systems Group*	JQA-EM5554	November 10, 2006
Audio-Visual Systems Group Tochigi Plant	JQA-EM0339	February 26, 1999

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A7887 ISO 9001: 2000
A17706 ISO9001: 2000

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Compound Semiconductor Systems Division*	
Electronic Components and Devices Group	
LED Division*	A17706

* The Division name has been changed to System Device Division III, Electronic Components and Devices Group, since March 1st, 2009.



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A16616 ISO 14001: 2004

Certifying organization: UL, Inc. [UKAS, ANAB certified]

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